			Na	tiona	al Ins	titute of E	lectronic	es & In	forma	tion Te	chnolo	ogy, Au	ranga	bad						
	Teach	ing and	Exan	ninat	ion S	cheme for	B.Tech	in Elec	tronic	s Engir	neering	g (Elect	ronic S	System	Engin	eering)			
Prog	ram Name: Electronics Engine	eering (I	Electi	onic	Syst	em Engine	ering)													
Prog	ram Code:B.TechWith Effect	from Ac	aden	nic Y	ear:	2021-2022														
Dura	ition of Program: 8 Semesters								Dı	iration	: 16 W	eeks								
Seme	ester: First																			
			T S	'eachii Schem	ng le							Examir	nation S	cheme						
Sr.	Course Title	Sub.				Credit				Theory						Prac	ctical			Grand Total
No		code	L	Т	Р	(L+T+P)	Paper	E	SE	Р	A	To	otal	E	SE	Р	A	То	tal	
							Hrs.	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	
1	Engineering Physics	1LP01	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
2	Engineering Drawing-I	1LP02	2	-	3	5	3	25	10	25	00	50	20	50	20	50	20	100	40	150
3	Engineering Mathematics-I	1L03	3	2	-	5	3	60	24	40	00	100	40	-	-	-	-	-	-	100
4	Electrical Engineering	1LP04	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
5	Basic computer programming, data structure and algorithm	1LP05	3	1	2	6	3	60	24	40	00	100	40	25	10	25	10	50	20	150
6	Energy and Environment Engineering	1L06	3	1	-	4	3	60	24	40	00	100	40	-	-	-	-	-	-	100
		Total	17	4	9	30	-	325	-	225	-	550	-	125	-	125	-	250	-	800

Student Contact Hours Per Week: 40 Hrs.

Medium of Instruction: English

Theory and practical periods of 60 minutes each. Total Marks: 800

Abbreviations: ESE- End Semester Exam, PA- Progressive Assessment, L - Lectures, T - Tutorial, P - Practical

• Under the theory PA, Out of 40 marks, 10 marks are for micro-project assessment to facilitate integration of COs and the remaining 20 marks is the average of 2 tests to be taken during the semester for the assessment of the cognitive domain LOs required for the attainment of the COs.

For the courses having ONLY Practical Examination, the PA has two parts, marks for : (1) Practical Part - 60% of total marks (ii) Micro-Project Part - 40% of total marks.

				ľ	Natio	nal Institute	e of Elect	tronics	& Info	rmatio	n Tech	nology,	Auran	gabad						
		Teachi	ng an	d Exa	amina	ation Schen	ne for B.	Fech in	Electr	onics E	nginee	ring (E	lectron	ic Syste	em Eng	gineerin	lg)			
Progr	am Name: Electronic	s Engine	ering	(Elec	troni	c System E	ngineeri	ng)												
Progr	am Code: B.TechWit	h Effect	from	Acad	emic	Year: 2021	-2022													
Durat	tion of Program: 8 Set	mesters								Dura	tion: 1	6 Week	S							
Seme	ster: Second																			
			T S	'eachir Schem	ng e							Examir	nation So	heme						
Sr.	Course Title	Sub.				Credit				Theory						Prac	tical			Grand Total
No	Course Thie	code	L	Т	Р	(L+T+P)	Paper	ES	SE	Р	A	To	tal	ES	SE	P	A	То	tal	
							Hrs.	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	
1	Engineering mathematics-II	2L07	3	2	-	5	3	60	24	40	00	100	40	-	-	-	-	-	-	100
2	Engineering chemistry	2L08	3	2	-	5	3	60	24	40	00	100	40	-	-	-	-	-	-	100
3	Engineering mechanics	2LP09	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
4	Electronic devices	2LP10	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
5	Workshop technology	2LP11	3	1	2	6	3	60	24	40	00	100	40	25	10	25	10	50	20	150
6	Communication skills	2L12	3	1	-	4	3	60	24	40	00	100	40	-	-	-	-	-	_	100

Student Contact Hours Per Week: 40 Hrs.

Medium of Instruction: English

30

Theory and practical periods of 60 minutes each. Total Marks: 750

Total

Abbreviations: ESE- End Semester Exam, PA- Progressive Assessment, L - Lectures, T - Tutorial, P - Practical

6

6

18

• Under the theory PA, Out of 40 marks, 10 marks are for micro-project assessment to facilitate integration of COs and the remaining 20 marks is the average of 2 tests to be taken during the semester for the assessment of the cognitive domain LOs required for the attainment of the COs.

-

360

240

-

-

75

-

75

-

150

-

750

600

For the courses having ONLY Practical Examination, the PA has two parts, marks for : (1) Practical Part - 60% of total marks (ii) Micro-Project Part - 40% of total marks.

-

National Institute of Electronics & Information Technology, Aurangabad

Teaching and Examination Scheme for B.Tech in Electronics Engineering (Electronic System Engineering)

Program Name: Electronics Engineering (Electronic System Engineering)

Program Code:B.TechWith Effect from Academic Year: 2021-2022

Duration of Program: 8 Semesters

Duration: 16 Weeks

Semester: Third

	Sr Course Title Sub											Exami	nation So	cheme						
Sr.	Course Title	Sub.				Credit				Theory						Prac	tical			Grand Total
No		code	L	Т	Р	(L+T+P)	Paper	E	SE	Р	A	То	otal	E	SE	Р	A	To	otal	
							Hrs.	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	
1	Engineering mathematics-III	3L13	3	2	-	5	3	60	24	40	00	100	40	-	-	-	-	-	-	100
2	Electronic measurement and instrumentation	3LP14	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
3	Management Economics	3L15	3	2	-	5	3	60	24	40	00	100	40	-	-	-	-	-	-	100
4	Python Programming	3LP16	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
5	Digital Logic and Circuits	3LP17	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
6	Linear Electrical Networks	3LP18	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
		Total	18	4	8	30	-	360	-	240	-	600	-	100	-	100	-	200	-	800

Student Contact Hours Per Week: 40 Hrs.

Medium of Instruction: English

Theory and practical periods of 60 minutes each. Total Marks: 800

Abbreviations: ESE- End Semester Exam, PA- Progressive Assessment, L - Lectures, T - Tutorial, P - Practical

• Under the theory PA, Out of 40 marks, 10 marks are for micro-project assessment to facilitate integration of COs and the remaining 20 marks is the average of 2 tests to be taken during the semester for the assessment of the cognitive domain LOs required for the attainment of the COs.

For the courses having ONLY Practical Examination, the PA has two parts, marks for : (1) Practical Part - 60% of total marks (ii) Micro-Project Part - 40% of total marks.

				Na	tiona	l Institute o	of Electro	onics &	. Inform	nation	Techn	ology, A	Aurang	gabad						
]	Feaching	and]	Exam	inati	on Scheme	for B.Te	ech in E	lectro	nics En	gineer	ing (Ele	ectroni	c Syste	m Engi	ineering	g)			
Progr	ram Name: Electronics I	Engineeri	ing (E	lectr	onic \$	System Eng	gineering	g)												
Progr	ram Code:B.TechWith F	Effect fro	m Ac	adem	ic Ye	ear: 2021-20	022													
Dura	tion of Program: 8 Seme	esters								Durati	on: 16	Weeks								
Seme	ster: Fourth																			
			T	eachin Scheme	lg P							Examin	nation Sc	heme						
Sr.	0 54	Sub.				Credit				Theory						Prac	tical			Grand Total
No	Course Title	code	L	Т	Р	(L+T+P)	Paper	ES	SE	P	A	То	tal	ES	SE	P	A	То	tal	1000
							Hrs.	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	
1	Power Electronics	4LP19	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
2	Electromagnetic and Field Theory	4L20	3	2	-	5	3	60	24	40	00	100	40	-	-	-	-	-	-	100
3	Microprocessor and Microcontroller	4LP21	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
4	Analog Communication	4LP22	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
5	Analog System Design	4LP23	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
6	Signals and System	4L24	3	2	-	5	3	60	24	40	00	100	40	-	-	-	-	-	-	100
		Total	18	4	8	30	-	360	-	240	-	600	-	100	-	100	-	200	-	800

Student Contact Hours Per Week: 40 Hrs.

Medium of Instruction: English

Total Marks: 800 Theory and practical periods of 60 minutes each.

Abbreviations: ESE- End Semester Exam, PA- Progressive Assessment, L - Lectures, T - Tutorial, P - Practical

• Under the theory PA, Out of 40 marks, 10 marks are for micro-project assessment to facilitate integration of COs and the remaining 20 marks is the average of 2 tests to be taken during the semester for the assessment of the cognitive domain LOs required for the attainment of the COs.

For the courses having ONLY Practical Examination, the PA has two parts, marks for : (1) Practical Part - 60% of total marks (ii) Micro-Project Part - 40% of total marks.

National Institute of Electronics & Information Technology, Aurangabad

Teaching and Examination Scheme for B.Tech in Electronics Engineering (Electronic System Engineering)

Program Name: Electronics Engineering (Electronic System Engineering)

Program Code:B.TechWith Effect from Academic Year: 2021-2022

Duration of Program: 8 Semesters

Duration: 16 Weeks

Semester: Fifth

			T S	'eachir Schem	ng e							Examir	nation Sc	cheme						
Sr.	Course Title	Sub.				Credit				Theory						Prac	tical			Grand Total
No	Course rule	code	L	Т	Р	(L+T+P)	Paper	ES	SE	P	A	To	tal	ES	SE	P	A	То	tal	
							Hrs.	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	
1	Digital Communication	5LP25	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
2	Control System Engineering	5L26	3	2	-	5	3	60	24	40	00	100	40	-	-	-	-	-	-	100
3	Digital signal processing	5LP27	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
4	Embedded system and IOT	5LP24	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
5	Printed Circuit Board Technology-I	5LP29	3	1	2	6	3	60	24	40	00	100	40	25	10	25	10	50	20	150
6	Information Theory and coding	5L40	3	1	-	4	3	60	24	40	00	100	40	-	-	-	-	-	-	100
		Total	18	4	8	30	-	360	-	240	-	600	-	100	-	100	-	200	-	800

Student Contact Hours Per Week: 40 Hrs.

Medium of Instruction: English

Theory and practical periods of 60 minutes each. Total Marks: 800

Abbreviations: ESE- End Semester Exam, PA- Progressive Assessment, L - Lectures, T - Tutorial, P - Practical

• Under the theory PA, Out of 40 marks, 10 marks are for micro-project assessment to facilitate integration of COs and the remaining 20 marks is the average of 2 tests to be taken during the semester for the assessment of the cognitive domain LOs required for the attainment of the COs.

For the courses having ONLY Practical Examination, the PA has two parts, marks for : (1) Practical Part - 60% of total marks (ii) Micro-Project Part - 40% of total marks.

			Na	tion	al Ins	stitute of E	lectronio	cs & In	forma	tion Te	chnolo	ogy, Au	ranga	bad						
	Teach	ing and	Exan	ninat	ion S	Scheme for	B.Tech	in Elec	tronic	s Engir	neering	g (Elect	ronic S	System	Engin	eering)			
Prog	ram Name: Electronics Engin	eering (l	Electi	ronic	Syst	em Engine	ering)													
Prog	ram Code:B.TechWith Effect	from Ac	caden	nic Y	ear:	2021-2022														
Dura	tion of Program: 8 Semesters								Dı	iration	: 16 W	eeks								
Seme	ester: Sixth																			
			T	eachiı Schem	ng							Examir	ation S	cheme						
Sr.	Course Title	Sub.				Credit			1	Theory						Prac	tical			Grand Total
No		code	L	Т	Р	(L+T+P)	Paper	E	SE	Р	A	To	tal	ES	SE	P	A	То	tal	
							Hrs.	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	
1	Antenna and wave Propagation	6L31	3	-	-	3	3	60	24	40	00	100	40	-	-	-	-	-	-	100
2	Printed Circuit Board Technology- II	6LP32	3	1	2	6	3	60	24	40	00	100	40	25	10	25	10	50	20	150
3	Computer Architecture and organization	6L33	3	1	-	4	3	60	24	40	00	100	40	-	-	-	-	-	-	100
4	Sensors & Transducers	6LP34	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
5	Software project management	6L35	3	1	-	4	3	60	24	40	00	100	40	-	-	-	-	-	-	100
6	Optical fiber communication	6LP36	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
7	Industrial Visit, Employability skill and Mini project lab	6P37	-	-	3	3	-	-	-	-	-	-	-	-	-	-	-	-	-	50
		Total	18	3	9	30	-	360	-	240	-	600	-	75	-	75	-	150	-	800
Stude Theo	ent Contact Hours Per Week: 40 Hrs.	each	Me Te	dium o otal Ma	of Instr arks: 8	ruction: Englis	sh													

Abbreviations: ESE- End Semester Exam, PA- Progressive Assessment, L - Lectures, T - Tutorial, P - Practical

• Under the theory PA, Out of 40 marks, 10 marks are for micro-project assessment to facilitate integration of COs and the remaining 20 marks is the average of 2 tests to be taken during the semester for the assessment of the cognitive domain LOs required for the attainment of the COs.

For the courses having ONLY Practical Examination, the PA has two parts, marks for : (1) Practical Part - 60% of total marks (ii) Micro-Project Part - 40% of total marks.

			National In	stitu	ute	of E	lectronics	& Info	rmatio	on Tec	hnolog	gy, Au	ranga	bad							
		Teaching and E	Examination	Sch	eme	for	B.Tech in	Electro	onics I	Engine	ering	(Elect	ronic S	Systen	n Engi	neerin	g)				
Pro	gram N	Name: Electronics Engineering (E	lectronic Sys	tem	Eng	gine	ering)														
Pro	gram (Code:B.TechWith Effect from Aca	demic Year:	202	21-2	022															
Dui	ation o	f Program: 8 Semesters							Dura	ation:	16 We	eks									
Sen	nester:	Seventh																			
				To	eachi chor	ing							Examin	ation S	cheme						
Sr.		Course Title	Sub.	6			Credit			,	Theory						Prac	tical			Grand Total
No			code	L	Т	Р	(L+T+P)	Paper	E	SE	P	A	То	tal	ES	SE	Р	A	То	tal	Total
	$\frac{1}{1} Digital system design using Verilog \qquad 7LP38 \qquad 3 - 2 5 3 60 24 40 00 100 40 25 10 25 10 50 20 150$																				
1 Digital system design using Verilog 7LP38 3 - 2 5 3 60 24 40 00 100 40 25 10 25 10 50 20 150															150						
1 Digital system design using Verilog 7LP38 3 - 2 5 3 60 24 40 00 100 40 25 10 25 10 50 20 150 2 Computer network and data communication 7LP39 3 - 2 5 3 60 24 40 00 100 40 25 10 25 10 50 20 150																					
	3.1	Satellite communication	7LP40.1																	<u> </u>	
	3.2	Mechatronics	7LP40.2																		l
3	3.3	Mobile and wireless communication	7LP40.3	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
	3.4	Artificial intelligence and machine learning	7LP40.4																		
4	Microw	vave Engineering	7L41	3	-	-	3	3	60	24	40	00	100	40	-	-	-	-	-	-	100
5	Project	Part I	7P42	1	-	6	7	-	-	-	-	-	-	-	-	-	-	-	-	-	100
6	6.1	Electronic product design Using EDA tools	7LP43.1	3	_	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
Ŭ	6.2	Solar installation and maintenance	7LP43.2			-	5	5	00	2.	10	00	100	10	23	10	20	10	20	20	150
			Total	16	-	14	30	-	300	-	200	-	500	-	100	-	100	-	200	-	800
Stu	dent Con	tact Hours Per Week: 40 Hrs.	Medium of Ins	tructi	on: I	Englis	sh														
Th	eory and	practical periods of 60 minutes each.	Total Marks:	800																	
Ab	breviatio	ns: ESE- End Semester Exam, PA- Progress	sive Assessment,	, L - I	Lectu	ires, 7	Γ - Tutorial,	P - Practio	cal												
• U	nder the	theory PA, Out of 40 marks, 10 marks are f	or micro-project	asses	ssme	nt to	facilitate inte	gration of	f COs ai	nd the re	emaining	g 20 mai	rks is the	e averag	ge of 2 te	ests to b	e taken o	luring tl	he seme	ster for	the

assessment of the cognitive domain LOs required for the attainment of the COs.

For the courses having ONLY Practical Examination, the PA has two parts, marks for : (1) Practical Part - 60% of total marks (ii) Micro-Project Part - 40% of total marks.

			National I	nstit	tute	of E	lectronics	& Info	rmatic	on Tec	hnolog	gy, Au	ranga	bad							
		Teaching and	Examination	Sch	em	e for	B.Tech in	Electr	onics I	Engine	ering	(Elect	ronic S	Systen	ı Engi	neerin	ng)			-	
Pro	gram N	Name: Electronics Engineering ((Electronic Sys	sten	ı En	gine	ering)														
Pro	- gram (Code:B.TechWith Effect from A	cademic Year	: 20	21-2	2022															
Du	ration o	of Program: 8 Semesters							Dura	ation:	16 We	eks									
Ser	nester:	Eighth																			
				T S	'each Schei	ing ne							Examin	ation S	cheme						G
Sr.	Course	Title	Sub.				Credit			r	Theory						Prac	tical			Total
No	course		code	L	Т	Р	(L+T+P)	Paper	E	SE	Р	A	To	tal	ES	SE	Р	A	То	tal	
								Hrs.	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	
1	Industri	ial automation using PLC and SCADA	8LP44	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
2	2.1	Digital image Processing	8LP45.1	2		2	~	2	(0)	24	40	00	100	40	25	10	25	10	50	20	150
2	2.2	Consumer Electronics	8LP45.2	3	-	2	5	3	60	24	40	00	100	40	25	10	25	10	50	20	150
3	RADA	R Communication	8L46	3	2	-	5	3	60	24	40	00	100	40	-	-	-	-	-	-	100
4	Project		8P47	1	2	12	15	-	-	-	-	-	-	-	-	-	-	-	-	-	200
	•		Total	10	4	16	30	-	180	-	120	-	400	-	50	-	50	-	100	-	600
Stu Th Al	ident Con eory and obreviation	ntact Hours Per Week: 40 Hrs. practical periods of 60 minutes each. ns: ESE- End Semester Exam, PA- Progr	Medium of In Total Marks: ressive Assessmen	struc 600 t, L -	tion: Lect	Englis	sh Γ - Tutorial,	P - Practi	cal	L	I	1	I	I	L	I	1	1			
•١	Inder the	theory PA, Out of 40 marks, 10 marks ar	e for micro-projec	t asse	essme	ent to i	facilitate inte	egration o	f COs aı	nd the re	emaining	g 20 ma	rks is th	e averag	e of 2 te	ests to b	e taken o	luring th	ne seme	ster for	the
ass E-	sessment (of the cognitive domain LOs required for	the attainment of	the C	COs.	for	(1) D reat:	1 Dout ()0/ of t-	المعرفة		iana D	is at D	+ 400/	of total	montra					
F0	r the cour	rses naving UNLY Practical Examination	, the PA has two p	arts, be c	mark lecla	is ior : re ac	(1) Practica Absent in M	11 Part - 6(Iark List)% 0I to and has	to rear	ls (11) M mear fo	icro-Pro	ject Par	t - 40% The m	of total f	marks. the ner	t for wh	ich can	didate v	vas nro	sent will
	no	ot be processed or carried forward.	Crammanon will	be t	icua	10 43 /		ai K 1218t	anu nas	to reap	pear 10	i traili	manoll.	ine ma	ai no Ul I	ine par		ich call	uiuaie v	as pres	sent will

Course title:	ENG	INEERING	Sub code	1L0	3		
	NIE I	nama nos-i	Structure	L	T	P	С
				3	0	0	3
Course Objec	tive:	• To expose student to underst calculus, Integral calculus, In and engineering.	and the basic impo finite series and Ma	rtance atrix t	e of I heory	Differe in sci	ntial ence
Course Outco	me:	• The terminal objectives of completion of teaching-learn would be able to identify an fundamental principles of eng	f the course are ing and evaluation d analyse the prob ineering mathemati	that, activ lems cs.	on vities, by ap	succe a stu plying	ssful ident g the
Contents			No. of hours	ESI	E Ma	arks ((%)
Module 1: Dif	feren	tial Calculus:	10	25			
Functions of sing theorem, Lagran indeterminate for	le variange's ms, cui	able: Limit, continuity and different theorem, Cauchy's theorem, rvature, curve tracing.	entiability. Mean va Taylor's theoren	llue th n wi	th r	ns: Ro emain	olle's ders,
Module 2: Int	egral	Calculus:	10	25			
Fundamental theo Applications in A Beta and Gamma	orem o Area, le functio	f Integral calculus, mean value t ength, volumes and surface of s ons, differentiation under integral	heorems, evaluatior olids of revolutions sign.	i of de s, Imp	efinite proper	e integ integ	grals, grals:
Module 3: Inf	inite s	series:	8	25			
Sequences, Infini absolute and con parameter, unifor	te serie nditiona m conv	es of real and complex numbers al convergence, improper integr vergence, power series, radius of o	, Cauchy criterion, rals, improper integ convergence.	tests grals o	of co depen	nverge	ence, on a
Module 4: Ma	trices	:	12	25			
Rank of matrix, c and orthogonal t reduction to diago	consiste ransfor onal for	ency of a system of equations, lin rmations, Eigen values and eige rm, Hermitian and skew Hermitia	ear dependence and n vectors, Cayley n matrices, Quadrat	l inde – Har ic for	pende miltor ms.	ence, li n theo	inear orem,
Reference Boo	oks:						
 Kreyszig, E., Piskunov, N. Thomas, G.E Michael D. G 	Advar , Diffe B. and H	nced Engineering Mathematics, Jo rential and Integral calculus, Mir Finney, R.L, Calculus and Analyti	ohn Wiley & Sons publishers Moscow c Geometry, Addiso	(Vol. on We	1, Vo	ol. 2) Longn	nan

- 4) Michael D. Greenberg, Advanced Engineering Mathematics, Pearson Education Pvt. Ltd
- 5) Jain R.K., Iyengar S.R.K, Advanced Engineering Mathematics, Narosa Publishers

Course title:	ENGINEERING DRAWING	Sub code	1L	.P02		
	DATIVITO	Structure	L	Т	Р	С
			2	0	2	4
Course Objective:	 To impart and include projection. Improve the visualization sk To enable the students wit conventions and standards in the students. 	oper understand kills. h various concep related to workin	ing ots ig d	of the like din rawing	theor nension in ord	y of ning, er to
	 To impart the knowledge or residential/ office building. 	n understanding a	and	drawing	g of si	mple
Course Outcome:	 Gain the importance of lines Gain the visualization of different angles from referent Will be able to draw an projections. Will be able to give proper descriptions 	, planes, solids in projections of ice plane. d visualise orth limensions to the	i eng line nogr pro	gineerin es, plan aphic a jections	g. les, so and is	olids in ometric
Content		No. of hours.	•	ESE	Mark	KS(%)
Module 1: Projection	ons of Straight Lines:	10		25		
Module 2: Projection Plane with surface paral perpendicular to other, p	ions (all four quadrants should be ons of planes: llel to one plane and perpendicula projections of planes inclined to b	8 ar to other, plane ooth the plane.	incl	25 ined to	one pl	ane and
Module 3: Projection	ons of Solids:	10		25		
Introduction to solids: above solids with axis i the planes, projection of	prisms, pyramid, cylinder, cone, nclined to one plane, projections composite solids (different arran	cube, tetrahedro of above solids ngement of sphere	on, s with es w	sphere, a axis in with abo	project clined ve soli	tions of to both ds).
Module 4: Orthogr Isometric views:	aphic Projections&	12		25		
Orthographic projection Introduction to pictoria isometric planes). Reference Books:	s of different machine parts, sect l views, isometric projections a	ional orthographi and isometric vie	ic prevention of the second seco	rojection (Isome	ns. etric ar	nd non-
 Bhatt N. D., Panchal Dhabhade M. L., "E Mathur, Laxminaray 	V. M., "Engineering Drawing", ngineering Graphics", VolI and van, "Elements of Engineering Dr	Charotar Publish VolII, Vision F awing", Jain Pub	ubl Publ	House. ications ttions, N	, Pune Iew De	elhi.

List of Experiments:

- 1) Introduction to BIS SP 46 1988.
- 2) Explanation of various drawing instruments, symbols, RF, Dimensioning, etc.
- 3) Conversion of pictorial views to orthographic / profile views.
- 4) Projection of points and lines.
- 5) Projections of planes.
- 6) Projections of lines and planes using Auxiliary planes.
- 7) Projections of solids.
- 8) Section and development of solids.
- 9) Intersection of solids.
- 10) Isometric views.
- 11) Practice of scales, Representative Factor and dimensioning on some practical exemplary figure.

Course title:	ELEC	CTRICAL ENGINEERING	Sub code	1LF	P04		
			Structure	L	Т	Р	С
				3	0	1	4
Course Object	ive:	 To enable the students, underst Electrical Engineering. To impart knowledge for unders systems, transformers, generator 	and the basic ide tanding the detai s, motors etc.	eas a ls of	nd pr electr	incipl ical p	es of
Course Outcon	ne:	 Predict the behaviour of any elect Formulate and solve complex AC Identify the type of electrical application. Realize the requirement of distribution of electric power and 	trical and magnet C, DC circuits. machine used transformers ir other application	ic cir for 1 tra 1s.	rcuits that ansmi	parti ssion	cular and
Content			No. of hours	E	SE M	larks	(%)
Module 1: Elec	etrical	Circuit:	8	20	0		
Network Theorem Power Transfer T Equivalent Curren Magnetic Circuit, Composite Magne	t Source Flux, N tic Circ	rposition Theorem, Thevenin's The n Voltage Source (Definition, Cha e), and Star-Delta Transformation. IMF, Reluctance, Analogy with Ele- puts	corem, Norton's aracteristics of P ctric Circuits. Sir	Theo raction nple	orem, cal So Calcu	Maxi ource, ilatior	mum and is for
Module 2: AC	Circu	its:	8	2:	5		
Periodic Function, Phasor Representa of Generation of System	, Avera ttion, R Single	ge & R.M.S., Values, Steady State I eactance & Impedance, Series & Pa Phase & Three Phase Voltages, I	Behaviour with S rallel Circuit, Po Power in Balanc	inus wer l ed T	oidal Factor Three	Excita r, Prin Phase	ation, ciple AC
Module 3: Elec	ctrical	Measurements:	8	20	0		
Definition, Indica Mechanisms, Amr Type & Moving I Energy Meter	ting, In neter & ron Ty	tegrating & Recording Instruments Voltmeters, P.M.M.C. pe, Electrodynamometer Type Watt	, Deflecting Cor meter's, Inductio	ntroll n Ty	ing & pe Si	t Dan ngle I	iping Phase
Module 4: Tra	nsforr	ners:	8	20	0		
Introduction, Basi Condition Transfo Open Circuit & Sh	ic Prino ormer o nort Cir	ciples, Construction, Phasor Diagra n Load, Balance of MMF on Sides, cuit Test, Voltage Regulation and Ef	am for Transform Phasor Diagram fficiency	mer 1, Eq	under uivale	[•] No ent Ci	Load rcuit,
Module 5: Pow	ver Sys	stems& Electrical Machines:	8	1:	5		
Elementary Idea al DC Shunt and Sen and Applications. Induction Motors Torque Slip Chara	bout Po ries Mo – Con cteristic	ower Generation, Transmission and I otor – Construction, Principle of Wo struction, Principle of Working of cs.	Distribution. orking, Character Single Phase an	istics	s, Spe - Pha	ed Co se Mo	ontrol
Reference B00	NS:						

- 1) Hughes, Electrical Technology, Pearson Publishers
- 2) Theraja B.L., Electrical Technology, S. Chand Publishers
- 3) Kothari D.P. and NagrathI.J., Theoryand Problems of Basic Electrical Engineering, Prentice Hall India
- 4) Kulshresta D.C., Basic Electrical Engineering, TMH India
- 5) Mittle and Mittal, Basic Electrical Engineering, TMH, 2005
- 6) Tarnekar S.G., and Kharbanda P.K., "A Textbook of Laboratory Course in Electrical Engineering", Chand S., 2006 (For practical)

List of Experiments:

- 1) Study and verification of Kirchhoff's laws applied to DC circuits.
- 2) Verification of Thevenin's Theorem.
- 3) To Verify Maximum Power Transfer theorem.
- 4) Study of AC series R-L-C circuit.
- 5) Determination of B-H curve of a magnetic material.
- 6) Study of AC parallel R-L-C circuits.
- 7) Study of balanced 3-phase circuits.
- 8) Determination of voltage regulation and efficiency of a single-phase transformer by direct loading.
- 9) Study of speed control of a DC motor by field current control and by armature voltage control.
- 10) Study of reversal of direction of rotation of a 3-phase induction motor.

Course title:	BASI PROC AND	C CONCEPTS OF GRAMMING, DATA STRUCTURE ALGORITHM	Sub code	1LP	05		
			Structure	L	Т	P	C
				3	0	1	4
Course Objec	ctive:	 To introduce basics of programming students. To help students understand how to software and develop practical programment mathematical statistic 	and develop logic model real world ramming skills of cal, applications in	cal thi proble studer to pro	ems i nts. ogran	g of nto t	the
Course Outco	ome:	 Acquire knowledge to give function Students will be able to create their of Acquire knowledge to use Arrays are Will be able to declare and initialize Will be able to write sequential and 	and parameter par own algorithm. ad strings. pointers. text files.	ssing.	' Ma	nlra	9/)
Content			No. of hours	ESE		rks(<i>%</i> 0)
Module 1: In	trodu	ction:	8	10			
Flow charts, dat conditional, arith Switch concept,	ta types hmetic functio	and storage classes, scope of variable expressions, enumerated data types, de n and parameter passing, recursive funct	es, arithmetic oper ecision making, b tions, macros.	rators, ranch	ass ing,	lgnm loop	ient, ing,
Module 2: Ba	sic pr	ogramming algorithms:	8	18			
Programs to ill mathematical se integers (Euclid programs.	ustrate ries, Fi l's met	basic language constructs in C like bonacci series, calculating square-root hod and otherwise), Calculating LCN	- Factorial, Sine of a number, calc M of 2 integers	c/cosin culatin and	ne an ng G simi	nd o CD (lar s	other of 2 such
Module 3: Ar	rays a	and applications:	8	18			
Introduction to o D array and pol Character arrays strstr etc) and the Insertion sort, I Introduction to	one dim ynomia (string eir func Linear Divide	ensional and 2-D array with examples. l operations, use of 2-D array to represes: s): String related functions (strlen, strcp tion definitions. Searching and Sorting r and binary search, partitioning an a and Conquer" via Mergesort and Quick	Representing a posent a matrix and by, strcat, strcmp, methods: Selection rray, merging of sort.	olynoi matri atoi, n sort, 2 so	mial x op itoa, Bub orted	usin erati reve ble s arr	g 1- ons. erse, sort, ays.
Module 4: St	ructur	es, Unions and Pointers:	8	18			
Basic concept, a pointers and arra sized 1-D and 2-	rray of ays, con D array	structures and its applications. Introduce the neept of dynamic memory allocation, us responses to structures.	ction (declaration se of pointers to the second sec	and in repres	nitial ent v	izati varia	on), ble-
Module 5: Fil	le Mai	nagement in C:	8	18			
Open, close, read	d and w	rite operations, Sequential and text files	•	1			

Reference Books:

- 1) Kerninghan; Ritchie, "C programming Language", PHI
- 2) Theraja B.L., Electrical Technology, S. Chand Publishers
- 3) Balguruswamy, "Programming in ANSI C", Tata Mcgraw Hill Publishing
- 4) Kakde and Deshpande, "C and data Structure", Charles River Media Publisher
- 5) Dromey R G, "How to Solve it by Computer", PHI

List of Experiments:

- 1) Write a Program to calculate and display the volume of a CUBE having its height (h=10cm), width (w=12cm) and depth (8cm).
- 2) Write a program to take input of name, roll no and marks obtained by a student in 5 subjects each have its 100 full marks and display the name, roll no with percentage score secured.
- 3) Simple Arithmetic Operation.
- 4) Write a C program to check whether a number is even or odd using ternary operator.
- 5) Write a C program to find the sum of individual digits of a positive integer.
- 6) Write a C program to print the numbers in triangular form.
- 7) Write a C program to find the second largest integer in a list of integers.
- 8) Write C programs that use both recursive and non-recursive functions.
- 9) Write a C program to perform arithmetic using Switch Statement.
- 10) Write a C program to perform factorial.
- 11) Write a C program to print Fibonacci no.

Course title:	PHY	ISICS	Sub code	1LP0			
	I		Structure	L	Т	Р	C
				3	0	0	3
Course Objec	tive:	 To equip the students with an under so that they can use the training ber This course gives a balance accounce well as some of recent development Engineering applications in different 	rstanding of the neficially in their nt of the fundan nents in this are nt branches.	"Scient higher nentals a best	ific N purs of Pl suite	Aethouits. nysic	ods" s as the
Course Outco	ome:	 The student will be able to understand many modern devices an technologies based on lasers and optical fibres. Student can also appreciate various material properties which are use in engineering applications and devices. 					and used
Content			No. of hours	ESF	E Mai	rks(%	%)
Module 1: Int	erfer	ence and Diffraction:	9	25			
son's interferome Fresnel and Frau grating, determin resolving power	son's interferometer, Fabry-Perot interferometer. Fresnel and Fraunhofer diffraction, Fraunhofer diffraction at circular aperture, plane diffraction grating, determination of wavelength using plane diffraction grating, dispersive power of grating, resolving power of grating.					tion ing,	
Module 2: Ser	micon	iductors:	9	25			
Position of ferm Hall effect, Hall LED, Zener diod	i level coeffi e, Sola	in intrinsic and extrinsic semiconduction, band structure of PN junction or cell, Photocell.	ictor, conductivi under forward b	ty in so ias and	emico l reve	onduc erse t	ctor, bias,
Module 3: Ma	agneti	c Materials& Dielectrics:	9	25			
Diamagnetic mat Types of magnet Dielectrics-Introd polar and non-po	erials, ic mate luctior lar die	Paramagnetic materials, Ferromagnet erials-hard materials and soft material n, dielectric constant, polarization, in lectrics, polarization-an atomic view,	tic materials, origonal s. induced dipoles, types of polariza	gin of r perma tion.	nagne anent	etizat dipo	tion, oles,
Module 4: Fil	ore O	ptics and LASER:	9	25			
Concept, fibre advantages of op Spontaneous and Engineering appl	materia tical fi Stimu ication	als, structure and classification of bre communication. lated emission, population inversion as of laser.	optical fibre, , Ruby laser, He	Numer lium N	ical eon g	apert gas la	ture, aser,
			1.111	D 11 1			
 Fiber opti Solid stat Electronic Fiber opti Fiber opti A course Publication Engineeri 	e elect c devic c com in Elec on,New	amunication-D.C.Agarwal. Wheeler P ronic devices-Streetman, Prentice Hal res and circuits-Allen Mottershade, Pr munication-Keiser. Mc Graw Hill Put ctrical Engineering Materials – S.P.Se v Delhi.	ublication, New 1 India, New Del entice Hall India blication th,P.V.Gupta, Di cation	Delhi hi , New I hanpat	Delhi Rai		
/) Engineeri	ing phy ment	sics-Avadhanalu and Kshirsagar, S.C	hand Publication	1			
List of Experi							

- 1) Determination of radius of curvature of Plano- convex lens by Newton's ring
- 2) Determination of wavelength by diffraction grating.
- 3) Study of CRO (amplitude, frequency, phase measurement).
- 4) Semiconductor diode characteristics of Zener and LED diode.
- 5) To plot Transistor characteristics using CE configuration.
- 6) Study of solar cell characteristics.
- 7) Study of photocell characteristics.
- 8) To study transistor as an amplifier (CE, CB and CC configuration).
- 9) To determine the band-gap in a semiconductor
- 10) To study Hall effect and Hall coefficient.
- 11) To study different types of Optical fibres.

Course title:	ENE ENC	CRGY AND ENVIRONMENTAL SINEERING	Sub code	1L06				
			Structure	L T P				
			I	3	0	0	3	
Course Objecti	ve:	 To teach the principal renewable en To explore the environmental impathe effects of different types of poll 	ergy systems. ct of various energ utants.	gy so	urces	and a	also	
Course Outcom	ne:	 Principal renewable energy systems Explore the environmental impact of effects of different types of pollutar 	 Principal renewable energy systems Explore the environmental impact of various energy sources and also effects of different types of pollutants. 					
Content			No. of hours	ES	E Ma	arks	(%)	
Module 1: Intro	oduc	tion:	8	20				
Present Energy reso -Energy Demand S Conventional Vs N	ource Scena Ion-co	s in India and its sustainability - Differ- rio in India-Advantage and Disadvan- onventional power generation.	ent type of conven tage of convention	itiona nal F	al Pov Power	ver P Plar	lant- nts —	
Module 2: Basi	cs of	Solar Energy:	8	20				
Basics of Solar End Environmental imp	ergy- bacts a	Solar Thermal Energy- Solar Photovol and safety.	ltaic- Advantages	and 1	Disad	vanta	iges-	
Module 3: Wind conversions and	d, Bi 1 res	omass, Geothermal ources:	8	20				
Power and energy shore Wind energy Biomass resources methods- Bioenerg Geothermal Energy	from - Env s-Bion y pro y reso	wind turbines- India's wind energy per ironmental benefits and impacts. mass conversion Technologies- Feed gram in India-Environmental benefits a urces –Ocean Thermal Energy Convers	otential- Types of lstock pre-process and impacts. sion – Tidal.	wind sing	d turb and	ines- treati	• Off ment	
Module 4: Air I	Pollu	ition:	8	20				
Air pollution- Sou measurement. Wate solid waste.	urces, er pol	, effects, control, air quality standar lution-Sources and impacts, Soil Pollu	rds, air pollution tion-Sources and i	act, impa	air cts, d	pollı ispos	ition al of	
Module 5: Gree	enho	use gases:	8	20				
Greenhouse gas eff fuels and impacts, I	fect, a Indus	acid rain. Noise pollution. Pollution as trial and transport emissions- impacts.	pects of various p	owe	r plar	its. F	ossil	
Reference Book	ks:							
 Boyle, G. 2004. Renewable energy: Power for a sustainable future, Oxford University press. B H Khan, Non-Conventional Energy Resources-The McGraw –Hill Second edition. G. D. Rai, Non-conventional energy sources, Khanna Publishers, New Delhi, 2006. Gilbert M. Masters, Introduction to Environmental Engineering and Science, 2nd Edition,Prentice Hall, 2003. 								

Course title:	ENG	SINEERING MATHEMATICS-II	Sub code:	2I	2L07			
			Structure:	E L T P			С	
				3	2	0	5	
Course Object	ive:	To make students understand the basic in (Differential calculus & Integral calcul differential equations in engineering.	nportance of us), Vector	multi calcu	i varia Ilus ar	ble ca nd or	lculus dinary	
Course Outcon	ne:	After the completion of the course, studies applicable problems.	dents are ab	e to	solve	indus	strially	
Content			No. of ho	urs	ESE N	Marks	s (%)	
Module 1: Cal	culus	of Functions of Several Variables	8	·		20		
Limit, continuity geometrical interp Total differentiatio undetermined mul	and d retatio on, cha tipliers	ifferentiability of functions of several van n, Tangent plane and normal line. Euler's in rules, Jacobian, Taylor's formula, maxim	riables, partia theorem on h a and minima	l der omog I, Lag	ivative geneou grange'	es and s, fund s met	their ctions, nod of	
Module 2: Mul	tiple	Integrals			8		20	
Double and triple volumes, Mass, Co	e integ entre of	rals, change of order of integration, changed f gravity.	ge of variabl	es, aj	pplicat	ion to	area,	
Module 3: Vec	tor Ca	alculus		5	8	4	20	
Scalar and vector fields, gradient of scalar point function, directional derivatives, divergence and curl of vector point function, solenoidal and irrotational motion. Vector integration: line, surface and volume integrals, Green's theorem, Stroke's theorem and Gauss divergence theorem (without proof).								
Module 4: Ord	inary	Differential Equations		8		20		
First order difference equations, Linear Picard's theorem, order linear equation of parameters, Sol	ential and B Picard on wit ution o	equations: Exact equation, Integrating fact ernoulli's form, orthogonal trajectories, Ex 's iteration method of solution (Statements of h constant coefficients, Linear independence f Cauchy's equation, simultaneous linear equ	tors, Reducib istence and U only). Solutio and depender ations.	le to Inique ns of nce, N	exact eness of second Iethod	differ of solu 1 and 1 of van	rential utions. higher riation	
Module 5:				8	8		20	
Analytic functions Construction of an functions, and bili	s, Cau alytic anear tra	chy. Riemann equations (Cartesian and pol functions given real or imaginary part, Confo ansformation.	ar), Propertie ormal mapping	s of g of si	analyti tandarc	c fund d elem	ctions, entary	
Reference Boo	ks							
	1. 2. 3. 4. 5.	Kreyszig, E., Advanced Engineering Mathe Piskunov, N., Differential and Integral calce Vol. 2) Thomas, G.B. and Finney, R.L, Calculus ar Wesley Longman. Michael D. Greenberg, Advanced Engineer Pvt. Ltd Jain R.K., Iyengar S.R.K, Advanced Engine	matics, John ulus, Mir publ d Analytic Go ing Mathemat eering Mather	Wiley ishers comet ics, P natics	v & Son s Mosc try, Ad earson s, Naros	ns cow (V dison Educa sa	ol. 1, ation	

Course title:	EN(GINEERING CHEMISTRY	Sub	code	:	2L(8		
	1		Stru	acture	cture: L T P				С
						3	2	0	5
 Course Objective: To present sound knowledge of chemistry fundamentals, understand the role of Applied Chemistry in the file engineering. To inculcate habit of scientific reasoni rationally. To introduce the students to basic principles of el construction and evaluation, electrochemical power sou of corrosion in metal/alloy and polymer. 					enrich ield o ing to lectro irces,	hing of so o do chen the	stuc cien o th nistr imp	lents ce a ne ta ry, c ortan	s to and ask cell nce
Course Outcom	ıe:	Students would become familiar with the important practical applications electrochemistry, solids, their properties and applications, and the polyr materials.					ions olyn	of ner	
Content			No. of ho	ours	ESE	C Ma	arks	s (%	6)
Module 1: Elec	troch	emistry		8				20)
conductivity of el potential, EMF set cells, cell EMF, its concentration cell, with and without tr	Conductivity of electrolytes- Specific, molar and equivalent conductivity, Nernst equation for electrode potential, EMF series, hydrogen electrode, calomel electrode, glass electrode, Electrolytic and galvanic cells, cell EMF, its measurement and applications, Weston standard cell, reversible and irreversible cells, concentration cell, electrode (hydrogen gas electrode) and electrolyte concentration cell, concentration cell with and without transference.							nic lls, cell	
Module 2: Corr	rosior	1			8	8		20	
Dry corrosion and atmospheric and so corrosion, protection protection, Chemic	wet o il corr on froi al con	corrosion, mechanisms, types of corrosion osion, Passivity, Polarization, over potentia m corrosion by metallic coatings, electrop version coatings and organic coatings- Pain	n, DMC, E al and its signating, election ating, enamels	DAC, s gnificar troless	tress, nce, F platir	inte Facto ng ar	er gr rs af nd ca	anu fecti atho	lar, ing dic
Module 3: Batt	eries				8	8		20	,
Different types of l Laclanche cell, Al working and appli Acid storage cell- principle.	batterio kaline cation -charg	es-Primary, Secondary & Flow battery and battery, NiCad battery, lithium battery & . Different types of fuel cells-H2/O2, pro ing & discharging principle, operation a	Fuel cell. V & Mercury pane-oxyge and uses.	Workin battery en, PEI Solar 1	g prir 7. Fue FC an batter	ncipl el ce nd S ry- i	e an 11- 7 OFC ts w	d us Thec C. Le vork	es- ory, ead ing
Module 4: Solid	l Stat	ie			8	8		20	
Types of solids - close packing of atoms and ions - bcc, fcc structures of rock salt - cesium chloride- spinel - normal and inverse spinel's, Stoichiometric Defect, controlled valency & Chalcogen semiconductors, Non-elemental semiconducting Materials, Preparation of Semiconductors-steps followed during the preparation of highly pure materials and further treatments. Semiconductor Devices-p-n junction diode.									
Module 5: Poly	mer				8	8		20	
Nomenclature, fun molecular weight of plastics and mould & applications of 1 polyurethanes. Com	Ictional leterm ing of PVA, nductiv	lity, classification, methods of polymeriz ination-Viscometry, light scattering metho- plastics into articles. Important thermoplas FLUON, PC, Kevlar, ABS polymer, phen ve polymers.	zation, mec ds. Plastics tics and the olic & amin	hanism -Mould rmoset no resi	n of ling c ting r ns, ep	poly const resine poxy	meri ituei s- sy resi	izati nts o nthe ins a	on, of a esis and

Reference Books	
	1. P. C. Jain and M. Jain, Engineering Chemistry, Dhanpat Rai Publishing
	Company, New Delhi, 2005.
	2. B.R. Puri, L.R. Sharma, M.S. Pathania, Principles of Physical Chemistry,
	Vishal Publishing Company, 2008.
	3. J. D. Lee, Concise Inorganic Chemistry, 5th Edn., Chapman and Hall, London,
	1996.
	4. S. S. Dara, S. S. Umare, A Text Book of Engineering Chemistry, S. Chand
	Publishing, 2011.
	5. F.W. Billmayer. Textbook of Polymer Science, 3rd Edn, Wiley. N.Y. 1991.
	6. A.R. West, Basic Solid State Chemistry, 2nd edition, John Wiley and Sons,
	1999.

Course title:	ENGINEERING MECHANICS	Sub code:	2LP09			
		Structure:	L T P C			
			3	0	2	5
Course Objecti	 To explain the importance of mechanic conservation equations. To explain the significance of centrol inertia. To introduce the techniques for analysin To apply the different principles to stud relative velocity and acceleration. To describe the trajectory of a particle u To identify the basic elements of a constitutive equations. 	 To explain the importance of mechanics in the context of engineering and conservation equations. To explain the significance of centroid, centre of gravity and moment of inertia. To introduce the techniques for analysing the forces in the bodies. To apply the different principles to study the motion of a body, and concept of relative velocity and acceleration. To describe the trajectory of a particle under projectile motion. To identify the basic elements of a mechanical system and write their constitutive equations. 				
Course Outcon	ne: The terminal objectives of the course i teaching-learning and evaluation activities and analyse the problems by applying the mechanics and to proceed to research, desi systems.	The terminal objectives of the course is that, on successful completion of teaching-learning and evaluation activities, a student would be able to identify and analyse the problems by applying the fundamental principles of engineering mechanics and to proceed to research, design and development of the mechanical systems.				
Content		No. of hours	ES	ΕM	arks	s (%)
Module 1: For	ce systems & Equilibrium	8			,	20
Vector representat reduction of a for Equilibrium of Pl systems (Beam, Tr	ton of force system, Moment of a force about a porce system to a force – a couple Wrench, Free E anar (including friction) and Spatial force system russes etc.)	and about an a Body Diagram, Ro m, Analysis of s	x1s; c eactio	oupl ons a lly d	e mo t sup eterr	oment; oports, ninate
Module 2: Cen	troid and Moment of inertia		8			20
First moment of a Radius of gyration	rea, Centroid of area, Moment of inertia, Polar mo , Section modulus.	ment of inertia, F	aralle	el axi	s the	eorem,
Module 3: Inte	rnal forces in member		8			20
Determination of Bending moment (variation of Axial force (Axial Force Diagram), Bending Moment Diagram) and twisting moment (Shear force (Shear force (Shear)	ear Fo	orce	Diag	gram),
Module 4: Con	cept of stress and strain		8			20
Normal and shear elasticity, Poisson ³	stress and strain, State of stress at a point, Stress 's ratio, Modulus of rigidity, Bulk modulus, Transfe	strain curve, Hoc ormation of stress	k's la	ıw, N	Aodu	lus of
Module 5: Determination of stress			8 20			
Stress across a re- rectangular, T & I torsion.	ctangular, T & I section, and circular section due section, and circular section due to shear force.	e to bending moi Stress across a ci	nent cular	Stres	ion o	ross a due to

Reference Books	
1 2 3 4 5 6 7 8	 Hibbler, Engineering Mechanics, Pearson Education, Asia Pvt Ltd. Beer F.P. and Johnston E.R., Vector Mechanics for Engineers: Statics and Dynamics, Tata McGraw-Hill Irving H. Shames, Engineering Mechanics: Static and Dynamics, Pearson Education, Asia Pvt Ltd. Meriam J.L. and Kraige L.G., Engineering Mechanics, John Wiley and Sons. Stephen Timoshenko, Strength of Materaials, Part -1, CBS Publishers and Distributors, New Delhi. Singer F.L. and Andrew Pytel, Strength of Material, Harper and Row Publishers, New York. Popov E.P., Mechanics of deformable bodies, Prentice-Hall Beer F.P. and Johnston E.R., Mechanics of materials, McGraw-Hill International
list of Experimen	its
1 2 3 4 5 6 7 8 9 1	 Verification of equilibrium equation for coplanar forces. Verification of Lami's theorem. Verification of Law of parallelogram of forces. Verification of Law of polygon of forces. Verification of equilibrium equation for spatial forces. Determination of coefficient of friction. Analysis of truss (Analytical / Graphical method).Determination of modulus of elasticity for copper wire. Determination of modus of rigidity of material. Flexural test on beam. Tension Test on Mild Steel Specimen

Course title:	ELECTRONICS DEVICES	Sub code:	2LP	P10			
		Structure:	L	Τ	Р	С	
			3	0	2	5	
Course Object	 To introduce basic semiconductor application. To understand analysis and design of s To learn to analyse the PN junction be in the operation of diodes and active design of diodes and design of	 To introduce basic semiconductor devices, their characteristics and application. To understand analysis and design of simple diode circuit. To learn to analyse the PN junction behaviour at the circuit level and its role in the operation of diodes and active device. 					
Course Outcor	 Inderstand the impact of wave nature semiconductor devices. Understand the carrier transport mecha Develop a fundamental understanding P-N junction diodes. Understand the physics, characterist transistors, Junction Field Effect Trans Field Effect Transistors. Understand the Solid State Device cap Circuit Performance. 	 Understand the impact of wave nature of particles on the performance of the semiconductor devices. Understand the carrier transport mechanisms in semiconductors. Develop a fundamental understanding of the static and dynamic behaviour of P-N junction diodes. Understand the physics, characteristics and models of Bipolar Junction transistors, Junction Field Effect Transistors and Metal Oxide Semiconductor Field Effect Transistors. Understand the Solid State Device capabilities and limitations on Electronic Circuit Performance. 					
Content		No. of hours	5 E	SE N	larks	s (%)	
Module 1: Basi	c Devices		8			20	
Semiconductor dia and clamping circ photodiode, opto-c	odes: V-I characteristics, Modelling for various cuits RC filters. Bipolar junction transistor (BJ coupler, V-I characteristics, optoelectronic circuits	circuit applicatio T), V-I characte	ons, re eristics	ectifie s, Bi	er, Cli asing.	ipping LED	
Module 2: Pow	er devices & Switching Devices		8	8		20	
Power diode, MOS MOSFET characte load.) IGBT, SCR	SFET (Basics of MOS Transistor operation, Constr ristics. MOSFET as switch, diode/active resistor, TRIAC, DIAC, UJT characteristics and applicatio	ruction of n-chan CMOS Inverter <i>a</i> ns.	nel E- is amp	-MOS olifier	SFET, :: Acti	E- ve	
Module 3: JFE	Т		8	8		20	
Introduction to JFI Volt-Ampere char (Self). FET as an High Impedance c	ET, Types, Construction, Operation, Static Characteristics, FET Configurations (CS/CD/CG) and amplifier and its analysis (CS) and its frequency incuits.	teristics, Pinch of nd their Compar response. Small	ff volt ison. signa	age, l Bias al mo	FET ing of del, F	f FET ET as	
Module 4: Elec	tronics Amplifiers & Oscillators		8	8		20	
Classification of amplifiers, Fundamentals of Low noise and Power amplifiers. Feedback amplifiers: Feedback concept and topologies, Effect of feedback on terminal characteristics of amplifiers. Barkhausen criterion, stability with feedback. Classification of oscillators, RC Oscillators: FET RC Phase Shift oscillator, LC Oscillators: Hartley and Colpitts oscillators, Crystal oscillators.							
Module 5: Multi-vibrators & Voltage Regulator			8 20			20	
IC555 Block diagram, Types of Multi-vibrators: Astable, Mono-stable and Bi-stable, Operation of Multi- vibrators using IC555. Applications of IC555 in Engineering, Block diagram of an adjustable three terminal positive and negative regulators (317,337) typical connection diagram, Introduction to Switch Mode Power supply (SMPS), Block diagram of SMPS, Types of SMPS. Comparison of Linear Power supply and SMPS.							

Reference Books	5
	1. Electronic devices and Circuit Theory", "R. Boylestad", "Pearson Education", 9th Edition
	2 "Electron devices" "S Poornachandra Sasikala" "Scitech" 2nd Edition
	3. "Electronic Devices and Circuits" "Millman Halkias" "TMH" 2000
	4. "Electronic Devices and Circuits", "DavidA Bell", "PHI", 4thEdition
list of Experime	nts
	1. Study and use of Oscilloscope, signal generator to view waveforms and measure amplitude and frequency.
	 V-I characteristics of PN Junction and Zener diodes, and determining its DC and AC resistance.
	3. Studies on half-wave and full-wave rectifier circuits without and with capacitor filter.
	4. Studies on clipper and clamper circuits.
	5. I-V characteristic of an n-p-n and p-n-p transistors, DC biasing the transistor in common-emitter configuration and determination of its operating point (i.e., various voltages and currents).
	6. Study on BJT fixed bias, self-bias, and voltage divider bias configurations.
· · · · · · · · · · · · · · · · · · ·	7. Transfer and Drain Characteristics of JFET (Find gm, rd and μ from characteristics).
	8. Study on FET fixed bias, self-bias configurations.
	9. Darlington Emitter Follower Amplifier.
	10. Differential Amplifier using Bipolar Junction Transistors.
	11. Single staged RC coupled current series emitter coupled feedback amplifier, Two stage RC coupled transistor Amplifier.
	12. Study of MOSFET in common source configuration.
	13. Study of OP-AMP in inverting, non-inverting configuration, summing amplifier, integrator, and differentiator.

Course title:	WO	RKSHOP TECHNOLOGY	Sub code:	2LF	P11		
			Structure:	L	Τ	Р	С
			l	3	1	2	6
Course Object	jective: To develop the technical skills of creating entities from raw materials. To "hands on" training and practice to students for use of various tools, de equipment and machines. To develop ability to understand, plan and impl various processes and operations to be performed on the raw material to object of desired shape and size.				s. To s, dev imple l to c	give vices, ment reate	
Course Outcon	ne:	 Know the importance of general safety Identify the basics of tools and equip metal, machine, welding and smithy. Fabrication of wooden joints and under Make metal joints and sheet metal wor Understand the basics of removal of attain specific shape. Familiarize with the production of sir metal, machine, welding and smithy tra- 	y precautions on di ment's used in fi rstand and joining k. material from v nple models in fi ades.	different shop floors. fitting, carpentry, sheet g of metals. work piece surface to fitting, carpentry, sheet			
Content			No. of hours	ESE	Ma	rks (%)
Module 1: Fitt	ing		8			20)
Use and setting o Term work to inclu	of fittin ude on	ng tools for chipping, cutting, filing, mark e job involving following operations: filing	ing, centre punch to size, drilling a	ing, dr nd tapp	illing ing.	g, tapj	ping.
Module 2: Car	pentr	·y		8		2	0
Use and setting or joints, wood tunin joint and report on	f hand g and 1 1 demo	tools like hacksaws, jack planes, chisels nodern wood turning methods. Term work nstration of a job involving wood tuning.	and gauges for co to include one car	onstruc pentry	tion job i	of va nvolv	rious ing a
Module 3: Smi	thy			8		2	0
Use and setting of	smith	y tools At least one job is to be demonstrated	d				
Module 4: Wel	lding			8		2	0
Use and setting of different job like, I	of tool Lap we	s and equipment's for edge preparation f elding of two plates, butt welding of plates.	for welding jobs	and A	rc w	elding	g for
Module 5: Mac	chinir	ng, CNC Machines & Foundry.		8		2	0
At least one metal demonstrated. At l	tuning least oi	g job is to be demonstrated. One job on CNC ne demonstration of mould making.	C Lathe and CNC	Milling	g ma	chine	to be
Reference Boo	ks						
	1. SI Wa 2. BS 3. W	K Hajra, CHoudhury, A K Hajra, CHoudhur orkshop Technology, Vol. I & II. S Raghuwanshi, A Course in Workshop Tec A .l Chapman, Workshop Technology, Part	ry, & Nirjhar Roy, chnology, Vol. 1 & t I, ll & III	, Eleme & II.	ents o	of	

list of Experim	ents
	1. Wood sizing exercise in planning, marking, sawing, chiselling and grooving to make
	1. Half lap joint
	2. Cross lap joint
	2. Exercise in arc welding for making
	1. Lap joint
	2. Butt joint
	3. Preparation of sand mould for the following
	1. Flange
	2. Anvil
	4. Preparation of joints, markings, cutting and filling for making
	1. V-joint
	2. T-joint
	5. Making of small parts using sheet metal
	1. Tray
	2. Funnel

Course title:	CON	MMUNICATION SKILL	Sub code:	2L1	2		
			Structure:	L	Т	Р	С
				3	1	0	4
Course Object	 The primary objective is to develop in the under-graduate students engineering a level of competence in English required for independent effective communication for academic and social needs. To impart to the students the skills that they need in their academic, and la in their professional pursuit. To train the students to adopt an innovat approach to English language teaching and learning. 					and atter ative	
Course Outcon	ne:	The students will be able to express the different levels of people in their academic	emselves in a me and social domain	eaning 1s.	gful	manne	er to
Content			No. of hours	ES	ΕM	arks ((%)
Module 1: Con	nmun	ication & Listening	8	5		2	20
An introduction - Its role and importance in the corporate world, Tools of communication, Barriers, Levels of communication, English for Specific purposes and English for technical purposes, Listening process & practice, Exposure to recorded & structured talks, class room lectures, Problems in comprehension & retention, Note-taking practice, Listening tests- Importance of listening in the corporate world.							evels ss & on &
Module 2: Rea	ding	& Speaking		8	3	2	20
Introduction of dif skimming, scannir Vocabulary extens Improving respond	fferent ng, infe sion. H ding ca	kinds of reading materials: technical & non- erring, predicting and responding to content, Barriers to speaking, Building self-confiden apacity, Extempore speech practice, Speech a	technical, Differe Guessing from co ce & fluency, Co ssessment.	nt rea ontext	ding t, No satio	strate te mal n prac	gies: king, ctice,
Module 3: Wri	iting			8	3	2	20
Effective writing appropriateness, b descriptions& inst	g prac previty ructior	ctice, Vocabulary expansion, Effective & clarity in writing, Cohesion & coheren as, Paragraph writing, Introduction to report v	sentences: role ce in writing, W vriting.	e of riting	acc of c	ceptab lefinit	ility, ions,
Module 4: Eng	ineer	ing Ethics		8	3	2	20
What is professio Morality, Engined Standards, The Sta Ethics, Blame-Re problems of Many	on?, Er ering andard sponsi Hands	ngineering and Professionalism, Models of Ethics, Variety of moral issues, Respon Care, The Positive face of Engineering Ethi bility and Causation types of inquiry mo s, Kohlburg's theory, Gilligan's theory Imped	Professionalism, sibility in Engin cs, The Negative ral dilemmas, m liments to Respon	Type eering Face oral a nsible	es of g, E of E auton Acti	Ethic ngine ngine omy, on.	ering ering The
Module 5: Safe	ety &	problem Framing		8	3	2	20
Engineering as social experimentation, Framing the problem, Determining the facts codes of ethics, clarifying Concepts, Application issues, Common Ground, General principles, Utilitarian thinking respect for persons, Engineer's Responsibility for Safety, Social and Value dimensions of Technology, Technology Pessimism, The Perils of Technological Optimism, The Promise of Technology , Computer, Technology Privacy and Social Policy, Honesty, Integrity & Reliability, Risk, Safety and Liability in Engineering, Risk Benefit Analysis – Collegiality and loyalty.							

Reference Books	5
1.	Krishna Mohan and Meenakshi Raman (2000) Effective English Communication,
	Tata McGraw Hill, New Delhi.
2.	Meenakshi Raman and Sangeetha Sharma (2006) Technical Communication, Oxford
	University Press, New Delhi.
3.	M. Ashraf Rizvi (2005) Effective Technical Communication, Tata McGraw-Hill,
	New Delhi.
4.	Christopher Turk (1985) Effective S peaking, E & FN Spon, London
5.	Golding S.R. (1978) Common Errors in English Language, Macmillan.
6.	Mike Martin and Roland Schinzinger, "Ethics in Engineering" McGraw Hill
7.	Charles E Harris, Micheal J Rabins, "Engineering Ethics, Cengage Learning
8.	Edmund G Seebauer and Robert L Barry, "Fundamentals of Ethics for Scientists and
	Engineers, Oxford University Press
9.	Caroline Whitback Ethics in Engineering Practice and Research, Cambridgs
	University Press.

Course title: EN	GINEERING MATHEMATICS - III	Sub code:	3L	13			
		Structure:	L	Т	Р	С	
			3	2	0	5	
 Course Objective: To explain the importance of numerical methods in sole equation, integration and algebraic equations To explain the significance of Laplace and z transform and differential and difference equation. To apply the different statistical and curve fitting techniques data. To describe the theory of complex variable 					ffere n sol	ential lving ht of	
Course Outcome:On successful completion of teaching-learning and evaluation activities, a stu would be able to apply fundamental concepts of Ordinary Differential Equa and Partial Differential Equations and the basic numerical methods for solution. Solve the problems choosing the most suitable method.					a stu Equa for	ident tions their	
Content		No. of hours	ES (%	E M)	arks	5	
Module 1: Numer	ical Method	8		2	20		
Lagrange's interpolati Picard's method, Tayle	on formula, Numerical differentiation, solution or 's series method, Euler's modified method and	of ordinary differed d Runge-Kutta four	entia th or	l equ der r	uatio neth	n by od.	
Module 2: Laplace	e Transform	8		4	20		
Laplace Transform, I integrals. Inverse Lapl	Definition, and Properties, Laplace transform ace transforms convolution theorem solution of 1	of elementary fund LDE by Laplace Tra	ction ansfo	, de orm.	rivat	ives,	
Module 3: Statisti	cs	8		4	20		
Measures of central Coefficient of Correlat	tendency, Measures of dispersion, Momentation, lines of regression of bivariate data, fitting	s, skewness, Kurto of curve, least squar	osis. re pri	Co incip	rrela de.	tion,	
Module 4: Comple	ex Variable	8			20		
Function of Complex function, Taylor's & I unit circle & along the	Variables, Introduction, Analytic function, Ca Laurent's series, Singularities, Residues, Cauchy upper half semi-circle, conformal and bilinear th	uchy-Riemann Equ V Residue theorem, ransformation.	ation Inte	ns, H grati	Harm ion a	ionic llong	
Module 5: Z Tran	sform&Vector Calculus	8		4	20		
Z- Transform, Z-transform of elementary function & properties. Inverse Ztransforms. Solution of difference equation by Z- transforms. Vector calculus, differention, gradient, divergence, curl of vector function. Vector integration. Green's Theorem, stoke's theorem, Gauss divergence theorem. Irrorational & solenoidal fields.							
Reference Books							
1	 P.N. Wartikar and J.N.Wartika, A Text Book II) B.S. Grewal, Higher Engineering Mathematics 	of Engineering Mat	thma	tics	(Vol	. I &	
	. Erwin Kreyszing, Advanced Engineering Mat	hematics, Willey E	aster	n Lt	d.	.11	

Course title:	Elect	tronic Measurement	Sub code:	code: 3LP14			
	&Ins	strumentation		_		_	
			Structure:	L	Т	Р	С
				3	0	2	5
Course Objective: The primary aim of this subject is to acquaint principles of measuring instruments and show how for the measurement of large number of variables.			quaint the studen v how each of the bles.	ts w n cai	ith 1 n be	the expl	basic oited
 Course Outcome: Explain basic concepts and definitions in measurement. Explain the operation and design of electronic instruments for paramet measurement and operation of different Transducers Explain the operation of oscilloscopes and the basic circuit blocks in the design of an oscilloscope. Explain the circuitry and design of various function generators. 						neter h the	
Content			INO. OF HOUTS	ЕЭ		arks	5(70)
Module 1: Fui Instrumentati	ndam on	entals of Electronic Measurement and	d 6	20			
Necessity of ele Measurements, F Elements of meas errors, Statistical	ctronic unction uremer analysi	Measurement, Block diagram of electron of instruments and measurement systems, A at system, Types of instruments, Theory of errors s, probability of errors, Limiting errors, Standa	nc measurement applications ofmeasures, Accuracy and H rds of measurement	syst asure Precis nt.	emen, sion,	Type t sys Typ	es of stem, stes of
Module 2: Ele	ctrom	echanical Instruments	8			20	
Construction of C mechanism, DC Ammeters, Ohm-	Galvano voltmet meters	ometer, Suspension Galvanometer, Torque an ter; AC voltmeters; Peak, average and true F and their design' AC indicatinginstruments, W	d deflection Galv MSvoltmeters; D att-hour meter; Po	anon igita wer	neter I Mi facto	, PN llime or me	AMC etres; eter.
Module 3: AC	, DC l	Bridges&Transducers	8			20	
DC Bridges : Wheatstone Bridge, Kelvin Bridge AC Bridges and their applications : Maxwell's Bridge, Hay's Bridge, Schering Bridge, Desauty's Bridge, Wein Bridge, Detectors for AC bridges. Static and dynamic characteristics, Classification of transducers, Capacitive transducer, Inductive transducer, Resistive transducer, RVDT, Strain Gauge, RTD, Optical Transducers, Hall effect transducer, Piezoelectric transducers, Transducers for measurement of Pressure, Temperature,Level, Displacement, Flow.							
Module 4: Osc	cillosc	ope and Signal Generators	8			20	
CRO : Types, Dual trace, High frequency, sampling and storage oscilloscopes, Applications of CRO. Signal Generators : Introduction, Sine-wave generator, standard signal generators, Audio frequency signal generation, RF generator, Pulse generator, Function generator.							
Module 5: Sig	nal Aı	nalyzer and Data Acquisition System	8			20	
Construction and operation of Signal analyzer, Wave analyzer, Harmonic Distortion analyzer, Spectrum analyzer and Logic analyzer; Signal conditioning and its necessity, process adopted in Signal conditioning, Functions of Signal conditioning, AC/DC Conditioning systems, Data conversion:ADC, DAC, Generalized data acquisition system: single channel and multi-channel DAS.							

Reference Bo	oks	
1 2 3 4	. A.I Tec 2. A.I Rai 3. S.S	 D. Helfrick and W.D. Cooper : "Modern Electronic Instrumentation and Measurement chniques", PHI Publications. K. Sawhney : "Electrical and Electronic Measurement and Instrumentation", Dhanpat & Sons Publications G. Kalsi : "Electronics Measurements", Mc Graw Hill Publications. H. Oliver and LM Cage : "Electronics Measurement and Instrumentation" Mc Graw
	Hil	l Publications
List of Experim	ents	
	1.	Displacement measurement using LVDT
	2.	Force/ Pressure measurement using Strain Gauge
	3.	Study of Data Acquisition System
	4.	Study of LabVIEW software
	5.	Study of LabVIEW projects, SubVIs, Block Diagram, Front Panel
	6.	Use of Loops, Case Structure, Sequence, Timing, Formula Node, Expression Node
	7.	Use of Arrays and Clusters
	8.	Study of LabVIEWs Visual display
	9.	Exploring String and File I/O
	10	Data Acquisition in LabVIEW

Course title:	M	anagerial Economics	Sub o	code:	3L15				
			Struc	cture:	L	Т	Р	С	
					3	2	0	5	
Course Objective: The objective of this course is to equip the student with the basic input Managerial Economics and Economic Environment of business and to i analytical skills in helping them take sound financial decisions for achieved higher organizational productivity.						uts of mpart ieving			
Course Outco	ome:	After completion of this course, the saspects of Managerial Economics and an therein will help them to make sound economic environment and market situat	course, the student will able to understand various phomics and analysis of financial statements and inputs make sound and effective decisions under different d market situations.					arious inputs ferent	
Content				No. of ho	urs	ESE	Mark	KS(%)	
Module 1: In	trodu	iction To Managerial Economics			8		20)	
Definition, nature Demand Determ	re and inants	scope of managerial economics- relation w , Law of Demand and its exceptions.	vith oth	er discipli	nes- I	Demar	nd Ana	alysis:	
Module 2: El	astici	ty Of Demand			8		20)	
Definition, Type governing dema Expert opinion Forecasting).	es, Me and fo meth	easurement and Significance of Elasticity of precasting, methods of demand forecasting od, Test marketing, Controlled experiment	of Dem g (Sur nts, Ju	and. Dema vey metho dgmental	and fo ods, S appro	brecas Statisti bach	ting, f calme to De	actors thods, emand	
Module 3: Th	neory	Of Production And Cost Analysis			8		20)	
Module 4: In	trodu	iction To Markets And PricingPolic	ies		8		20)	
Market structur competition. Pri cost plus pricing peak load pricing	es: T ce-Ou g, mar g.	ypes of competition, features of perfect tput determination under perfect competition ginal cost, limit pricing, skimming pricing,	comp on and bundli	etition, m monopoly ng pricing,	onopo – Me seale	oly- r ethods ed bid	nonop of Pı pricir	olistic ricing- ng and	
Module 5: Bu	isines	ss Organisations And New			8		20)	
EconomicEnvironment Image: Characteristic features of business, features and evaluation of sole Proprietorship, partnership, Joint Stock Company, public enterprisesand their types, changing business environment in post-liberalizationscenario.									
Reference Bo	oks								
	1	Aryasri: Managerial Economics and Financ	ial Ana	lysis, 4/e, '	TMH				
	2	Varshney & Maheswari: Managerial Econo	mics, S	ultan Char	nd				
	3	Premchand Babu, Madan Mohan:Financial	Accou	nting and A	Analys	sis,Hir	nalaya	ı	
	4	S.A. Siddiqui and A.S. Siddiqui: Manageria New Age International	al Econ	omics and	Finan	cial A	nalysi	.8,	
	5	Joseph G. Nellis and David Parker: Principl New Delhi	les of B	Susiness Ec	onom	ics, P	earson	, 2/e,	
	6	Domnick Salvatore: Managerial Economics	s in a G	lobal Econ	omy,	Cenga	age		

Course Title:	PY	THON FOR IOT	S	ub code:					
			S	tructure:	L	Τ	Р	C	
					3	0	2	5	
 Course Objective: To study Python Programming fundamental To study and develop python programming application for To study raspberry pi and design IoT applications. 									
Course Outcom	e:	Able to understand various pythonImplement Various IoT system us	n web so sing Py	crapping thon Programm	ing and	raspt	erry pi		
Content				No. of hour	s ES	E Ma	arks (%)	
Module 1: Pyth	on C	oncepts, Data Structures, Class	ses		3		20		
Interpreter – Progra Sequences - Strings Binary Files - Read	am Ex s, Tup ling ar	ecution – Statements – Expressions – les, Lists and - Class Definition – Con d Writing.	Flow (structo	Controls – Fund rs – Inheritance	etions - e – Over	Nume loadi	eric Ty ng – Te	pes – ext &	
Module 2: Data	Wra	angling:			8		20)	
Combining and Me Regular Expression	erging	Data Sets – Reshaping and Pivoting	– Data	Transformatio	n – Stri	ng M	anipula	ation,	
Module 3: Data	Aggre	egation, Group Operations, Time ser	ries & V	Web	8		20)	
Scrapping :									
GoupBy Mechanic Cross Tabulations Shifting. Data Act Downloading web	s – D – Dat quisiti pagest	Pata Aggregation – GroupWise Opera e and Time Date Type tools – Time ion by Scraping web applications – through form submission – CSS Select	tions a Series Submit ors.	nd Transforma Basics – Data tting a form -	tions – Ranges, Fetchi	Pivot Freq ng w	Tables uencies eb pag	s and s and ges –	
Module 4: – Vis	ualiz	ation in Python :			8		2	20	
Matplot lib package setting values – Pat	e – Ple ches.	otting Graphs – Controlling Graph – A	dding '	Text – More G	raph Ty	pes –	Getting	g and	
Module 5: Impl	emei	ntation using Raspberry Pi :			8	8 20		20	
Working with Raspberry Pi 3 Model - Installing OS and Designing Systems using Raspberry pi - Configuring Raspberry Pi for VNC Connection - Getting introduced to Linux OS Basic Linux commands and uses - Getting Started with Python - Interface sensor and Actuator with Raspberry Pi									
Text/Reference	Bool	ks:							
 Mark Lutz, "Learning Python", O'Reilly Media, 5th Edition, 2016. White, "Hadoop: The Definitive Guide", Third Edition - O'Reilly, 2012. Brandon Rhodes and John Goerzen, "Foundations of Python Network Programmin The Comprehensive Guide to Building Network Applications with Python", Apre Second Edition, 2016. 						ning: press,			

List of Experime	ents:
	1. Design IoT gateway using Raspberry Pi board and necessary devices.
	2. Understand and Implement five basic and advance python program using raspberry pi python IDE
	3. Interface RGB LED with raspberry pi using python programming
	4. Interface relay board and Implement home automation IoT Programmed using python programming
	5. Control DC Motor using raspberry pi and python programming
	6. Design web control IoT applications using raspberry pi and python programming
	7. Interface DHT 11 with raspberry pi using python programming
	8. Implement IoT DHT11 MQTT protocol using Python programming

Course title:	Digital Lo	gic And Circuits	Sub code:	3LF			
			Structure:	L	Τ	Р	С
				3	0	2	5
Course Object	tive: • 1	 Understanding the basics of Digital Electronics and different number systems and conversion between them. Design and construction of the basic and universal logic gates. Studying the Boolean algebra and simplification of Boolean expression using different methods. Study and construction of sequential logic circuits, understanding various design of flip flops. Studying the programmable logic devices, shift registers counters and various memory devices. 					
Course Outco	me: After funda betwe vario shift	After studying this course students would have a thorough understanding of the fundamental concepts and techniques used in digital electronics.Gain knowledge between different types of number systems, and their conversions. Design various logic gates and simplify Boolean equations. Design various flip flops, shift registers and determining outputs. Design different types of counters.					
Content			No. of h	ours	ESE	Marl	KS(%)
Module 1: Nu	mber Syster	m & Codes	8		20		
Number systems Division), Dimin code, error detect	and their inte ished radix an ion and correc	r-conversion, Binary Arithmetic (and radix compliments, BCD code tion.	Addition, Subtrac es, Excess-3 code	tion, M , Gray	lultip code	licatio e, Har	on and nming
Module 2: Log	gic Gates &	Logic Families		8	20)	
Digital Logic Ga characteristics, M Families.	ites, Various IOS and CM	Logic Families like RTL, DTL, OS devices, TTL CMOS Interfac	TTL and ECL, ing, IEEE/ANSI-	I2L, wo	orkin ntatio	ng and on of	l their Logic
Module 3: Con	nbinationa	Logic Design		8	20)	
Boolean Algebra, Basic Theorems and properties of Boolean Algebra, Boolean Functions, Canonical and Standard forms-map method, Two, Three, Four and Five variable maps, Sum of products and Product of Sums Simplification, NAND and NOR implementation, incompletely specified functions, Ex-OR functions, The tabulation method, Determination of Prime implicants, Selection of Essential Prime implicants, The cube notation, Sharp operation, Iterative Consensus, Generalized Consensus, Minimization of Multiple output switching functions, Determining Prime implicants using Generalized Consensus, Finding a Minimum cover, Breaking cyclic and similar structures, Standard IC's and their applications.							
Module 4: MSI and PLD Components				8	8 20		
Binary adder and sub tractor, Multiplexers, Decoders/De-multiplexers, Read Only Memory, Programmable Logic Arrays, Programmable Array Logic, Implementation of Combinatorial Logic using these devices.							
Module 5: Sequential Logic Design820							
Introduction, S-R Flip-flops, JK flip-flop, D flip-flop, T flip-flop, master slave flip-flop. Flip-flop excitation table, Interconversion of flip-flop, Classification of sequential circuits, Register and Counter circuits. A to D and D to A converter circuits.							
Reference Boo	oks						
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	1	Digital Design: M. Morris Mano, Prentice Hall of India.					
	2	Modern Digital Electronic: R.P.Jain (TMH)					
	3	Digital Principle and Applications Malvino and Leach- (TMH)					
	4	Modern Digital Systems Design: Cheung (WPC)					
	5	Fundamentals of Digital Electronics: Anand Kumar (PHI)					
	6	Subrata Ghosal, "Digital Electronics," Cengage publication, 2nd edition, 2018					
	7	A. K. Singh, "Foundation of Digital Electronics & Logic Design," New Age Int. Publishers.					
	8	D.V. Hall, "Digital Circuits and Systems," Tata McGraw Hill, 1989.					
	9	W.H. Gothmann, "Digital Electronics- An Introduction to Theory and Practice," PHI, 2 nd edition, 2006.					
list of Experin	nents						
	1	Introduction to digital electronics lab- nomenclature of digital ICs, specifications, study of the data sheet, Concept of VCC and ground, verification of the truth tables of logic gates using TTL ICs					
	2	Implementation of the given Boolean function using logic gates in both SOP and POS forms.					
	3	Verification of state tables of RS, JK, T and D flip-flops using NAND & NOR gates.					
	4	Implementation and verification of Decoder using logic gates.					
	5	Implementation and verification of Encoder using logic gates.					
	6	Implementation of 4:1 multiplexer using logic gates.					
	7	Implementation of 1:4 de-multiplexer using logic gates.					
	8	Implementation of 4-bit parallel adder using 7483 IC.					
	9	Design, and verify the 4-bit synchronous counter.					
	10	Design, and verify the 4-bit asynchronous counter.					
	11	Implementation of Mini Project using digital integrated circuits and other components.					

Course title:	Line	ear Electrical Networks	Sub	code:	3LP18				
	1		Structure: L T					С	
					3	0	2	5	
 Course Objective: To study the basics of circuit analysis. To solve D.C. circuits by using KVL and KCL. To solve A.C. circuits by using KVL and KCL. To apply theorems for finding the solutions of network problems. Analyse the frequency response of circuits and to obtain the correlati between time domain and frequency domain response specifications. Design low pass, high pass, band pass and band elimination filter networks 									
Course Outcon	ne:	Understand basics electrical circuits w electrical network theorems. Apply 1 transient analysis. Determine differe frequency domain techniques. Analyse an electrical circuit. Design network filt	vith nod Laplace ent net RLC c ers.	al and mes transform work func ircuits. Det	sh ana for s tions. termin	lysis stead App e the	Appr y stat preciat stabi	reciate e and te the lity of	
Content				No. of ho	urs	ESE	Marl	ks(%)	
Module 1: Intr	oduc	tion&Network Theorems			8		20		
Laplace transform and duality of neu Thevenin's and N Tellegan's theorem	n, conc tworks lorton's n, anal	ept of independent and dependent source, Brief review of Signals and Systems. s theorem, Millman's theorem, maximum ysis of circuits using theorems.	es, anal Superp n powe	ysis of spe position and r transfer t	cial si l Reci heorer	gnal proci	wave ity the mpen	forms, eorem, sation,	
Module 2: 1ra	nsien	t Analysis of Networks			8		20) 	
condition, Solution	s, Trar n using	differential equation approach and Lapla	for DC	sform meth	od.	excita	ation,	Initial	
Module 3: Netv	work	Analysis			8	8 20			
State variable met large scale netwo representation, An	thod, A orks, 1 alysis	nalytic and numerical solutions, Two Po Formulation and solution of network using NGSPICE.	ort Netw graph	orks, Grap of simple	h theo netwo	retic rks,	analy State	sis for space	
Module 4: Net	work	Synthesis			8		20)	
Network reliabilit Foster and Causer	y, Hur forms	witz Polynomials, Positive real function of realization, Transmission zeroes, Synt	s, Prope hesis of	erties of RC transfer fu	C, RL nction	& L s.	C netv	works,	
Module 5: Pass	sive F	'ilter Design			8		20)	
Butter worth and Frequency and imp	Butter worth and Chebyshev approximations, Normalized specifications, Frequency transformations, Frequency and impedancede-normalisation, Types of frequency selective filters, Linear phase filters.								

Reference Books	S	
	1	"Network and systems" by D.Roy - Choudhary
	2	"Circuit Analysis - with computer applications to problem solving" by Someshwar C. Gupta, Jon W. Bayless, Behrouz Peikari.
	3	Franklin F. Kuo, "Network Analysis and Synthesis", John Wiley.
	4	Vanvalkenburg, "Network Analysis ", Printice Hall of India Pvt. Ltd., New Delhi, 1994.
	5	A William Hayt, "Engineering Circuit Analysis," 8th Edition, McGraw-Hill Education.
	6	A. Anand Kumar, "Network Analysis and Synthesis," PHI publication, 2019.
	7	Sudhakar, A., Shyammohan, S. P., "Circuits and Network," Tata McGraw-Hill New Delhi, 1994.
list of Experime	nts	
	1	Verification of Kirchhoff's laws.
	2	Verification of Superposition theorem.
	3	Verification of Thevenin's Theorem and Maximum power transfer theorem.
	4	Verification of Tallegen's theorem.
	5	Measurement of power and power factor in a single phase AC series inductive circuit and study improvement of power factor using capacitor.
	6	Study of phenomenon of resonance in RLC series circuit and obtain resonant frequency.
	7	Determination of parameters of AC single phase series RLC circuit.
	8	To find poles and zeros of admittance function.
	9	Design and find cut-off frequency of low pass and high pass filters.
	10	Design and find the pass band frequencies of band pass filters.
	11	Design and find the stop band frequencies of band reject filters.

Course titl	e:	Power Electron	ics	Sub code:4LP19							
				Structure:	L	Т	Р	С			
					3	0	2	5			
 Course Objective: To study the characteristics and operation of the various semicond devices. To analysis different power electronic converters. To learn the practical application of the different type of converters To learn the practical application of the different type of converters To learn the practical application of the different type of converters To learn the practical application of the different type of converters To learn the practical application of the different type of converters To learn the practical application of the different type of converters 											
		with several	power electronic switches.	N Character			<u>/[1</u>				
Content	D				E	SE I		(%)			
Nodule 1:	Powe	r Electronic Co	nverters	δ		_	20				
Phase control Typical control for integral co	lled (A ol circ ontrol/	C/DC), 1-phase/3-2 hit; Harmonics and hase control strate	Phase, Semi/full/dual; Analysi power factor; Voltage control gies, Cycloconverter.	s and performance lers (AC/DC), Typ	wit ical	h pa cont	ssive rol c	e load, ircuits			
Module 2:	Chop	per		8			20				
Basic choppe chopper circu	er class 1it, Sou	fication, Basic cho ce filter	opper operation, Control strate	gies, Chopper conf	igura	ation	, Th	yristor			
Module 3:	Inve	ter		8			20				
Classification Performance Classification and Harmoni	n of i param n of Re c reduc	verter, Single Ph eter of inverter, V sonant Converter: ion.	ase: Half bridge voltage so /oltage control of inverter, F Series resonant inverters, Para	urce inverters, Fu PWM inverter, Th allel inverter, Curro	ll b ree ent s	oridgo phas sourc	e in e in e In	verter, verter, verter,			
Module 4:	Cont	ol of DC Drive	s and AC drives	8			20				
Criteria for se DC motor co phase drives/ Basic princip motor drives,	electin ntrol so Three les of Adjus	drive components hemes for DC mote hase drives, DC-D peration and its cha able AC drives.	, Basic characteristics of DC as or speed control, DC drives, ar C converter drives, PLL drives aracteristics, Speed control me	nd its equivalent cin ad adjustable speed s, Closed loop cont thod, Closed loop c	rcuit DC rol c	, Me driv of DC rol of	thod e. Si C driv f ind	s of ngle ves, uction			
Module 5:	Powe	· Electronics A _l	pplication	8			20				
Battery charg UPS, SMPS, stabilizer, Te the utility grid	Battery charging regulator, Flasher circuits, Protective SCR circuits, Ring counter, Time delay circuits, UPS, SMPS, Static relay, Emergency lightening system, Single phase preventer, Servo controlled voltage stabilizer, Temp Controller, Static circuit breaker, Renewable energy sources and energy storage system to the utility grid.							rcuits, oltage tem to			
Reference	Book										
	1	P.C. Sen , " Power	r Electronics ", Tata McGraw I	Hill							
	2	M.H. Rashid , " Po	wer Electronics ", John Wiley	v & Sons							
	3	General Electric, "	SCR manual "								
	4	G. K. Dubey, S. R	Doradle, "Thyristorised Powe	r Controller "	Controller "						

	5	J. M. Jalnekar and N. B. Pasalkar, "Power Electronics" Technical Publication
	6	Ned Mohan, T.M. Undeland and W.P. Robbins, "Power Electronics: Converters, Applications and Design", John Wiley, Singapore, 1994
	7	M D Singh and K. B Khanchandani, "Power Electronics", Tata McGraw Hill
	8	B.K.Bose, "Power Electronics & A.C. Drives", Prentice Hall, 1986.
list of Exp	erim	ents
	1	Thyristor V/I characteristics & Measurement of holding current of SCR.
	2	Firing circuit of SCR.
	3	Commutation of SCR.
	4	TRIAC and DIAC characteristics.
	5	Single phase/Three phase, Thyristor –Bridge converter with R/RL load
	6	Series inverter
	7	Parallel inverter
	8	SCR application (Any one).
	9	DC chopper
	10	AC/DC drives

Course title:	Elect	tromagnetics and Field Theory	Sub code:	41					
			Structure:	L	Т	Р	С		
				3	2	0	5		
Course Object	erstand and deve s in modern cor omagnetic wave Antennas	elop app mmunicates and ra	lication diatii	ons re	lated tems				
Course Outco	me:	To understand the concept of electromagn dynamic electromagnetic waves, concept strong concept waveguide, transmission li	etic waves , deta of simple dipole nes and smith cl	ails of st antenna hart	atic a is and	nd I to bu	ild a		
Content			No. of ho	ours I	ESE I	Marks	\$(%)		
Module 1: Veo	ctor ca	alculus		2		5			
Orthogonal Coo Divergence, Curl	rdinate - their	System, Transformations of coordinat physical interpretations; Laplacian operate	te systems; De or.	el oper	ator;	Grad	ient,		
Module 2: Ele	ctrost	atics		8		20			
Coulomb's Law, Density, Gauss I Equations for Ele Dielectric Consta Poisson's and Lap Problems.	Electri Law and ectrosta ant, Iso place's	ac Field Intensity – Fields due to Differe d Applications, Electric Potential, Relation tic Fields, Electric dipole, Energy Density, potropic and Homogeneous Dielectrics, C Equations, Capacitance – Parallel Plate, Co	ent Charge Dist ns Between E a , Convection an continuity Equation coaxial, Spherical	ribution and V, 1 d Condu tion, Re l Capaci	s, Ele Maxv uction elaxat tors,	ectric vell's n Curr ion T Illustr	Flux Two ents, 'ime, ative		
Module 3: Ma	gneto	statics&Maxwell's Equations		10		25			
Biot-Savart Law, Equations for Ma Magnetic torque a Faraday's Law an Maxwell's Equa Electromagnetic f	Biot-Savart Law, Ampere's Circuital Law and Applications, Magnetic Flux Density, Maxwell's Two Equations for Magneto static Fields, Magnetic Scalar and Vector Potentials, Forces due to Magnetic Fields, Magnetic torque and moment, Magnetic dipole, Inductances and Magnetic Energy, Illustrative Problems. Faraday's Law and Transformer e.m.f, Inconsistency of Ampere's Law and Displacement Current Density, Maxwell's Equations in Different Final Forms and Word Statements. Boundary Conditions of Electromagnetic fields: Dielectric-Dielectric and Dielectric-Conductor Interfaces, Illustrative Problems.								
Module 4: EM	[Wav	e Characteristics		10		25			
Wave Equations for Conducting and Perfect Dielectric Media, Uniform Plane Waves – Definition, All Relations between E & H, Sinusoidal Variations, Wave Propagation in Lossless and Conducting Media, Conductors & Dielectrics – Characterization, Wave Propagation in Good Conductors and Good Dielectrics, Polarization,Reflection and Refraction of Plane Waves – Normal and Oblique Incidences, for both Perfect Conductor and Perfect Dielectrics, Brewster Angle, Critical Angle and Total Internal Reflection, Surface Impedance, Pointing Vector, and Pointing Theorem – Applications, Power Loss in a Plane Conductor, Illustrative Problems									
Module 5: Tra	nsmis	sion Lines&Antennas		10		25			

Transmission Lines: Types, Transmission line parameters (Primary and Secondary), Transmission line equations, Input impedance, Standing wave ratio & power, Smith chart & its applications, Applications of transmission lines of various lengths, Micro- strip transmission lines – input impedance, Illustrative Problems.

Antenna Concepts, Antenna Characteristic; Hertzian dipole (Radiation Fields, Radiation Resistance, Radiation patterns, Directive Gain); Properties and typical applications of Half-wave dipole, Loop antenna, Yagi-Uda array, Array Antennas.

Reference	Book	ζ <u>s</u>
	1	Principles of Electromagnetics, 4th Edition, Matthew O H Sadiku, Oxford University
		Press.
	2	Electromagnetic Field Theory & Transmission Lines, G.S.N. Raju, Pearson Education
	3	Electromagnetic Waves Shevgaonkar, Tata-McGaw-Hillr –R K
	4	Engineering Electromagnetics, 2ed Edition - Nathan Ida, Springer India
	5	Fields & Waves in Communication Electronics, S. Ramo, J. R. Whinnery& T. Van
		Duzer, John Wiley
	6	Electromagnetic Theory & Applications, A. K. Saxena, Narosa Publishing House Pvt.
		Ltd.
	7	Electromagnetics, 2ed Edition – J. A. Edminister, Tata-McGraw-Hill.
	8	Engineering Electromagnetics, 7 th Edition-W.H.Hayt& J. A. Buck, Tata-McGraw-Hill

Course title	: N	Micro	oproces	sor and	d Micro	ocontro	oller	Sub o	code:	de: 4LP21					
			Structu						cture:	L	Т	Р	С		
										3	0	2	5		
Course Obje	ective	/e: 7 i	This subject deals about the basic 16-bit (8086) processor and an 8-bit (8051) controllers, their architecture, internal organization and their functions, interfacing an external device with the processors/ controllers.												
Course Outc	come	e: I s t	The stud Micropro structure Micropro through s	ent will ocessor b of the ocessors serial & p	be able based per Microp & Micro parallel p	e to appl rsonal co processor ocontroll ports.	ly a b omput , dist lers ar	er syste er syste inguish nd anal	oncept of d em, identify and analy yze the dat	igita a d yze ta tr	al fu letai the ansf	inda led s pro fer in	mentals to s/w & h/w operties of nformation		
Content		I							No. of ho	ars	E	SE N	Marks(%)		
Module 1: 80	0 86 A	Archi	itecture	è					8				20		
Introduction to modes, Accessi Real and Protec	adva ng im ted m	anced 1 mmedia modes	micropro ate & Re of operat	cessors, gister da ion, Add	8086 in ata, Mem dress trar	nternal ar nory acce nslation,	chitec essing. Memo	ture, M 8086 r ory orga	lemory, Org ninimum/m nization, P	gani axir agin	zatio num g.	on, A n mo	Addressing de system,		
Module 2: 80	086 I	Instru	uction S	Set					8				20		
8086 data trans Conditional & interrupts respo 8259 a interrupt	offer in Unc onses, t cont	instruct conditi s, 8086 ntroller,	tions, Ar ional bra interrup , Exampl	ithmetic inch ins t types, l es using	instruct structions Example 8259 A	ions, Bit s, Proces es, Hardy with 808	mani ssor c ware in 38.	pulation control nterrup	n instructio instruction application	ns, 1 s, C ns, I	Strin Over Mult	ng in view tiple	structions, of 8086 interrupts,		
Module 3: K	eybo	oard	& Disp	lay inte	erfacin	g			8				20		
Keyboard inter description, Fur 8086.	facing nctior	ng, inte onal des	erfacing scription	LED dis , Softwa	splays, 8 ire opera	3279 key ation, Inte	board erface	/ displa consid	y controlle erations, C	r, B rcui	floci t co	c dia	ngram, Pin etions with		
Module 4: A	dvar	nced	Microp	orocess	ors				8			20			
Introduction to architecture, P Architecture : P	Pent ipelin Proper	ntium a ning I erties of	and Pent Introduct f RISC S	tium pro ion to 1 ystems (o archite Pentium Comparis	ectures: I II, Per son with	RISC ntium CISC	concep III an archite	ts, BUS o d Pentium cture.	pera 4	tion pro	, Su cesso	iper scalar ors. RISC		
Module 5: In	ntrod	ductio	on to M	licroco	ntrolle	rs			8				20		
Study of micro micro controller using microcon and other indust	Study of micro controller (MCS 51 family- 8051) - Architecture - Comparison of various families of 8 bit micro controllers. System design techniques interfacing of LCD, Stepper motor, Keyboard and ADC /DAC using microcontrollers. Study of micro controller 8096 - Architecture, Typical application in automotive and other industries, Introduction to super pipelined super scalar architectures of microcontrollers.														
Reference B	ooks	S													
	1	D. H	all, " Mi	croproce	essor and	Interfac	ing (8	086), 21	nd ed,TMH						
	2	Gibs	on, " Mic	croproce	ssor and	Interfac	ing", 2	2nd edit	tion, PHI						
	3	Trieb softw	oel and S vare, Har	ingh, " T dware ar	The 8088 nd Appli	and 808 cations '	86 Mic ', PHI	croproc	essors : Pro	gran	nmi	ng, I	nterfacing,		

	4	Brey, " Intel Microprocessors, 8086 to Pentium and Pentium pro processor: Architecture, Programming and interfacing", 4th edition, PHI / Pearson
	5	Ajay Deshmukh, "Microcontrollers (Theory and Applications) –TMH
	6	M.A. Mazidi&J.G.Mazidi, The 8051 Microcontroller and Embedded systems 3rd Indian reprint, Pearson Education.
list of Expen	rimei	nts
	1	Microprocessor 8086 based development system
	2	Simple arithmetic programs
	3	Array manipulation programs
	4	Code conversion programs
	5	LED Bank interface
	6	ADC ,DAC interface
	7	Stepper Motor interface
	8	Programming exercises in c and assembly language covering program and data memory
	9	i/o port, Peripheral and external interrupt, power saving modes
	10	Interfacing of devices like keys, relays, leads, sevensegment, LCDModule, Matrix keyboard etc.

Course title:	Ana	log Communication	Sub code:	4 L	P22			
	Structure:							
	3	0	2	5				
Course Object	nunicat ion tecl ivers. ce of A city.	unication systems. on techniques. vers. æ of Analog ity.						
Course Outcor	ne:	Acquire knowledge on the basic concep Analyse the Analog modulated and den noise on the performance of communic concepts of information and capacity.	of Analog Co nodulated system cation systems.	ommur ns. Vei Know	ify t the	on Sy he eff fundar	stems. Fect of nental	
Content			No. of hours	ESE	Mar	ks(%)		
Module 1: Intr	oduc	tion	8			20		
carrier communic sideband suppress modulator, Balanc signals, Quadratus representation of Generation of SSE	cation, sed ca ced mo re amp SSB 3 signa	Amplitude Modulation (AM), Rectifier rrier (DSB-SC) modulation & its demo dulator, Frequency mixer, sideband and ca plitude modulation (QAM), Single sideba signals & their demodulation schemes ls, Vestigial sideband (VSB) modulator & co odulation & Demodulation	detector, Enve odulation, Switc arrier power of A and (SSB) trans (with carrier, and demodulator, Illu	elope of hing n AM, G smissio nd sup istrativ	letec nodu enera n, T press e Pro	etor, I lators, ation o ime d sed ca oblems 20	Double Ring of AM omain arrier), s.	
Concert of insta		future for a second sec		Dom	J			
Concept of instan modulated waves modulation, Verif Generation of FM Practical frequenc FM Capture Effe multiplexing (FDM	– Nar ication I wave y demo ct,. Ca M), and	us frequency, Generalized concept of a row band frequency modulation (NBFM) of Frequency modulation bandwidth rela s – Indirect method, Direct generation; D odulators, Small error analysis, Pre-empha- arrier Acquisition- phased locked loop (H I Super-heterodyne AM receiver, Illustrativ	ngle modulation ; and Wide ban tionship, Feature emodulation of sis, & De-empha PLL), Costas lo re Problems.	n, Ban ad FM es of a FM, B asis filt op, Fro	(WE ngle and ers, I	th of BFM), modu pass li FM rec ncy di	angle Phase lation, imiter, ceiver, ivision	
Module 3: Nois	se in (Communication Systems		8		20)	
Types of noise, Ti representation of r probability of erro systems with chan FM, PM in the pre	Types of noise, Time domain representation of narrowband noise, Filtered white noise, Quadrature representation of narrowband noise, Envelope of narrowband noise plus sine wave, Signal to noise ratio & probability of error, Noise equivalent bandwidth, Effective noise temperature, and Noise figure, Baseband systems with channel noise, Performance analysis (i.e. finding SNR expression) of AM, DSB-SC, SSB-SC, FM, PM in the presence of noise, Illustrative Problems.							
Module 4: Ana	log p	ulse modulation schemes		8		20)	
Pulse amplitude m & demodulation, demodulation sch Sensitivity, Selecti	Pulse amplitude modulation – Natural sampling, flat top sampling and Pulse amplitude modulation (PAM) & demodulation, Pulse-Time Modulation – Pulse Duration and Pulse Position modulations, and lemodulation schemes, PPM spectral analysis, Illustrative Problems. Radio Receiver measurements: Sensitivity, Selectivity, and fidelity							
wiouule 5: 1110	rmat	ion & Channel Capacity		0	1	20	,	

Introduction, Information content of message, Entropy, Entropy of symbols in long independent and

dependent sequences, Entropy and information rate of Mark off sources, Shannon's encoding algorithm, Discrete communication channels, Rate of information over a discrete channel, Capacity of discrete memory less channels, Discrete channels with memory, Shannon – Hartley theorem and its implications, Illustrative problems.

Reference B	ooks	
	1	B. P. Lathi, "Modern Digital and Analog Communication Systems," Oxford Univ.
		press, 3rd Edition, 2006
	2	Sham Shanmugam, "Digital and Analog Communication Systems", WileyIndia
		edition, 2006.
	3	A. Bruce Carlson, & Paul B. Crilly, "Communication Systems – An Introduction to
		Signals & Noise in Electrical Communication", McGraw-Hill International Edition,
	4	Sth Edition, 2010.
	4	Simon Haykin, Communication Systems, whey-india edition, 3 rd edition, 2010.
	5	Herbert Taub& Donald L Schilling, "Principles of Communication Systems", Tata
		McGraw-Hill, 3rd Edition, 2009.
	6	George Kennedy and Bernard Davis, "Electronics & Communication System", TMH,
		2004.
1. 4 CD	•	4
list of Exper	imer	its
	1	Amplitude modulation and demodulation
	2	Frequency modulation and demodulation.
	3	Characteristics of Mixer
	4	Pre-emphasis & de-emphasis.
	5	Pulse Amplitude Modulation and demodulation
	6	Pulse Width Modulation and demodulation
	7	Pulse Position Modulation and demodulation
	8	Radio Receiver measurements – Sensitivity, Selectivity, & Fidelity
	9	Sampling Theorem – verification
	10	Time division multiplexing.

Course title	:	Analog System Design	Sub code	e:	4LP23					
			Structur	e:	L	Τ	P	C		
					3	0	2	5		
 Course Objective: Design of OPAMPS, Classification of OPAMPs. To study and design various linear applications of OPAMPs. To study and design various nonlinear applications of OPAMPs 										
Course Outcome: Understand the basic building blocks of linear integrated circuits and i characteristics. Analyze the linear, non-linear and specialized applications of operational amplifiers. Understand the theory of ADC and DAC. Realize the importance of Operational Amplifier.										
Content		·		No. of l	iours	ES	E Ma	rks(%)		
Module 1:	Op-A	Amp Fundamentals and Application	ons	8			20	C		
their peculiari techniques, Instrumentatio converter, Co LM339, Bandy	ties a invert on am mpara width	and application areas. Review of Op-amp ing, non-inverting configurations. S plifier and applications, Integrator, Diffe itors, Limitations of Op-amp as Compar and slew rate limitations, Precision rectifie	parameters, I umming and rentiator and ator, Schmit ers, Peak dete	Frequency mplifier, l applica t trigger, ector.	y resp Dif tions. Com	onse, ferenc V to parato	offset e ar I and or IC	nulling nplifier, I to V such as		
Module 2: 0	OP- A	mp signal generators and Active I	Filter Desig	gn	8		20	C		
Sine wave gen converters, fur BPF, band reje	erator nction ect an	rs, Multi vibrators, Triangular wave genera generator IC 8038.All types of filter respo d bi quad filters, sensitivity analysis.	tors, Saw too onses, First of	oth gener der activ	ators, e filte	V to I rs LP	F and 1 and H	F to V IP,		
Module 3: N	Non-	inear Applications and Phase Loc	ked Loops		8		20	0		
Introduction to VCO Block characteristics FSK demodula	o Log diagr of P ator.	Antilog amplifiers and Analog multiplier am of PLL IC 565 free running freq LL, Applications of PLL - Frequency system	s, Block diag uency, lock nthesizer, FN	ram of P range, 1 demod	LL Pl captu ulator	nase I re rai , AM	Detecto nge, 7 demo	or, LPF, Fransfer odulator,		
Module 4: I	Desig	n of Analog Systems			8		20)		
Review of se Regulated and power amplifie Design of AM	lectio Swite er and /FM o	n parameters of Analog passive and acc ched mode. Design of Preamplifier circuits IC based P.A., Design of Tone Control C letectors.	tive compon using IC, D ircuits: Activ	ents; De esign of t e tone co	sign (ransis ontrol,	of Portorize Grap	wer S d clas hicEqu	upplies: s A/B/C ualizers,		
Module 5: I	Desig	n and Synthesis of Digital Systems	5		8		2	20		
Introduction to of IC based co criteria of tran Pressure, Hum	Introduction to Finite State Machines, State diagrams; Design of Mealy FSM; Design of Moore FSM, Design of IC based counter circuits using 7490.7492,74192,74190 etc, Multiplexers, De- multiplexer trees. Selection criteria of transducers, display devices; Design of Data Acquisition System for parameters like: Temperature, Pressure, Humidity, and Light.									
Reference H	Book	5								
	1	RamakantGaikwad, "Op-amps and Linea	r integrated c	rcuits",	PHI					
	2	D.RoyChoudhary, Shail Jain, Linear Integ	grated Circui	ts, New A	Age Ir	iternat	tional			

	3	Bowans, "Digital Instrumentation", TMH Publications
	4	Waller C. Bosshart, "PCB Design & Technology", TMH
	5	Bert Haskell, "Portable Electronics Product Design and Development", MGH Publication
	6	William Flecther, "An Engineering Approach to Digital Design", PHI
list of Expe	rime	nts
	1	Inverting amplifier and Non-inverting amplifier
	2	Summing amplifier / subtractor
	3	Integrator/ Differentiator
	4	Frequency response of active filter (LP/HP/BP)
	5	Voltage regulator ICs LM723
	6	Voltage to Frequency converter
	7	Waveform generator 8038 etc.
	8	PLL 565
	9	Analog to Digital converter
	10	Digital to Analog converter

Course title:	Signa	lls and Systems	Sub code:	"	4L2	24		
			Structure:]	L	Т	Р	С
				•	3	2	0	5
 To study about signals and systems. To do analysis of signals & systems (continuous domain & frequency domain methods. To understand the stability of systems through the To know various transform techniques in the analysis 						ete) 1 ROC. s and	using syste	time ms.
Course Outco	 For integral-differential equations, the students will have the knowledge make use of Laplace transforms. For continuous time signals the students will make use of Fourier transfor and Fourier series. For discrete time signals the students will make use of Z transforms. The concept of convolution is useful for analysis in the areas of linear system and communication theory. 						ge to form tems	
Content No. of here				ours	ES	E M	arks('	%)
Module 1: Sig	nals ar	nd systems	8				20	
Continuous Time Functions, Contin SYSTEMS : Disc LTI Systems Desc	and Dis nuous an rete Tin cribed b	screte Time signals, Exponential and Sinus and Discrete Time Systems, basic System Pro- ne LTI Systems, Continuous Time LTI Sys by Difference equations	oidal Signals, U operties. LINE A tems, properties	nit Im AR TI of LT	puls ME I Sy	e and INV /stem	l Unit A RI A Is, cau	Step ANT sal
Module 2: For	irier s	eries representation of periodic sig	nals	8			20	
Response of LTI properties of CT Fourier series and	system Fourier l LTI Sy	s to Complex Exponentials, Fourier series Series, Fourier Series representation of stems, Filtering, Examples of CT filters, E	s Representatior DT periodic Sig xamples of DT	n of C gnals, filters	T p proj	eriod pertie	ic Sig es of I	nals, DFS,
Module 3: Con	ntinuo	us time Fourier transform		8		20		
Representation of multiplication pro Equations. Magn domain and Frequ	Representation of a periodic Signals by continuous FT, FT of periodic signals, convolution and multiplication property of continuous FT, systems characterized by Linear Constant Coefficient Differential Equations. Magnitude and phase representation of FT, Magnitude and phase response of LTI systems, Time domain and Frequency domain aspects of ideal and non-ideal filters.							
Module 4: Lap	place T	Fransform		8			20	
Definition-ROC-Properties-Inverse Laplace transforms-the S-plane and BIBO stability-Transfer functions- System Response to standard signals-Solution of differential equations with initial conditions.								
Module 5: Dis Fourier Trans	Module 5: Discrete Time Fourier Transform (DTFT) And Discrete820Fourier Transform (DFT):20							
SAMPLING: San from its samples property, multipli Equations.	SAMPLING: Sampling theorem, Impulse sampling, sampling with zero order Hold, Reconstruction of signal from its samples using interpolation, Effect of under sampling. Properties of DTFT and DFT, convolution property, multiplication property, Duality, Systems characterized by Linear Constant Coefficient Difference Equations.							
Module 6: Z-T	Module 6: Z-Transform ⁸						20	

Z-transform, Region of convergence and its properties, Inverse Z transform, properties of ZT, Analysis and characterization of LTI systems using ZT, LTI Systems, System function algebra and block diagram representations.

Reference Books

1	Alan V. Oppenheim, Alan S. Willsky, S. Hamid Nawab, Signals and Systems Prentice Hall India, 2nd Edition, 2009.
2	John G. Proakis, Dimitris G. Manolakis, Digital Signal Processing, Principles, Algorithms, and Applications, 4th Edition, PHI, 2007.
3	B.P. Lathi, —Signals, Systems & Communicationsl, 2009, BS Publications.
4	Simon Hykin, "Signals and Systems", John Wiley
5	Robert A. Gable, Richard A. Roberts, Signals & Linear Systems, 3rd Edition, John Wiley, 1995.
6	Harish Parthasarathy,"Signals and Systems" JK International Second Edition.
7	HWEI P.HSU Schaum's, "Signals and Systems" TMH
8	M.J.Roberts,"Signals and Systems" TMH Ed 2003

Course title:	Digi	tal Communication	Sub code	ub code: 5LP25					
			Structur	e:	L	Т	Р	C	
					3	0	2	5	
Course Object	ive:	 To understand the key modules of digital communication systems with emphasis on digital modulation techniques The design of the systems which involves randomness using mathematical analysis and computer simulations. Learn about theoretical bounds on the rates of digital communication system and represent a digital signal using several modulation methods Draw signal space diagrams compute spectra of modulated signals and apply redundancy for reliable communication. 							
		 To demonstrate the concepts involved in digital communication. To explain the concepts of digital modulation schemes. To analyze the performance of digital communication systems. 							
Content			No. of h	ours	ESE Marks (%)				
Module 1: Ran	ndom	Variables and Random Process		12		2	20		
Deterministic and Random Signal: Types of random variables, cumulative distribution function and probability density functions, Standard distributions: Gaussian, exponential, Rayleigh, uniform, Bernoulli, binominal, Poisson, discrete uniform and conditional distributions. Functions of one random variable: distribution, mean, variance, moments and characteristics functions. Random Processes: Random processes, stationary processes, mean and covariance functions, periodicity, linear filtering of random processes, power spectral density, examples of random processes: white noise process and white noise sequence, Gaussian process, Poisson process, Markov process.									
Module 2:Digit	tal co	mmunication and modulation basics		8			20		

Band pass and Low pass signal, Introduction to Digital communication systems, Pulse code modulation, differential pulse code modulation, delta modulation, adaptive delta modulation, PSD of Line Coding schemes, Pulse shaping, Scrambling, Eye diagram, Gram-Schmidt orthogonalization scheme.

8	20					
DPSK, QPS	K and					
8	20					
for Channe	el with ISI and					
roduction o	f Multichannel					
8	20					
Optimum threshold detection, Concept of Matched Filters, BER analysis of BASK, BFSK, BPSK, Model						
of Spread Spectrum Digital Communication. Direct Sequence Spread Spectrum Signal (DS-SS), Frequency						
	8 DPSK, QPS 8 for Channer roduction o 8 SK, BFSK, Signal (DS-S					

Hopped Spread Spectrum Signal (FH-SS).

Reference E	Books	8
	1	John G. Proakis & Masoud Salehi, "Digital Communications", 5th Edition, McGraw Hill
	2	B.P. Lathi, "Modern Digital and Analog Communication Systems", 4th Edition,
		Oxford University Press
	3	H. Taub, D L Schilling, Gautam Saha, "Principles of Communication", 4th Edition, McGraw Hill
	4	Singh & Sapre, Analog & Digital Communication Systems, 3th Edition, McGraw Hill
	5	John G. Proakis,"Communication Systems Engineering 2nd Edition, Pearson Education, 2015
	6	(Schaum's Outline Series) H P HSU & D Mitra, "Analog and Digital Communications", McGraw Hill 3rd Edition
	7	Bernard Sklar, Digital Communications, Pearson Education
	8	Simon Haykin, "Communication Systems", 5th Edition, Wiley India
list of Exper	rime	nts
	1	Design and Generation of random binary signals
	2	Study of impairments of signals generated in experiment 1 on passing through a simulated channel by observing Eye Pattern.
	3	Generation Unipolar NRZ, Polar NRZ, Unipolar RZ and Polar RZ line codes.
	4	Generation Manchester and AMI line codes
	5	Conversion of analogue signal into PCM format and its study
	6	Design and implementation of Delta Modulator for analogue signals
	7	Design, implementation and study of BASK Modulator and demodulator
	8	. Design, implementation and study of BPSK Modulator and demodulator
	9	Design, implementation and study of BFSK Modulator and demodulator
	10	Design, implementation and study of multiplexer and de-multiplexer of digital signals using TDM.
	11	study of spread spectrum signal

Course title:	Con	trol System Engineering	Sub code:	5L2	26			
			Structure:	L	Τ	Р	С	
				3	2	0	5	
Course Objecti	ive:	 To introduce different types of system and identify a set of algebraic equations to represent and model a complicated system into a more simplified form to interpret different physical and mechanical systems in terms of electrical system to construct equivalent electrical models for analysis. To employ time domain analysis to predict and diagnose transient performance parameters of the system for standard input functions and identify the needs of different types of controllers and compensator to ascertain the required dynamic response from the system. Formulate different types of analysis in frequency domain to explain the nature of stability of the system. 						
Course Outcon	ne:	 Develop the mathematical model of mechanical and electrical systems. Develop transfer function for a given control system using block diagram reduction techniques and signal flow graph method. Determine the time domain specifications for first and second order systems. Determine the stability of a system in the time domain using Routh-Hurwitz criterion and Root-locus technique. Determine the stability of a system in the frequency domain using Nyquist and bode plots. Develop a control system model in continuous and discrete time using state variable techniques. 						
Content			No. of hou	rs I	ESE M	lark	s(%)	
Module 1: Intr	oduc	tion to Control Systems	7			20		
Types of Control Mechanical Syster Transfer functions,	Syste ms, E , Blocl	ems, Effect of Feedback Systems, Diffe lectrical Systems, Analogous Systems. E k diagram algebra and Signal Flow graphs	rential equation of Block diagrams and	Phys I sign	sical S al flov	yste w gr	ems – caphs:	
Module 2: Tim	e Res	sponse of feedback control systems	s 8		4	20		
Standard test signals, Unit step response of First and Second order Systems. Time response specifications, Time response specifications of second order systems, steady state errors and error constants. Introduction to PI, PD and PID Controllers (excluding design).								
Module 3: Stability analysis					4	20		
Concepts of stability, Necessary conditions for Stability, Routh stability criterion, Relative stability analysis: more on the Routh stability criterion, Introduction to Root-Locus Techniques, The root locus concepts, Construction of root loci.								
Module 4: Free	queno	cy domain analysis and stability	9		4	20		
Correlation between time and frequency response, Bode Plots, Experimental determination of transfer function. Introduction to Polar Plots, (Inverse Polar Plots excluded) Mathematical preliminaries, Nyquist Stability criterion, (Systems with transportation lag excluded) Introduction to lead, lag and lead-lag compensating networks (excluding design).								

Module 5: Introduction to Digital Control System	8	20

Introduction, Spectrum Analysis of Sampling process, Signal reconstruction, Difference equations. Introduction to State variable analysis: Introduction, Concept of State, State variables & State model, State model for Linear Continuous & Discrete time systems, Diaganolisation.

Reference Books

1	Automatic Control Systems (With Matlab Programs), HASAN SAEED, S. K.
	Kataria& Sons
2	Control systems, K.R. Varmah, McGraw hill
3	Control System Engineering, D. Roy Chowdhuri, PHI
4	Digital Control system, B.C. Kuo, Oxford University Press.
5	Control System Engineering, I. J. Nagrath& M. Gopal. New AgeInternational
	Publication
6	Modern Control Engineering, K. Ogata, 4th Edition, Pearson Education

Course Title:	Digita	ll Signal Processing	Sub co	de:	5LP27			
				ure:	L	Т	Р	С
			1		3	0	2	5
Course Objective	 Course Objective: To study about discrete time systems and to learn about FFT algorithms. To study the design techniques for FIR and IIR digital filters. To study about Realization of Digital systems. 						ns.	
Course Outcome	:	 Able to do analysis and characterization of the discrete time systems. Use Fourier analysis concept for frequency domain representation and analysis. Realize the implementation of discrete time systems. Design the different aspects of IIR and FIR filters. Calculate the spectral density parameters for measuring the performance. 						tion and nce.
Content				No. of ho	ours	ESE	Marl	ks(%)
Module 1: Introc	luction	to discrete time signals and sy	ystems	8			20)
Discrete Fourier Tra computation of the I Goertzel algorithm, (ansform, DFT, Div Chirp-z (Linear filtering methods based on vide and Conquer approach, Radix -2 transform, quantization effect in comp	the DFT, 2, radix-3 putation o	Filtering and radix f the DFT	of loi -4 Fas	ng sec st Fou	juence rier Ti	es. Direct ransform,
Module 2: Imple	menta	tion of the Discrete time system	ns	8			20)
Structure for the reasonable sampling structure, filter.	alization lattice s	of discrete time FIR and IIR syst tructure. State space system analysis	ems, Dire s and stru	ect Form, actures. R	casca ound-	de fo off ef	rm, F fects	requency in digital
Module 3	De	esign of FIR Digital Filters		8			20)
Magnitude and pha Techniques for FIR FIR Filters, Design c	se respo (Low pa of Minim	onse of digital filter, frequency res ass, high pass, band pass and band re num phase FIR Filters.	sponse of eject) filte	E Linear jers. Desig	phase n of C	FIR Optima	filters al Line	, Design ear phase
Module 4	De	esign of IIR Digital Filters		8			20)
IIR filter design by approximation of derivatives, impulse invariant approach and bilinear transformation. Butterworth filters, Chebyshev filters, Inverse Chebychev filter and elliptic filters, Design of Low pass, high pass, band pass and band reject IIR filters. Spectral transformation of IIR filters, Effects of Finite word length in digital filters.								
Module 5	Sp	ectral Estimation methods		8			20)
Spectral estimation, spectral estimation, I	Energy Paramete	Density Spectrum, Estimation of a eric and nonparametric method for po	utocorrel wer spect	ation and rum estim	powe ation.	er spe	ctrum	, DFT in
Text/Reference I	Text/Reference Books :							
	1	1 Discrete Time Signal Processing, Oppenheim & Schafer, PHI Ltd, Third Edition				Edition		
	2	Digital Signal Processing: Principles Algorithms and Applications, Proakis John and Manolakis.					akis John	
	3	Digital Signal Processing- A computer based approach, Sanjit K. Mitra, McG Hill Education.					McGraw	

List of Experiments		
	1	Compute linear convolution, circular convolution and cross correlation of two sequences.
_	2	Verify different properties of Discrete Fourier Transform.
_	3	Implement different FFT algorithms.
-	4	Design and implementation of low pass, high pass, band pass and band reject FIR filters.
-	5	Design and implementation of low pass, high pass, band pass and band reject IIR filters of different types.
	6	Computation of power spectral density, correlation function and correlation matrix of stochastic systems.
-	7	Implementation of basic digital signal processes algorithms for different applications like demising, edge detection etc. using computer programming.
	8	Implementation of basic digital signal processes algorithms for different applications like denoising, edge detection etc. using digital signal processors like TMS DSP kits.

Course Title:	Embedded system and IOT	Sub code:	5LP	28		
		Structure:	L	Т	Р	С
			3	0	2	5
 Students will understand the discipline of Embedded system and Io' its application to the development of real time embedded system Students will learn basic Embedded Microcontroller & practices and appropriate applications. Students will understand the principles of analysis and design fo development. Students will think about IoT applications to construct embedded system of high quality which is reliable and easy to understand, modify maintain. 						T and d their or IoT system by and
Course Outcome	• Define basic concepts of embe	edded system				
	 Describe ARM contex-in mich Illustrate the design of M2M 1 Test developed IoT protocols Test embedded application us 	IoT application. for requirements val ing Linux Operating	idatior g syster	n. m		
Content		No. of h	ours	ESE	Marl	ss(%)
Module 1: Introd	luction to Processor Architecture	8			20	
Architecture of hit processors –pipelini prediction –register Cortex-M – NVIC – Module : Robotic	Architecture of Intel processors from 80286 to Pentium-Microarchitectural techniques of advanced processors –pipelining-superscalar concept –Out of order execution –Speculative execution – branch prediction –register renaming -Multicore processors- Processors beyond Pentium- Architecture of ARM Cortex-M – NVIC – WICSleep modes – peripheral programming of a Cortex-M processor.Module : Robotics Design and Application820					
					- 20	55III <u>5</u> .
Module 3: Mach	ine To Machine Communication	8			20	
M2M to IoT – A Market Perspective – Introduction, Some Definitions, M2M Value Chains, IoT Value Chains, An emerging industrial structure for IoT. M2M to IoT- An Architectural Overview – Building architecture, Main design principles and needed. An IoT architecture outline, standards considerations. Review of internet protocols –Processing platforms for IoT-sensors – actuators-Cloud computing models.						
Low power, low ra agriculture etc, - IoT	Low power, low range protocols –Zigbee –BLE – 6LoWPAN. Applications for IoT-Smart home, city, agriculture etc, - IoT services Project work on Design and development of an IoT product.					
Module 5: Linux	8			20		
Linux and linux dev board.	ice drivers –Linux Internals-Project work o	on porting a real tim	e OS (onto a	n emb	edded

Text/Refe	erenc	ee Books :						
	1	Lyla B. Das, The x86 Microprocessors: 8086 to Pentium, Multicores, Atom, and the 8051 Microcontroller : Architecture ,Programming and Interfacing, Second Edition, Pearson Education, India 2014						
	2	Lyla B. Das, Architecture, Programming, and Interfacing of Low-power Processors – ARM7, Cortex-M, Cengage, 2017						
	3	Jan Holler, VlasiosTsiatsis, Catherine Mulligan, Stefan Avesand, Stamatis Karnouskos David Boyle, From Machine-to-Machine to the Internet of Things: Introduction to a Nev Age of Intelligence, 1 st Edition, Academic Press, 2014.						
	4	ArshdeepBagha, Vijay Madisetti, Internet of Things, A hands on approach, 2015						
	5	Daniel P. Bovet, Marco Cesati, Understanding the Linux Kernel, 3rd Edition, O'Reilly,2005						
List of Ex	kperi	ments for						
	1	Display Hello WORD message using UART						
	2	Using mobile hotspot network communicate server and Client						
	3	Display Temperature Sensor reading on Putty using UART						
	4	Interface Receiver and transmitter to send data						
	5	Interface LMT86 with ADC to get readings on the UART						
	6	Blink LED using suitable pattern						
	7	Display light intensity on the UART						

Course Title:	Printed Circuit Board Technology-1	Sub co	de:	5LP	29		
		Structu	ire:	L	Τ	Р	C
				3	1	2	6
 Course Objective: To study about PCB Fundamentals, types and its classification. To study the design rules for Analog, digital and mixed circuits. To study about Transient, AC Sweep, DC Sweep and simulation for various electronic circuits. To study about PCB design and manufacturing process flow sides boards) & DSB(Double sided Boards). 						al elec ration SSB (ctronic point (Single
Course Outco	 Able to do analysis of various electronic circuits. Design the Schematics and PCB layout for SSB(Single sides boards) & DSB(Double sided boards). Perform Artwork generation using Film master equipment. Generate various PCB Manufacturing files and drill files required for PCB fabrication. 						
Content			No. of ho	ours	ESE	2 Mar	ks(%)

Module 1: Introduction and overview of printed circuit board design6	6	15
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History & Definition of printed circuit board design, Classification of PCBS- SSB, DSB (PTH & Non PTH), Multilayer PCB, Application of various PCBs, Introduction to Semiconductor Packing Technology, Role of scale & Grid in PCB design, PCB mounting methods and PCB standards, Layout Considerations-Land Requirement, Layout Methodology, Design Elements & Performance Parameters, Manufacturing Documentation like role of Block Diagram, Schematic drawing, Net-list generation Assembly Drawing, Mechanical Drawing.

Module 2: Lavout Planning, Artwork generation using Film master	

30

12

Electrical Design Considerations-Resistance in general, Capacitance in general, Inductance of Conductor and Conductor Pattern, Component placement approach with respect to conductor width, conductor shapes, Thermal Consideration, Mounting consideration, requirement of heat sink, Layout check with respect to mechanical and electrical consideration, Layout Methodology, Layout Design Checklist and inspection, Useful standards, Artwork approach and design guidelines for SSB & DSB design, Artwork Preparation Methods-Taping UP: Laying down the tapes and drafting material using appropriate methods, Design Guidelines for Artwork Preparation - Conductor Orientation, Conductor, Routing, Spacing, Importance of hole diameter and solder Pad diameter, Advance methods of Artwork generation, Artwork Inspection and checks, Introduction parameters of Photographic film like film emulsions, dimensional stability of film master, types of films, Types of Reprographic Cameras, Dark Room setup and procedure of film processing, Film Registration, Faults related to film processing and remedies.

Module 3: Design rules For PCBs & Automation in PCB Design

30

12

Design rule for High frequency amplifiers & oscillators, Design rule for Multistage amplifiers with high power o/p stage, Design rule for feed-back amplifier, Design rule for differential amplifier,

Supply and ground line conductors' considerations, Design rules for TTL,CMOS & ECL circuits, Reflection and Crosstalk, Ground to supply noise, E.M. Interference, Problems in design & recommendations, Dividing

Circuit into High and Low Power Parts, Copper Clad Laminates, PCB Terminal Connections & their Assembly, Conductor Width & Thermal Consideration, Limitation of Manual Designing, Introduction to various EDA tools, CAD operation, Schematic Capture & Layout, Automation in component Placements, Routing Assignments and routing Procedures, Post process and Gerber data generation, Design rules check, Generation of film master using photoplotter, data transfer mechanisms.

Module 4: Design with Multi- layer Boards and Flexible PCBs.

6

15

Techniques - **PTH**, Buried and **blind** via, Materials **for Multi** - Layer boards, Mechanical & Electrical Design consideration for **Multi**-Layer Boards, Fabrication Process for Multi-Layer Boards, Useful Standards for Multi-layer PCBs, Construction of Flexible PCBs - Types of films, Foils & Adhesives, Design considerations for Flexible Circuits, Manufacturing of Flexible Circuits, Rigid Flex Printed Circuits Boards, Advantages of Flexible Circuits, Special Applications of Flexible Circuits, Stencil Printing of SMD, Industrial SMT Assembly Process, SMD Soldering - Manual and Reflow Soldering Techniques, Repair and Rework of SMDs, Advantages and Limitations **of** SMT.

Module 5: PCB Technology Trends, Quality, Environmental Concerns in PCB Industry

4 10

Fine Line Conductor with Ultra - Thin Copper Foil, Multi Wire Board, Metal Core PCBs, Additive and Semi additive Process, Mechanical Milling of PCBs, Quality Assurance in PCB, Testing for Quality Control Methods, Testing for Printed Circuits Boards, Reliability Testing, Acceptability of PCBs, Pollution Control in PCB Industry, Polluting Agents, Recycling of water, Recovery Techniques, Air pollution, Recycling of PCBs fabrication, Lead - free Soldering.

Text/Reference Books :

1	Printed Circuit Boards: Design and Technology, Walter C Bosshart ,Tata McGraw- hill publication
2	Printed Circuit Boards: Design, Fabrication, Assembly & Testing, R S Khandpur, Tata McGraw-hill publication
3	Printed Circuit Boards, Coombs Clyde F., Tata McGraw-hill publication
4	The Design & Drafting of Analog Printed Circuit boards, Darryl Lindsey, Bishop Graphics Inc
5	Printed Circuit Boards: Design Techniques For EMC Compliance, Montrose Mark I, IEEE Press Series of Electronics Technology

List of Experiments

1	Design the current mirror circuit in schematic editor using Autodesk Eagle software and Run the operating point analysis simulation.
2	Design the basic diode circuit in schematic editor using Autodesk Eagle software and Run the Transient Analysis simulation.
3	Design the basic MOSFET circuit in schematic editor using Autodesk Eagle software

	and Run the DC Sweep Analysis simulation.					
4	Design the BJT Oscillator circuit in schematic editor using Autodesk Eagle software and Run the Transient Analysis simulation.					
5	Create the library component resistor with the following dimensions and specifications using Autodesk Eagle software.					
6	Create the library component for 555 timer IC with the given dimensions and specifications using Autodesk EAGLE Software.					
7	Create the library component for G5LE OMRON RELAY with the given dimensions and specifications using Autodesk EAGLE Software.					
8	Create the library component for NCP716B LDO with the given dimensions and specifications Autodesk EAGLE Software.					
9	Design the USB TO TTL/CMOS Programmer circuit using FTDI232 IC into schematic editor and draw the PCB layout for the same in Autodesk EAGLE software, run the Electrical Rule Check(ERC) in schematic editor.					
10	Design the Astable Multivibrator circuit using 555 timer ic into schematic editor and draw the PCB layout for the same in Autodesk EAGLE software, generate BOM, netlist and run design rule check.					
11	Design the DC TO DC 5V Voltage regulator circuit using LM317 IC into schematic editor and draw the PCB layout for the same in Autodesk EAGLE software, generate gerber files for top electrical and bottom electrical.					
12	To learn the process of generating files(HPGL, ISEL, Excellon) for CNC drilling and milling machine.					
13	To learn the process of generating 3D files format and observe the DXF view.					
14	Study the various format settings done in photoplotter machine. Learn about artwork generation software, the concept of importing PCB Gerber file and converting files to photoplotter format.					
15	To learn the process of generating legends(silkscreen) for Top electrical/ bottom electrical (SSB) Or both (DSB).					

Course Title:	Info	rmation Theory and Coding	eory and Coding Sub code: 5L.			5L30			
			Structu	ire:	L	Т	Р	C	
					3	1	0	4	
Course Object	ive: ne:	 To familiarize the students with the Information Theory. To study and understanding of the concept of coding technique and its applications. To understand the aspects of channel capacity. To study the various techniques of coding and decoding in information theory. To understand the various multiple access techniques. Learn the concept of information and entropy Describe the Shannon's theorem for coding Describe the channel capacity Apply various kinds of coding methodology. Describe the real time application of coding techniques. 							
Content				No. of he	ours	ES	E Mar	ks(%)	
Module 1: Intr	oduct	tion to Information Theory			8			20	
Entropy, discrete encoding, ARQ sy	memor vstem	ry less source, Shanon's noiseless codi	ng theore	m, shenoi	n's fa	ano c	ode, ru	n length	
Module 2: Nois	sy Co	ding System				8		20	
Encoding of discr channels.	ete sou	urces. Markov sources, Shannon's nois	y coding	theorem	and o	conve	rse for	discrete	
Module 3: Cha	nnel	Capacity				8		20	
Channel model, c channel capacity code, channel capa	channe and bo acity fo	l coding theorem, information capacit ounds for discrete channels, Technique or MIMO system.	y theorem es of codi	n &its in ng & deo	nplic codir	ation g, ra	Calcul ndom s	ation of selection	
Module 4: Cyc	lic co	des & Information Theory Appl	ication			8		20	
Cyclic codes, data theory.	comp	ression, cryptography, overview of encr	yption tec	hnique. A	pplic	cation	of info	ormation	
Module 5: Con	volut	ional codes & Communication li	ink			8		20	
Convolutional arithmetic codes. Introduction to multiuser communication, Multiple access technique. Introduction to satellite communication system. Binary signalling , TDMA & CDMA wireless communication system. Text/Reference Books :									
	1	R.B. Ash. Information Theory Prentice H	all, 1970						
	2. Shu Lin and D.J. Costello Jr., Error Control Coding, Prentice Hall, 1983								
	3	Ranjan Bose - Information Theory Coding	g and Cryp	tography, '	ГМН	-			
	4	N. Abramson, Information and Coding, M	IcGraw Hil	1, 1963					
	5	M. Mansurpur, Introduction to Informatio	n Theory, 2	McGraw H	Hill, 1	987.			
	6	Taub and Schilling - Principle of Commun	nication Sy	stems, (TN	MH) 2	2nd ed	ition		

Course title:	Sub co	ode:	6L31					
			Struct	ure:	L	T	P	C
			1		3	0	0	3
 Course Objective: To understand the basic terminology and concepts of Antennas. To attain knowledge on the basic parameters those are considered in antenna design process and the analysis while designing that. Analyse the electric and magnetic field emission from various basic ant and mathematical formulation of the analysis. To have knowledge on antenna operation and types as well their usage in time field. Aware of the wave spectrum and respective band-based antenna usage and to know the propagation of the waves at different frequencies through different space environment structure. 						in the ntennas in real nd also ifferent		
Course Outco	me:	 Analyse radiation patterns of antenna Evaluate antennas for given specific Illustrate techniques for antenna pat Design antennas for specific application 	as cations rameter n ations	neasureme	nts			
Content			No. of	hours	ESE	Mar	ks (%	6)
Module1: Ant	tenna Ba	asics And thin linear wireanter	nna	10		2	20	
Electric Dipole, (Radiated Power, Natural current d Illustrative Proble and Short Dipole, Module 2: VH Arrays with Paras	Quarter w Radiatio listribution ems. Loop , Radiation IF, UHF sitic Elem	vave Monopole and Halfwave Dipole on Resistance, Beamwidths, Directive ns, fields and patterns of Thin Linea on Resistances and Directivities of Smart AND Microwave Antennas – ments, Yagi - Uda Arrays, Folded Dip Modes, Practical Design Considerati	e – Currenvity, Effe vity, Effe r Centre- op, Comp all and La I: oles & th	nt Distribu ective Are fed Anten parison of arge Loops 8 eir charact	eristics	Field (Effec Differ Ids of tative 2 , Helio	Comp tive 1 rent L Smal Treat 20 cal Ar	onents, Height. engths, Il Loop ment).
and Normal Mod Pyramidal Horns,	- Helical geometry, Helix Modes, Practical Design Considerations for Monofilar Helical Antenna in Axial and Normal Modes. Horn Antennas - Types, Fermat's Principle, Optimum Horns, Design Considerations of Pyramidal Horns, Illustrative Problems.							
Module 3: VH	IF, UHF	AND Microwave Antennas –	II:	8		2	20	
Microstrip Antennas - Introduction, Features, Advantages and Limitations, Rectangular Patch Antennas - Geometry and Parameters, Characteristics of Microstrip Antennas. Impact of Different Parameters on Characteristics, Reflector Antennas - Introduction, Flar Sheet and Corner Reflectors, Paraboloidal Reflectors - Geometry, Pattern Characteristics, Feed Methods, Reflector Types - Related Features, Illustrative Problems.								
Module 4: Antenna Arrays and Antenna Measurements:					20			
Point Sources - Definition, Pattern, arrays of 2 Isotropic Sources - Different Cases, Principle of Pattern Multiplication, Uniform Linear Arrays - Broadside Arrays, End fire Arrays, EFA with Increased Directivity, Derivation of their Characteristics and Comparison, BSAs with Non- UNIT form Amplitude Distributions - General Considerations and Binomial Arrays, Illustrative Problems.Introduction, Concepts - Reciprocity, Near and Far Fields, Coordinate System, Sources of Errors. Patterns to be Measured, Pattern Measurement Arrangement, Directivity Measurement, Gain Measurements (by Comparison, Absolute and 3-Antenna Methods).								
Module 5: Wa		10		4	20			

Introduction, Definitions, Categorizations and General Classifications, Different Modes of Wave Propagation, Ray/Mode Concepts, Ground Wave Propagation (Quantitative Treatment) - Introduction, Plane Earth Reflections, Space and Surface Waves, Wave Tilt, Curved Earth Reflections, Space Wave Propagation - Introduction, Field Strength Variation with Distance and Height, Effect of Earth's Curvature, Absorption, Super retraction, M-Curves and Duct Propagation, Scattering Phenomena, Tropospheric Propagation Sky Wave Propagation - Introduction, Structure of Ionosphere, Refraction and Reflection of Sky Waves by Ionosphere, Ray Path, Critical Frequency, MUF, LUF, OF, Virtual Height and Skip Distance, Relation between MUF and skip Distance, Multi-hop Propagation

Text/Refere	ence Books:
	1. Antennas for All Applications – John D. Kraus and R. J. Marhefka, and Ahmad S. Khan TMH, New Delhi, 4th ed., (Special Indian Edition) 2010.
	2. Electromagnetic Waves and Radiating Systems – E.C. Jordan and K.G. Balmain, PHI, 2nd ed 2000
	3. Antenna Theory - C.A. Balanis, John Wiley & Sons, 3rd ed., 2005
	4. Antennas and Wave Propagation – K.D. Prasad, SatyaPrakashan, Tech India Publications, New Delhi, 2001.
	5. Transmission and Propagation – E.V.D. Glazier and H.R.L. Lamont, The Services Text
	Book of Radio, vol. 5, Standard Publishers Distributors, Delhi.
	Antennas – John D. Kraus, McGraw-Hill (International Edition), 2nd Ed.
List of Exp	eriments:
	1. To study various antennas, its application and tentative radiation pattern. (study experiment)
	2. To study and observe the radiation patter of strait dipole antenna.
	3. To study and compare the radiation patter of folded dipole with straight dipole antenna and comment on the radiation resistance and it's matching with free space.
	4. To study and compare the radiation pattern of 3-element and 5-element Yagi and give
	your comment on effect of addition of parasitic elements to the given antenna.
	5. To study the variation of radiated field with distance from transmitting antenna
	6. To study and plot the radiation pattern of the Log-Periodic antenna and observe its
	frequency independency
	7. To study and observe the radiation pattern of the horn antenna
	8. Introduction to HFSS (High Frequency Simulation Software)
	9. Micro Strip antenna design and simulation using HFSS.
	10. Study of Antenna Measurement setup in Anechoic chamber.

Course Title:	Pri	nted Circuit Board Technology-2	Sub code:	6	6LP32		
			Structure:	L	Т	P	C
				3	1	2	6
 Course Objective: To study about PCB materials, copper clads and other manufacturing process. To study the PCB fabrication process flow for SSB (Sing (Double sided boards). To study about through hole and SMT PCB soldering and 					dame ded be	ntals coards)	f PCB &DSB
Course Outcom	 Able to do fabrication for SSB & DSB plated through hole PCBs. Perform CNC Drilling and Milling operation along with UV exposure Developing, Etching and Stripping operation for SSBs & DSBs. Perform Through hole plating operation of PCBs for DSBs. Perform PCB assembly process for Through hole and SMT PCBs 					posure,	
Content			No. of hou	irs E	SE N	Iarks	(%)
Module 1: Pro Preparation:	opert	ies of Copper Clad Laminates a	and Surface	8		,	20
Manufacturing Pro Laminates and tes Preparation, Manua Module 2: Mec Need for Mechanic Punching Drilling	Manufacturing Process of copper Clad, Physical and Electrical properties of Laminates, Evaluation Laminates and test methods like peel strength, flexural strength, Surface Preparation: Need ofSurfa Preparation, Manual Cleaning Process, Mechanical Cleaning Process, Trends in cleaning processes. Module 2: Mechanical Operation: 8 20 Need for Mechanical Operations, Cutting Methods - Shearing, Sawing, Blanking, Milling & Routing, Hethods 8 20						ion of Surface 20 g, Hole
Use of UV laser for	- Clas r Drill	ing PCB, Hybrid Laser drilling Process, Us	seful Standards.	nng pro	oolein	s, Mici	o vias,
Module 3: Plati	ing a	nd Etching Process:		8	3		20
Need for Plating, Types of plating. Platting Techniques-Immersion plating for Tin and Gold, Electroless Copper plating & Electroplating in detail, Special Platting Techniques, Alternative Finishes, Plating Defects & Plating Quality Control, Consideration for shop floor, Useful standards, Etching Solution and Chemistry, Equipment for etching, Facilities for Etching Area, Problems in Etching, Electrochemical Etching, Mechanical Etching							
Module 4: Screen Printing and Photo printing in PCB Fabrication:							20
Introduction, Mater curing methods, D Printing process, coating/lamination Features & categor	rial reo irect a Photo metho ies. Pr	quired for screen printing -screen Frames, S and Indirect Methods of Pattern transfer, M o resist in general, Characteristic of j ods, Manufacturing process of SSB and DS rocessing of Dry - Film Resist, Trouble sho	Screen fabrics Sq Ianual Screen pr photo resist, T B using wet film oting.	jueegee rinting, ypes o proces	s, Prin Autor f Pho s, Dry	nting In natic S otoresi	iks and Screen- st and Resist -
Module 5: Com	npone	ent Assembly and Soldering Techni	ques:		8		20
Classification of component assembly Techniques, Formation and mounting Techniques, PCB Repair and rework, Introduction & Theory of Soldering, Types of solder alloys and fluxes, Solder Paste for SMDS, Tools. Soldering Techniques - Manual soldering, Mass soldering, Role of solder mask, Solder mask application methods, Quality Control of solder Joints, Solder Joint Defect & cause.							

Text/Reference Books:					
1. 2. 3. 4. 5.	 Printed Circuit Boards: Design and Technology, Walter C Boss hart, Tata McGraw-Hill publication. Printed Circuit Boards: Design, Fabrication, Assembly & Testing, R S Khandpur, Tata McGraw-Hill publication. Printed Circuit Boards, Coombs Clyde F., Tata McGraw-Hill publication. The Design & Drafting of Analog Printed Circuit boards, Darryl Lindsey, Bishop Graphics Inc. Printed Circuit Boards: Design Techniques for EMC Compliance, Montrose Mark I, IEEE Press series of Electronics Technology. 				
List of Experiment	5:				
1. 2. 3. 4. 5. 6. 7. 8. 9. 10 11 12 13 14 15 16 17 18	 Draw the basic electronic component footprints on given Grid sheet in 2x dimensions and study the datasheets for all given components. Study the datasheets of Through hole Resistor and LED. Draw the Basic LED circuit on the Given Grid sheet along with component footprints and route manually. Study the datasheet of LM317M Voltage regulator IC. Draw 5V Voltage regulator circuit on the given grid sheet along with component footprints and route manually. Study the datasheet of 555 TIMER IC. Draw the AstableMultivibrator circuit using 555 Timer IC on the given grid sheet along with component footprints and route manually. Learn about PCB cleaning Process, study the operation and working of PCB brushing machine and perform brushing operation on FR-4 copper clad. Learn about CNC milling and perform drilling operation on FR-4 copper clad for SSB and DSB. To learn the process of galvanic plated through hole machine, and study the operation and working of through hole plating machine and perform operations on double sided PCBs. To develop the artwork on photo films using photo plotter machine, installation of films on machine and developing of the photo films using developer bath and fixer bath. To learn about PCB lamination Process, study the operation and working of PCB laminator machine, laminate Single sided board using PCB laminator machine on FR-4 copper clad. Learn about PCB Ultraviolet exposing process, study the operation and working of Ultraviolet exposing machine and perform Artwork film Exposure operation on FR-4 single Sided Board. To learn About PCB developing Process, study the operation and working of PCB developing machine. To learn about PCB developing Process, study the operation and working of PCB laminator machine and perform Artwork film Exposure operation on FR-4 single Sided Board. To learn about PCB developing Process, study the operation and working of PCB developing machine.				

Course Title:	Computer Architecture And Organization	Sub code:6L		L 33		
		Structure	: L	Т	Р	C
			3	1	0	4
Course Object	 Course Objective: To understand the basic hardware and software issues of computer organization. To provide an overview on the design principles of digital computingsystems. To understand the representation of data at machine level. To understand how computations are performed at machine level Course Outcome: Ability to analyse the abstraction of various components of a computer. 					ns.
	 Ability to analyse the hardware and software issues and the interfacing. Ability to work out the trade-offs involved in designing a moderncomputer system. 					
Content		No. of	ESE M	ark	s (%	(0)
Modulo 1. Intr	voduction of Processor	hours 8		20		
Nodule 1: Introduction of Processor 8 20						
Introduction, Technologies for building Processors and Memory, Performance, The Power Wall, Operations of the Computer Hardware, Operands Signed and Unsigned numbers, Representing Instructions, Logical Operations, Instructions for Making Decisions						
Module 2: Instructions Set			20			
MIPS Addressing for 32-Bit Immediate and Addresses, Parallelism and Instructions: Synchronization, Translating and Starting a Program, Addition and Subtraction, Multiplication, Division, Floating Point, Parallelism and Computer Arithmetic: Sub word Parallelism, Streaming SIMD Extensions and Advanced Vector Extensions in x86.						
Module 3: Arc	hitecture Building Block	8		20		
Logic Design Conventions, building a Datapath, A Simple Implementation Scheme, overview of Pipelining, Pipelined Datapath, Data Hazards: Forwarding versus Stalling, Control Hazards, Exceptions, Parallelism via Instructions, The ARM Cortex – A8 and Intel Core i7 Pipelines, Instruction –Level Parallelism and Matrix Multiply Hardware Design language.						
Module 4: Mer	mory Mapping	8		20		
Memory Technologies, Basics of Caches, Measuring and Improving Cache Performance, dependable memory hierarchy, Virtual Machines, Virtual Memory, Using FSM to Control a Simple Cache, Parallelism and Memory Hierarchy: Redundant Arrays of Inexpensive Disks, Advanced Material: Implementing Cache Controllers.						
Module 5: Mer	mory Management	8		20		
Disk Storage and Dependability, RAID levels, performance of storage systems, Introduction to multi- threading clusters, message passing multiprocessors.						

Text/Reference Books:				
	1.	David A. Patterson and John L. Hennessey, "Computer organization and design, The		
		Hardware/Software interface", Morgan Kauffman / Elsevier, Fifth edition, 2014		
	2.	V. Carl Hamacher, Zvonko G. Varanesic, and Safat G. Zaky, "Computer Organization		
		", 6 th edition, McGraw-Hill Inc, 2012.		
	3.	William Stallings, "Computer Organization and Architecture", 8th Edition, Pearson		
		Education, 2010		

Course Title:	SENSORS AND TRANSDUCERS	Sub code:	Sub code:			
		Structure:	L	Т	Р	С
			3	0	2	5
Course Objectiv	 To study about operation and princip To study about thermocouples of application. To study about displacement poprinciple of working and its application. 	ple of working for operation, prince osition and pro- tion.	or sensor iple of ximity s	s and t worki	ransdu ng ai s oper	ucers. nd its ration,
Course Outcom	 Concept behind working of measurement systems and different types of sensors and transducers. Sensor to measure various physical parameters used in Industry and normal measurement applications. Working principle of resistive, inductive and capacitive transducers and their applications. Understanding of thermocouples, piezoelectric and pyro-electric transducers and their applications. Understanding of acoustic, optical sensors and other sensors and their applications. 					
Content	N	No. of hours	ESE N	Marks	s (%))
Module 1: I Transducer base	ntroduction to Sensor and ed Measurement system:	8		20)	
Introduction, Gene configuration, stati measurement data, sensor technologies.	ral concepts and terminology of meas c and dynamic characteristics of a mea standards and calibration, transducers and	surement system asurement system sensors, classifi	ns, Ger m, stati cation, e	neral i stical emergin	input- analy: ng fie	output sis of lds of
Module 2: Resis	tive, Reactancevariation &Electrom	agnetic Senso	rs:	8		20
Potentiometers, Stra Light-Dependent Ro Sensors, Signal Cor Measurements, Cap	in Gauges, Resistive Temperature Detector esistors (LDRs), Resistive Hygrometers, Re inditioning for Resistive Sensors: Resistance acitive Sensors, Inductive Sensors, Electroma	rs (RTDs), Therr esistive Gas Ser Measurement, V agnetic Sensors.	nistors, Isors, Li Voltage I	Magne quid C Divider	to res Condu	sistors, ctivity namic
Module 3: Flow,	Pressure & Level Transducers:			8		20
Flow Transducers Anemometer, Ultra meter, Coriolis Ef Membranes And T Sensors, Vacuum S	Like Differential Pressure, Variable Area, sonic Flow meter, Turbine Flow meter, V fect Flow meter, Pressure Transducers I hin Plates, Piezoresistive Sensors, Capaciti sensors, Level Transducers Like Displacer,	, Positive Displa Vortex Flow me Like Mercury F ive Sensors, VR , Float, Pressure	acement, ter, Elec Pressure P Senso Gages,	, Elect ctromaş Senso ors, Op Balan	romag gnetic r, Be toelec	gnetic, Flow llows, ctronic ethod,

Module 4: Thermocouples & Temperature Sensors:	8	20

Time-Of-Flight Measurements, Level Measurements By Detecting Physical Properties.

Thermoelectric Sensors: Thermocouples, Piezoelectric Sensors, Pyroelectric Sensors, Electrochemical

Sensors, Acoustic Temperature Sensors, Nuclear Thermometer, Magnetic Thermometer, Semiconductor Types, Thermal Radiation, Quartz Crystal, NQR, Spectroscopic Noise Thermometry, Heat Flux Sensors.

Module 5: Digital & Semiconductor Sensors & Sensors for Robotics:

8

20

Position Encoders, Resonant Sensors, SAW Sensors, Sensors Based On Semiconductor Junctions, Sensors Based On MOSFET Transistors, Charge-Coupled And CMOS Image Sensors, Fiber-Optic Sensors, Ultrasonic-Based Sensors, Biosensors, Proximity Sensors: Typical Sensor Characteristics, Technologies For Proximity Sensing, Electro-Optical Sensors, Capacitive Sensors, Magnetic Sensors.

Text/Reference Books :						
1	. Patranabis D., "Sensors And Transducers", Prentice-Hall India.					
2	. Ramon Pallas & John G. Webster, "Sensors and Signal Conditioning", John Wiley					
	& Sons					
3	. Webster John G., "Instrumentation and Sensors Handbook", CRC Press					
4	Jacob Fraden, "Handbook of Modern Sensors: Physics, Designs and					
	Applications", Springer					
5	. Shawhney A. K., "Electrical And Electronics Measurements And					
	Instrumentation", DhanpatRai& Sons					
List of Experiments:						
1	. To study the strain gauge characteristics.					
2	. To study the characteristics and weight measurement by load cell.					
3	. To study the construction of LVDT and its use in displacement and thickness					
	measurement.					
4	. To study the flow measurement by differential pressure type transducer.					
5	. To study the characteristics of LDR, thermostat and thermocouples.					
6	6. To study the testing and calibration of T, J, K, R and S thermocouples.					
7	7. To study the voltage – intensity characteristics of a phototransistor.					
8	. To study the ramp response characteristics of filled in system thermometer.					
9	• To study step response of RTD and thermocouple.					
	0. To study Hall Effect Transducer.					
	1. To study the characteristics of piezoelectric sensors.					
	2. Measurement of temperature, depth etc by optical fibre sensor.					
	3. To study the characteristics of Charge-Coupled and CMOS Image Sensors.					
Course Title:	ADVANCE IOT	Sub code:				
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		Structure:	L	T	P	C
			3	0	2	5
Course Objective: • To study IoT architecture • To study Network Layer Protocols • To study IoT Services and security protocol.						
	 Able to understand IoT Securit Able to understand IoT Service 	y Protocols. s layer protocol				
Content		No. of hours	ES	E Ma	arks (%)
Module 1: INT	RODUCTION	8	•		20)
IoT architecture ou area networking, D Analytics	tline, standards - IoT Technology Fundata management, Business processes in I	amentals- Devices and gat oT, Everything as a Servic	eways e(Xaas	, Loca S), M2	al and 2M and	wide d IoT
Module 2: IOT	REFERENCE ARCHITECTUR	E	8		20)
Introduction, Func	tional View, Information View, Deple Real-World Design Constraints- Introdu	oyment and Operational ction, Technical Design co	View, nstrair	Othe	er Rel	evant
Module 3: IoT DATA LINK LAYER & NETWORK LAYER 8 20 PROTOCOLS 8 20 PHY/MAC Layer(3GPP MTC, IEEE 802.11, IEEE 802.15), Wireless HART,Z Wave, Bluetooth Low Ener Zigbee Smart Energy, DASH7 - Network Layer-IPv4,IPv6, 6LoWPAN, 6TiSCH,ND, DHCP, ICMP, RI					ergy, RPL,	
Module 4: - IoT	TRANSPORT & SESSION LAY	ER PROTOCOLS	8		2	20
Transport Layer (T AMQP, MQTT	CP, MPTCP, UDP, DCCP, SCTP)-(TLS	S, DTLS) – Session Layer	-HTTI	P, Co.	AP, XI	MPP,
Module 5: IoT S PROTOCOLS	ERVICE LAYER PROTOCOLS & SE	CURITY	8		2	20
Service Layer -one RPL, Application I	M2M, ETSI M2M, OMA, BBF – Securi Layer	ty in IoT Protocols – MAC	2802.1	5.4 , 0	5LoW	PAN,
Text/Reference	Books:					
	 Daniel Minoli, "Building the In EvolvingWorld of M2M Comm Publications ,2016 Jan Holler, VlasiosTsi Avesand,StamatisKarnouskos, Da Internet ofThings: Introduction Academic Press, 2015 Bernd Scholz-Reiter, Florian Things",ISBN 978-3-642- 19156-4 N. Ida, Sensors, Actuators and The 	nternet of Things with I nunications", ISBN: 978 atsis, Catherine avid Boyle, "From Mach to a New Age of Inte Michahelles, "Architect 5 e-ISBN 978-3-642-1915" eir Interfaces, Scitech Publ	Pv6 a -1-118 Mulli ine-to lligenc ing t 7-2, Sp ishers,	nd M -4734 gan, -Mach ce'', 1 he I rringer 2014	11Pv6: 7-4, S nine to st Ed nterne ; 2016	The Willy tefan o the ition, t of

List of Experime	ents:
	1. Scanning the available SSID's in the range of Wi-Fi.
	2. Demonstration of a peer-to-peer network topology.
	3. Check the connectivity to any device in the same network.
	4. Send hello world to TCP server existing in the same network
	5. Reading Temperature and Relative Humidity value from the sensor
	6. Reading sensor data from sensorand sending into UART.
	7. Transmitting the measured physical value from the sensor over the air.
	8. BLE beacon: Experiment involves initializing BLE stack, advertising packet/beacon
	(Eddystone frame format may be used) and starting the advertisement.
	9. Experiment is to understand BLE GATT protocol and develop profiles based on GATT services.
	10. Point to point communication of two C-Motes over the radiofrequency.
	11. Reading Temperature, Relative Humidity, Light intensity value from light sensor,
	Proximity detection with IR LEDvalue from the sensor.
	12. Demonstrate CoAP Protocol using Terminal
	13. Demonstrate MQTT protocol using Terminal
	14. Demonstrate DHT11 Sensor using free cloud services.

Course title:	OPTICAL COMMUNICATION	Sub code	: (6LP36				
		Structur	e:	L	T	Р	С	
				3	0	2	5	
 Course Objective: To study about the various optical fiber modes, configuration and transmission characteristics To learn about the various optical sources, detectors and transmission techniques To explore various idea about optical fiber measurements and various coupling techniques To enrich the knowledge about optical communication systems and networks 						ision Ipling orks		
Course Outcor	 Demonstrate an understanding of option propagation and transmission propertie estimate the losses and analyse the prosignal in different types of fibers Describe the principles of optical sour methods Compare the characteristics of fiber optical sour properties of the principles of	 Demonstrate an understanding of optical fiber communication link, structure, propagation and transmission properties of an optical fiber. estimate the losses and analyse the propagation characteristics of an optical signal in different types of fibers Describe the principles of optical sources and power launching-coupling methods Compare the characteristics of fiber optic receivers 						
Content		No. of	hours	ESF	E Ma	arks	(%)	
Module 1: Intr	oduction to Optical Fibers	8				20		
and configurations in cylindrical op fabrication technic	al optical fibre communication system- basic of -mode analysis for optical propagation through tical fibre-transverse electric and transverse jues-fiber optic cablesclassification of optical fib	fibersmode magnetic per-single mo	and defined s in plan modes- ode fiber	ar wa fiber -grad	nsop ve g ma ed in	tical r uide-r terials idex fi	nodes nodes s-fiber iber.	
Module 2: Tra	nsmission Characteristic of Optical Fib	er	8			20		
Attenuation-absor symbol interferen polarization mode single mode fiber-	ption –scattering losses-bending losses-core and ce and bandwidth-intra model dispersion-mate dispersion-intermodal dispersion optimization R-I Profilecut-off wave length-dispersion calcul	d cladding le terial disper n of single ation-mode	osses-sig sion- w mode fi field diar	gnal d avegu ber-cl meter	lispen nide harac	rsion dispe cterist	-inter rsion- ics of	
Module 3: Opt	ical Sources and Detectors		8			20		
Sources: Intrinsic and extrinsic material-direct and indirect band gaps-LED-LED structuressurface emitting LED-Edge emitting LED-quantum efficiency and LED power-light source materials-modulation of LED-LASER diodes-modes and threshold conditions-Rate equations-external quantum efficiency-resonant frequencies-structures and radiation patterns-single mode laser-external modulation-temperature effort.Detectors: PIN photo detector-Avalanche photo diodes-Photo detector noise-noise sources-SNR-detector response time-Avalanche multiplication noise-temperature effectscomparisons of photo detectors.								
Module 4: Opt	ical Receiver, Measurements and Coup	ling	8			20		
Fundamental receiver operation-preamplifiers-digital signal transmission-error sources-Front end amplifiers-digital receiver performance-probability of error-receiver sensitivity-quantum limit.Optical power measurement-attenuation measurement-dispersion measurement- Fiber Numerical Aperture Measurements- Fiber cut- off Wave length Measurements- Fiber diameter measurements-Source to Fiber Power Launching-Lensing Schemes for Coupling Management-Fiber to Fiber Joints-LED Coupling to Single Mode Fiber-Fiber Splicing,Optical Fiber connectors.								
Nodule 5: Opt	ical Communication Systems and Netw	orks	ð			20		

System design consideration Point – to –Point link design –Link power budget –rise time budget, WDM – Passive DWDM Components-Elements of optical networks-SONET/SDHOptical Interfaces-SONET/SDH Rings and Networks-High speed light wave Links-OADM configuration-Optical ETHERNET-Soliton.

Reference Bo	oks:
	 "Fibre Optics: Communication and Application" by Henry Zanger and Cynthia Zanger "Fibre Optic Communications" by Harold B Killen "Fiber Optics" by Robert J Hoss "Fibre Optic Communication" by Agarwal D C "Integrated Optics" by T Tamir
list of Experir	nents:
	 Demonstration and study of different types of Optical Fibers. To Establishanalog link using optical fiber cable. To Establish Digital link using optical fiber cable. To measure propagation or attenuation loss in optical fibre. To Study Bending Loss in fiber optic communication. To Measure the Numerical Aperture (N.A.) of the Fiber Optic Cable. Demonstration and study of different types of Optical fiber connectors. To implement Frequency Modulation technique with fiber optic. Setting up of Fiber Optics voice link using Intensity Modulation. To Study the Fiber Optic Splicing and Joining.

Course title:	Digital System Design using Verilog	Sub code:	7LF	7LP36				
		Structure:	L	Т	Р	С		
			3	0	2	5		
Course Object	 Course Objective: To study and design digital circuits using Verilog HDL. To learn the design of VLSI circuits using SPICE. To perform schematic, layout, DRC and LVS of the mentioned circuits. 							
Course Outcon	 Orderstand the concepts of Verilog La Design the digital systems as an activi Study the design and operation of sem in application specific digital system. Inspect how effectively ICs are embed for different application. Design and diagnosis of processors an systems. 	 Understand the concepts of Verilog Language. Design the digital systems as an activity in a larger systems design context. Study the design and operation of semiconductor memories frequently used in application specific digital system. Inspect how effectively ICs are embedded in package and assembled in PCBs for different application. Design and diagnosis of processors and I/O controllers used in embedded systems. 						
Content		No. of hours	ESE	Ma	rks (%)		
Module 1: Intr	oduction and Methodology	8		2	0			
Digital Systems Combinational Ba Number Basics: U Sequential Basics:	and Embedded Systems, Real-World Circ sics: Combinational Components and Circuits, V Insigned integers, Signed Integers, Fixed point I Sequential Data paths and Control Clocked Synch	uits, Models, D Verification of Co Numbers, and Flo hronous Timing M	Design Ombina Dating-p Iethodo	Me tiona point plogy	thodo al Circ Num 7.	logy. cuits. bers.		
Module 2: Intr	oduction to Verilog HDL	8			20			
Verilog as HDL, Verification, Syste Tools. Language Characters, Comm Parameters, Opera	Levels of Design Description, Concurrency, em Tasks, Programming Language Interface (PI Constructs and Conventions: Introduction, nents, Numbers, Strings, Logic Values, Strengt tors.	Simulation and S LI), Module, Simu Keywords, Ident hs, Data Types,	Synthe ulation ifiers, Scalars	sis, and Wh s and	Funct Syntl iite S d Vec	ional hesis pace ctors,		
Module 3: Sequ	uential and Combinational Circuit Desig	n 8	20					
Synchronous and asynchronous FSM design, Basic design steps, State encoding techniques, Analysis of sequential circuits, Algorithmic state machines (ASM) charts. Design with basic logic gates, comparators, data selectors, priority encoders, decoders, full adder, ripple-carry adder, carry-look ahead adder, HDL models.								
Module 4: Prog	grammable Logic Devices	8			20			
PAL, PLA, PLD, CPLD, FPGA. Case Studies: Xilinx 9500 CPLD series, SPARTAN FPGA, VIRTEX Series, Review of Multi FPGA boards for real time application development. Case Studies: Design, Simulation, Synthesis and Implementation of Sequential Designs like- ALU design, CPU design: Code converters.								
Module 5: FPC	Module 5: FPGAs 8 20							
Field Programmable gate arrays- Logic blocks, routing architecture, design flow technology mapping for FPGAs, Case studies Sitar x XC4000 & ALTERA's FLEX 8000/10000 FPGAs: AT &T ORCA's (Optimized Reconfigurable Cell Array): ACTEL's ACT-1,2,3 and their speed performance								

Reference Boo	oks:
	 Peter J. Ashen den, —Digital Design: An Embedded Systems Approach Using VERILOG, Elsevier, 2010. J Bhasker, A Verilog HDL Primer, BS Publication Fundamentals of Logic Design with Verilog Design–Stephen. Brown and Zvonko Vranesic, TMH, 2ndEdition 2010. Advanced Digital Logic Design using Verilog, State Machine & Synthesis for FPGA –Sunggu Lee, Cengage Learning, 2012. Advanced Digital Design with Verilog HDL –Michael D. Ciletti, PHI, 2009.
List of Experi	ments:
	 To write the Verilog code for Basic and universal logic gate. To write the Verilog code for 8:1 Multiplexer. To write the Verilog code for 1:8 De-multiplexers. To write the Verilog code for 3:8 Decoder. To write the Verilog code for Shift Register. To write the Verilog code for Adder. Half Adder b) Full Adder To write the Verilog code for Comparator Circuits. To write the Verilog code for Flip Flops. D - FF b) JK-FF c) T-FF To write the Verilog code for Sequential counter. To write the Verilog code for BCD to 7 Segment Decoder.

Course title:	Data Communication & Computer	Sub code:	7 L	7LP39		
	Network					-
		Structure:	L	Т	Р	С
		3 0 2				5
Course Object	 A data communication and computer networks has been growing with rap technological progress. Computer communication through networking becom essential part of our life. By considering importance of networking in day toda lire, it is essential for students to know the basic concept of networks lil network classification, network topologies network devices. This course deal with the important concepts and techniques related to da communication and enable students to have an insight in to technologinvolved to make the network communication possible. The theory, practical experiences and relevant soft skills associated with the course are to be taught and implemented, so that the student demonstrates the following industry-oriented COs associated with the above-mentione competency: a. Analyze the functioning of data communication and computer network. b. Select relevant transmission media and switching techniques as per need. c. Analyse the transmission errors with respect to IEEE standards. d. Configure various networking devices. 			rapid omes today i like data ology n this es the ioned		
Content		No. of hours	ESI	EM	arks	(%)
Module 1: Intr	oduction	8	20			
Data Communicat	iona Naturalia. The Internet Distance on d Star	ndanda Naturanti Ma	dala	Lor	T home	laalta

Data Communications, Networks, The Internet, Protocols and Standards, Network Models, Layered Tasks, The OSI Model, Layers in the OSI Model, TCP/IP Protocol Suite, Addressing, Physical Layer and Media, Data and Signals, Analog and Digital, Periodic Analog Signals, Digital Signals, Transmission impairment, Data Rate Limits, Performance, Digital Transmission, Digital-to-Digital Conversion, Analog-to-Digital Conversion, Analog Transmission, Digital-to-analogue Conversion, Analog-to-analogue Conversion

Module 2: Physical and Data Link Layer	8	20

Bandwidth utilization: Multiplexing and Spreading, Multiplexing, Spread Spectrum, Transmission Media, Guided Media, Unguided Media: Wireless, Switching, Circuit-Switched Networks, Datagram Networks, Virtual-Circuit Networks, Structure of a Switch, Using Telephone and Cable Networks for Data Transmission, Telephone Networks, Dial-up Modems, Digital Subscriber Line, Cable TV Networks, Cable TV for Data Transfer Error Detection and Correction, Introduction, Block Coding, Liner Block Codes, Cyclic Codes, Checksum, Data Link Control, Framing, Flow and Error Control, Protocols, Noiseless Channels, HDLC, Point-to-Point Protocol, Multiple Access, Random Access, Aloha, Controlled Access, Channelization, IEEE Standards, Standard Ethernet, Changes in the Standard, Fast Ethernet, Gigabit Ethernet, IEEE 802.11, Bluetooth, Connecting LANs, Backbone Networks, and Virtual LANs, Connecting Devices, Backbone Networks, Virtual LANs, Cellular Telephony, Satellite Networks, Sonet/SDH, Architecture, Sonet Layers, Sonet Frames, STS Multiplexing, Sonet Networks, Virtual Tributaries, Virtual-Circuit Networks: Frame Relay and ATM, Frame Relay, ATM, ATM LANs.

Module 3: Network Layer

20

Logical Addressing, IPv4 Addresses, IPv6 Addresses, Network Layer: Internet Protocol, Internetworking, IPv4, IPv6, Transition from IPv4 to IPv6, Network Layer: Address Mapping, Error Reporting and Multicasting, Address Mapping, ICMP, IGMP, ICMPv6, Network Layer: Delivery, Forwarding and Routing, Delivery, Forwarding, Unicast Routing Protocols, Multicast Routing Protocols.

Module 4: Tran	sport Layer	8	20		
Process-Process Delivery: UDP, TCP and SCTP, Process-to-Process Delivery, User Datagram Protocol (UDP), TCP, SCTP, Congestion Control and Quality of Service, Data Traffic, Congestion, Congestion Control, Two Examples, Quality Service, Techniques to improve QoS, Integrated Services, Differentiated Services, QoS in Switched Networks.					
Module 5: Appl	ication Layer	8	20		
Domain Name Sys Internet, Resolution (DDNS), Encapsula Electronic Mail, F Management: SNM Multimedia, Digitiz Streaming Live Auc	stem, Name Space, Domain Name Space, Distr n, DNS Messages, Types of Records, Registra ation, Remote Logging, Electronic Mail and Fi File Transfer, WWW and HTTP: Architecture IP, Network Management System, Simple Net zing Audio and Video, Audio and Video Compre dio/Video, Real-Time Interactive Audio/Video, R	ribution of Name ars, Dynamic Do le Transfer, Rem , Web Documer work Managemen ession, Streaming TP, RTCP, Voice	e Space, DNS in the omain Name System note Logging, Telnet, nts, HTTP, Network nt Protocol (SNMP), Stored Audio/Video, over IP.		
Reference Book	s:				
List of Experim	 Data Communications and Networking, Fou TMH. Computer Networks, A.S. Tanenbaum,4th ed Introduction to Data communications an education. Data and Computer Communications, G.S. Taylor and Francis Group. An Engineering Approach to Computer Net Education Understanding communications and Netwo Learning. Ents: Configure Peer-to-Peer Network with at lease 	urth Edition by Bo dition, Pearson ed d Networking, N S. Hura and M. works-S. Keshav rks,3rd Edition, N	ehrouza A. Forouzan, lucation. W. Tomasi, Pearson Singhal, CRC Press, ,2nd Edition, Pearson W. A. Shay, Cengage		
	 Create desired standard network cable includitester. Connect Computers using given topology with Connect Computers using wireless media. Write a C program for CRC Error Detection Create a Network Using Bluetooth-(Piconet/ Share Printer and Folder in a network and another. Install operating, system (Windows/Linux-R Configure File Server. Configure Client to File Server and use file set in Configure DI-TCP server. Run Basic TCP/1P Utilities and Network netstat, path ping, route. Install Wireshark and configure as packet sn Set access rights and security permissions for 16. Create 1PV6 based small computer network source-based simulator) 	ding cross cable a ith wired media. 'Scatternet). transfer a file fr dedHat/Ubuntu). services. c commands: ipo iffer. r user. rk using a simula	nd test by using cable rom one computer to config. ping, tracert, ator (preferably open		

17. Setting up a wireless network.

Course title:	Satellite Communication	Sub code:	ib code: 7LP40.1				
		Structure:	L	Т	P	C	
			3	0	2	5	
Course Object	 To enable the student to become familia Study of satellite orbits and launching. Study of earth segment and space segme Study of satellite access by various user 	To enable the student to become familiar with satellites and satellite services. Study of satellite orbits and launching. Study of earth segment and space segment components. Study of satellite access by various users.					
Course Outcor	 Understand the orbital and functional systems. Architect, interpret, and select appropri specified satellite communication system Analyse and evaluate a satellite link and link performance. Select an appropriate modulation, mult schemes for a given satellite communication systems as per given specify, design, prototype and the communication systems as per given specified satellite specif	orbital and functional principles of satellite communication pret, and select appropriate technologies for implementation of te communication systems. aluate a satellite link and suggest enhancements to improve the ce. opriate modulation, multiplexing, coding and multiple access iven satellite communication link. gn, prototype and test analogue and digital satellite systems as per given specifications.					
Content		No. of hours	ES	E Marks (%)			
Module 1: Orb	ital Mechanics	8	20				
Introduction: Ove bands. Orbital Me Angles, Orbital p outage, Coverage	rview of Satellite Communications, GEO, MEO chanics: Orbit Equations, Locating the satellite w erturbation, Effects of earth's oblate ness, moon angle, slant range, satellite launching.	and LEO satellite . r. t. the earth, Or and sun, Satellite	e sys rbita e ec	stem l ele lipse	is, fr emen e, su	equency ts, Look n transit	
Module 2: Sate	ellite subsystems	8	20				
Attitude and Orbi System, Satellite a	t Control System (AOCS), Telemetry, Tracking a ntennas, Communications subsystem, transponders	nd Command Sys s.	stem	(TT	[&C)), Power	
Module 3: Sate	llite Link Design	8	20				
Basic transmission design, Up link c telephone signals,	n theory, System noise temperature and G/T rat lesign, System design examples. Modulation and Analog FM SCPC, PSK, QPSK.	io, CNR, CIR, A d Multiplexing: F	CI, FM v	IMI with	, Do mul	wn link ltiplexed	
Module 4: Mul	tiple Access Schemes	8	20				
FDM/FM/FDMA, TDMA, Frame structure, frame acquisition, synchronization, TDMA in VSAT network, On-board processing, CDMA, Spread spectrum transmission and reception, DS-SS CDMA capacity. Error Control for Digital Satellite Links: Error control coding, Block codes, Convolution codes, Implementation of error detection on satellite links.							
Module 5: VSA	Module 5: VSAT Systems & LEO Satellite systems820						
Overview of VSAT systems, Network architectures, Access control, Multiple access selection. Orbits, Coverage and frequency bands, off axis scanning, delay and throughput, NGSO constellation design.							

Reference Books	:
1.	Satellite communication, "Timothy Pratt, Charles Bostian, Jeremy Allnut", John
	Willey and Sons Inc, 2nd edition.
2.	Satellite Communication Systems Engineering, "W. L. Pritchard, H.G. Suyderhoud,
	R.A. Nelson," Pearson Education, 2nd edition.
3.	M. RICHHARAIA, Satellite Communication Systems, BS Publishers, 2nd Edition,
	2008.
4.	Satellite Communications Systems: systems, techniques and technology, 5th edition,
	by G. Maral, M. Bousquet, Z. Sun, Publisher: John Willy and sons.
5.	Satellite Communication Technology, Dr. K. Miya, 2nd edition.
6.	G. D. Gordon and W. L. Morgan, "Communications Satellite Handbook," Wiley
	India, 2010
7.	D. Roddy, "Satellite Communications," 4thEd., Tata McGraw-Hill Education, 2006.
8.	TRI.T. HA, Digital Satellite Communications, McGraw-Hill, 2000.
List of Experime	ents:
List of Lab Assignm	nents / Experiments OR List of Tools on which the lab assignment should be based (If
Any)	

Course title:	Mechatronics	Sub code:	7LP40.2				
		Structure:	L	Т	Р	C	
			3	0	2	5	
Course Object	 To prepare learners to identify, a to mechatronics engineering. To enable the learners in building CNC machines, rapid prototyp interdisciplinary approach. To prepare the learners to use mengineering in order to simulate a To develop the ability of learner innovative product design and approach. 	 To prepare learners to identify, analyse and solve engineering problems relate to mechatronics engineering. To enable the learners in building and programming technology systems such a CNC machines, rapid prototyping systems, industrial robotics etc. throug interdisciplinary approach. To prepare the learners to use modern tools involving different disciplines of engineering in order to simulate and solve real life problems. To develop the ability of learners to synthesize data and technical concepts for innovative product design and process automation using concurrent desig approach. 					
Course Outcon	 ne: The theory, practical experiences and are to be taught and implemented, sindustry-oriented COs associated wit Install and maintain the sensors a Install and Maintain CNC Machine Install and Maintain pneumatic constant of the sensor of the sen	 The theory, practical experiences and relevant soft skills associated with this course are to be taught and implemented, so that the student demonstrates the following industry-oriented COs associated with the above-mentioned competency: Install and maintain the sensors and transducers of mechatronics systems. Install and Maintain CNC Machine. Install and Maintain pneumatic components in mechatronic systems. Install and Maintain hydraulic components in mechatronic systems. Install and Maintain different components of robotic systems. 					
Content		No. of hours	ESI	E Ma	arks	(%)	

Module 1: Sensors for Mechatronics system	8	20

Mechatronics system architecture: Sensors, signal conditioners, PLC/ Embedded controllers, pneumatic, hydraulic and electrical actuators.

Introduction to Real Time Mechatronics System: Block diagram & Functions: Real time mechatronics system (Flexible Manufacturing System: FMS), Computer Integrated Machines: CIM))

Sensors: Construction, principle of operation and application) Proximity and position Sensors: Photo electric sensors, Hall Effect sensors, optical encoder, eddy current proximity sensor, inductive sensor, capacitive sensor.

- i. Velocity Sensors: Electromagnetic transducers, Techno generators
- ii. Motion Sensors: Stroboscope, pyro electric sensors.
- iii. Acceleration sensors: strain gauge accelerometer. Piezoelectric
- iv. Pressure sensors: Load cells
- v. Torque sensors: Torque Measurement using strain gauge, torque measurement using torsion bar (optical method, capacitive method, proximity sensor method, stroboscope method).
- vi. Signal conditioners: Need of isolators, filters, amplifiers, fluid amplifiers and optical amplifiers and data converters in mechatronics.

Module 2: Basic Mechatronics systems	8 20
~	

Basic System Models: Introduction, mechanical system building blocks Translational and Rotational system building up a mechanical system model, Electrical system building blocks -building up a model for an electrical system. System Models: Introduction, rotational-translational systems, electromechanical systems - System components & function. (No mathematical modelling), CNC Machines: General configuration of CNC system, advantages of CNC, part programming of CNC machines, G codes and M codes, small application programs, CNC based drilling machine.

Module 3: Pneumatic Sys	tem	8	20				
Basic Pneumatic Systems: Basic, Pneumatic system circuit, Air compressors, filters and regulators, air treatment, valves. Actuators: Principle of operation of linear actuators (single acting cylinder, double acting cylinder) rotary actuators (rotating vane, gear type) and direction control valves (poppet valve, spool valve), Pneumatic System: Applications, Advantages and Limitations.							
Module 4: Hydraulic Syst	em	8	20				
Actuators: Principle of operation of linear actuators (single acting cylinder, double acting cylinder) rotary actuators (rotating vane, rack and pinion type). Mechanical Motion Element: cams, gear, belt, rack and pinion and bearings (principle of operation and application), Hydraulic System: Applications, Advantages and Limitation.							
Module 5: Robotics and N	Iechatronics Applications	8	20				
Robotics: Block diagram and effectors), construction and deg robot. Microcontroller based Microcontroller based car park diagram, role of mechatronic in Reference Books:	function of each component (senso rees of freedom of cylindrical, spheric antilock brake system. Microcom barrier system. AGV (Automated G guided vehicle.	ors, drive system, con cal and Cartesian robo troller based pick a Guided Vehicle): Bas	ntrol system, end ts, applications of and place robot. ic concept, block				
1 Damaak	andron K. D. Wiener Dachaum C. K	· Dala Sun danam MG	. "Machataniag				
-Integra 2008 IS 2. Bolton, 0131210 3. Rajput, 219-285 4. Singh, N Delhi,20	 -Integrated Mechanical electronic systems" Wiley-India, New Delhi First edition, 2008 ISBN: 978-81-265-1837-1. 2. Bolton, W., "Mechatronics" Pearson Education, New Delhi, 2003,3rd Edition, ISBN: 0131216333. 3. Rajput, R. K. "Mechatronics" S. Chand & Co. ltd. New Delhi, 1st Edition, ISBN: 81-219-2859-1. 4. Singh, M. D.; Joshi, J. G., "Mechatronics" PHI Learning Private Limited, New Delhi 2006, ISBN: 8120329864. 						
List of Experiments:							
1. Identify2. Choose3. Use release3. Use release3. Use release3. Use release4. Measure5. Identify6. Identify7. Identify8. Develop8. Develop9. Trouble10. Test the11. Trouble12. Test the13. Trouble14. Simulat16. Demons17. DemonsDevelop17. Demons	different types of proximity and posit the appropriate sensors for the given a vant transducer for velocity, motion, a d applications. the speed of the given motor using st various components of translational nector various components of rotational meetor various components of electrical syste simple programs for CNC using G co e). shoot pneumatic system of mechatronic pneumatic system available in your L shoot hydraulic system of mechatronic hydraulic system available in your La shoot different mechanical actuators of e the working of cylindrical, spherical of freedoms. the the working of pick and place robot. trate the working of Automated Guide try/Videos). trate the working of Anti-lock Braking	ion sensors. applications. acceleration and torque roboscope sensor. mechanical system. chanical system. em. ode and M code. (open ic systems. ab. c systems. ab. c systems. b. of mechatronic system and Cartesian robot sl (MATLAB / Simulinl e Vehicle (Virtual Lab g System (ABS) (Virtu	e sensors for the a-source s howing different k software). / Demonstration ual Lab /				

Course title:	Mob	ile and Wireless Communication	Sub code:	7LP40.3				
			Structure;	L	Τ	Р	С	
				4	0	2	5	
Course Objective: In this world of connectivity and collaborative work environment, in necessary to connect to the network from anywhere, with anybody, at time. Wireless communication provides connectivity with mobility, flexible and convenience. Wireless devices are used across the various industries Healthcare, Education, Automation, Renewable energy sector, Automatice etc. Effective use of Social networking has become possible due to high wireless devices. This course will help the students to develop skills to hawireless and mobile communication systems.				it is t any bility s like obile h end andle				
Course Outco	ome:	 The theory, practical experiences and relevant soft skills associated with this course are to be taught and implemented, so that the student demonstrates the following industry-oriented COs associated with the above-mentioned competency: Troubleshoot mobile handsets. Assess cellular systems capacity. Assess performance of standards of different cellular mobile systems. Select relevant wireless technology suitable for various applications. Test the performance of various wireless protocols. 						
Content			No. of hours	ES	ΕN	larks	; (%)	
Module 1: Wireless Communication System:820			20					
Wireless network generations, Mobile Radio standards- AMPS, N- AMPS, IS -95, GSM, UMTS, CDMA 2000, Mobile wireless systems: Cordless Telephone system and Cellular telephone system								

Fixed wireless networks: Wireless Local Loop (WLL) & Local Multipoint Distribution System (LMDS), Mobile Phone Unit: Block diagram, working, features, of transmitter, and receiver section, Frequency Synthesizer, Control unit and Logic Unit of Mobile phone, sensors: speakers, camera, touch screen, motion sensors and other common sensors.

Module 2: Fundamentals of Cellular System	8	20
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Cellular concept fundamentals: Cell, cell structure, Cluster, Reuse factor, minimum reuse distance, basic cellular system: mobile station, base station, Traffic channel (Forward and Reverse), Control channel (Forward and Reverse), Frequency reuse, channel assignment strategies, F land off strategies: Concept of handoff, Types of Handoffs: Hard, Soft, Queued, delayed, MAHO (Mobile Assisted Handoff), Proper. and Improper Handoff, Umbrella cell approach, Interference and system capacity: Co-Channel interference, Adjacent Channel Interference, Channel Planning for wireless systems Improving Coverage and capacity in cellular systems: Cell splitting, Sectoring, Microcell Zone concept. Repeaters for range extension.

Module 3: Digital Cellular Mobile Standards	8	20
-		

Global System for Mobile Communication (GSM): Features and Services, GSM radio aspects, GSM architecture, GSM channel types, Security aspects. GSM Call routing: Mobile terminated call and mobile originated call sequence, stages of call processing in GSM, IS-95/CDMA One: features, Radio aspects, comparison with GSM standards.

Signaling System No.7 (SS7): Network services part (NSP), Message transfer Part (MTP), Signaling Correction Control part (SCCP), Services and performance of SS7.

Module 4: Advance Wireless Standards	8	20
Need for 2C and 4C to hard one INT 2000 also a dander With	C	

Need for 3G and 4G technology, IMT-2000 global standards: Vision, Compatibility, service and spectrum requirements, UMTS /W-CDMA standard: Features, architecture, UMTS Air- interface specification,

security procedure, CDMA 2000, features and advanced versions, advantages of CDMA 2000 over 3G-GSM standards. Next generation mobile standards: Features of 4G & 4G LTE, VoLTE, 4.5G, 5G.

Module 5: Wireless Network Technologies	8	20
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Bluetooth technology: Features, architecture, frequency band, IEEE 802.15.1 and other wireless protocol, applications, personal area network (PAN) RFID: Concept, frequency band, classification of RFID tags, applications WEAN technology: IEEE 802.11, WLAN system architecture, radio spectrum WMAN /Wi-max/IEEE 802.16 WMAN and IEEE 802.16a WiMAX Mobile Ad-hoc networks (MANET's): MANET topologies, applications.

Reference	Books:
	1. Mobile Cellular Telecommunications System by Lee, C. Y. William.
	2. Wireless Communication- Principles and practice by Rappaport, S. Theodore.
	3. Wireless Communication by Signal, T. L.
	4. Wireless and mobile network Architectures by Lin Yi-Bang Clamtac Imrich.
list of Exp	eriments
	 Identify different sections and components of mobile phone such as ringer section, dial section, receiver section and transmitter section, camera, microphone, speaker, flash light. Identify the inbuilt sensors of mobile handset and test their performance. Perform cold test of different sections of mobile phone unit. Test the supply of the Transmitter /Receiver section of mobile phone unit. Test the Battery charger section and power management unit of mobile phone unit. Determine the coverage area of a split cell which has radius half the radius of original cell. Determine the channel capacity of a cellular system service area comprised of 4/7/12 microcells with 8/12/16 channels per microcell. Determine the channel capacity if each microcell in the above lab exercise split into 4 minicells and each minicell is further split into 4 microcells. For the 7- cell cluster and 168-voice channels cellular system, determine the assignment of voice channel to each cell if Omnidirectional antenna is used at the cell site. For the 7- cell cluster, 168-voice channels cellular system, determine the assignment of voice channel to each sector if 3- sector 120° and 6 -sector 60° directional antenna are used at the cell site. Perform installation, registration, activation and authentication of mobile applications on mobile handset. Read/Retrieve the contents of SIM card using relevant software. Execute Network service commands using relevant software.

Course title:	Artificial Intelligence and Machine Lean	rning	Sub co	de:	'	7LP	40 .	.4
			Structu	ire:	L	Т	Р	C
		ľ			3	0	2	5
Course Object	 Course Objective: To introduce the basic concepts, theories and state-of-the-art techniques artificial intelligence. To introduce basic concepts and applications of machine learning. Help students to learn the application of machine learning /A. I algorithms the different fields of science, medicine, finance etc. 					of in		
Course Outco	 Understand concept of knowledge transform the real-life information in Understand state space and its search Understand machine learning conceptant handled by machine learning. Apply the machine learning concepts 	 Understand concept of knowledge representation and predicate logic and transform the real-life information in different representation. Understand state space and its searching strategies. Understand machine learning concepts and range of problems that can be handled by machine learning. Apply the machine learning concepts in real life problems. 					nd be	
Content		No. of	hours	ESE	Ma	rks	(%)
Module 1: Int	roduction	8	8		2	0		
Introduction to A Artificial Intellig Language Possess	rtificial Intelligence, Foundations and History of gence, Intelligent Agents, Structure of Intellige sing.	Artificia nt Agen	l Intellige ts. Comp	ence, A outer v	Appl visio	ication, N	ons [atu:	of ral
Module 2: Intr	roduction to Search		8		2	0		
Searching for sol and optimistic pro	utions, Uniformed search strategies, Informed sea oblems, Adversarial Search, Search for games, Alp	urch strat ha - Beta	egies, Lo pruning.	cal sea	rch	algo	rithi	ns
Module 3: Kno	owledge Representation & Reasoning		8		2	0		
Propositional log chaining, Resolut Networks.	ic, Theory of first order logic, Inference in Finition, Probabilistic reasoning, Utility theory, Hidd	rst order len Mark	logic, F ov Mode	orward ls (HN	& 1M)	Bac , Ba	kwa yesi	an
Module 4: Ma	chine Learning		8		2	0		
Supervised and u data - Naive Baye	nsupervised learning, Decision trees, Statistical leas models, Learning with hidden data - EM algorith	earning n nm, Reinf	nodels, le forcement	arning learni	with ng.	n cor	nple	ete
Module 5: Pat	tern Recognition		8		2	0		
Introduction, Design principles of pattern recognition system, Statistical Pattern recognition, Parameter estimation methods-Principal Component Analysis (PCA) and Linear Discriminant Analysis (LDA), Classification Techniques – Nearest Neighbour (NN) Rule, Bayes Classifier, Support Vector Machine (SVM), K – mean clustering.								
Reference Boo	oks:							
1. 2. 3. 4. 5.	Stuart Russell, Peter Norvig, "Artificial Intelligence Education Elaine Rich and Kevin Knight, "Artificial Intellige E Charniak and D McDermott, "Introduction to An Education Dan W. Patterson, "Artificial Intelligence and Exp Tom M. Mitchell, —Machine Learning, McGraw- 2013.	ce – A M ence", Mo rtificial In ert Syste Hill Educ	odern App cGraw-Hi ntelligenco ms", Pren cation (Inc	proach ll e", Pea tice Ha dia) Pr	", Pe rson all o ivate	earso 1 f Ind e Lin	n ia niteo	1,

	6. Ethem Alpaydin, -Introduction to Machine Learning (Adaptive Computation and
	Machine Learning), The MIT Press 2004.
List of E	Experiments:
	1. Implement A* Search algorithm.
	2. Implement AO* Search algorithm.
	3. For a given set of training data examples stored in a .CSV file, implement and demonstrate
	the Candidate-Elimination algorithm to output a description of the set of all hypotheses consistent with the training examples.
	4. Write a program to demonstrate the working of the decision tree based ID3 algorithm. Use an appropriate data set for building the decision tree and apply this knowledge to classify a new sample.
	5. Build an Artificial Neural Network by implementing the Backpropagation algorithm and test the same using appropriate data sets.
	6. Write a program to implement the naïve Bayesian classifier for a sample training data set stored as a .CSV file. Compute the accuracy of the classifier, considering few test data sets.
	7. Apply EM algorithm to cluster a set of data stored in a .CSV file. Use the same data set for clustering using k-Means' algorithm. Compare the results of these two algorithms and comment on the quality of clustering. You can add Java/Python ML library classes/API in the program.
	8. Write a program to implement k-Nearest Neighbour algorithm to classify the iris data set. Print both correct and wrong predictions. Java/Python ML library classes can be used for this problem.
	9. Implement the non-parametric Locally Weighted Regression algorithm in order to fit data points. Select appropriate data set for your experiment and draw graphs.

Course title:	Microwave Engineering	Sub code:	7L4	7L41			
	Structure:			Т	Р	С	
3 0 0 3							
Course Object	 An understanding of microwave wa and network analysis. An ability to design microwave mat An understanding of RADARs and an analysis 	of microwave waveguides, passive & active devices, tubes sis. n microwave matching networks. of RADARs and its applications.					
Course Outcor	 Familiarity with basic concepts and Ability to demonstrate waveguide co Ability to solve problems on microw Ability to design, implement, ar communication system Ability to get idea about different microw 	nd theory of RF & Microwave Engineering. components, assemble them. cowave communication system. analyze and maintain a high frequency microwave network circuit.				ing. uency	
Content		No. of hours	ESE	Ma	rks (%)	
Module 1: Intr	oduction	8		2	20		
RF & Microwave	spectrum, Historical Background, Typical appl	ication of RF & Mi	crowav	es.			
Module 2: Mic	rowave Tubes	8		2	20		
Limitation of con Magnetron, travel	ventional tubes in microwaves, two cavity ar ling wave tube, Backward wave oscillator–worl	nd multicavity Kly king principles, cha	stron, l racteris	Refle	ex Kly	/stron,	
Module 3: Sen	niconductor Microwave Device	8		4	20		
Tunnel diode, Gunn diode, IMPATT diode, TRAPATT diode, Microwave bipolar transistor, hetero- junction bipolar transistor, parametric amplifier Passive Components: S-matrix, Directional coupler, Bethe-hole coupler, Magic tee, Hybrid ring, Circulator, Isolator.					uetero- ulator,		
Module 4: Mic	rowave Measurement	8		- 	20		
Measurement of measurement, Imp	VSWR-Low, Medium and High, Measure bedance measurement.	ement of power,	Bolom	eter,	Freq	uency	
Module 5: Mic	Module 5: Microwaves820						
Introduction to sat	ellite communication, Radar, Industrial applica	tion of microwaves	•				
Reference Boo	ks:						
	1. Microwave Devices & Circuits S.Y. Liao Pearson Education/PHI 2. Microwave Engineering, Monojit Mitra, Dhanpat Rai New Delhi 3. Microwaves, K. C. Gupta, New Age Publisher 4. Microwave Engineering, Kulkarni, Dhanpat Rai New Delhi						

Course title:	Pro	ject Part -I	Sub code:		7 P	42				
			Structure:		L	Т	Р	С		
Course Object	ive:	Final Year Projects represent the culm Engineering degree. Projects offer the learned throughout the program. As presentation, submission of a thesis, undertaken. The projects undertaken span a divers simulation and experimental studies. The student learning in technical, project man	ination of study opportunity to ap ssessment is by and a public se range of topic he emphasis is n nagement and pre	toward oply ar demor cs, inc ecessa sentatio	ls th nd e: ns o nstra ludin rily on sj	e Ba xtend of a tion ng the on f	achel d ma of heore cacili es.	or of iterial minar work etical, tating		
Course Outcon	ne:	 On successful completion of the course s Demonstrate a sound technical know Undertake problem identification, f Design engineering solutions to approach. Conduct an engineering project. Communicate with engineers and form. Demonstrate the knowledge, skills a 	students will be all wledge of their se formulation and so complex proble the community a and attitudes of a	ble to: lected plution ems ut t large profess	proj ilisi in v	ect to ng a writto al en	opic. a sys en ar ginee	stems n oral er.		
Content			No. of hours	ESE	mar	ks (%)			
 The project we on topic related the select the topic, be system, which wi The batch has survey, technical give a talk on the will appoint two in the select the topic. 	ork wi o the y con ll be s to pr detail e selec interna	Il be carried out by a batch of at the most electronics, telecommunications, compute sulting the guide from above mentioned to ubmitted at the end of second term of curr repare a typed report of not less than 25 s, design, related data etc. It should be in cted topic in presence of staff members and al examiners to assess the term work; guid	3 students (Prefer er science and all opic. They have to rent academic yea pages. This sho the proper forma nd students. The e shall be one of t	rably 2 ied fiel o desig r. uld inc t. Even Princip the exa	stud lds. ' n an clude cy ca cal, o mine	dents The d fal e the andic of th ers.	batcl brica liter late h late ins	rking h will te the rature has to stitute		

Course title:	Elec	ctronic Product Design Using EDA tools	Sub code:		7LF	43.1	
			Structure	L	Τ	Р	C
				3	0	2	5
Course Object	tive:	 To produce graduates with a solid four fundamentals including hardware, softwar competent to apply this knowledge in the design industry. To ensure that graduates will be proficient high sensitivity to the needs of society, economically and socially feasible. To produce graduates who have the nece skills to be an effective part of the resear development. To produce graduates who are adequate chosen field and build greater technical ke as technology advances and changes. 	in analysing re- and mathem eir chosen car in analysing re- and provide ressary compe- rch field of e ely motivated nowledge and	ctroni natics eer in eal life solut tence lectron to co devel	cs E and 1 the e prol ions and nics o ontinu op hi	nginee nake electro olems which innov design e in gher s	with a are ative and their skills
Course Outco	ome:	 1.An ability to independently carry out resear work to solve practical problems An ability to write and present a substantial 3.Students should be able to demonstrate a per the specialization of the program. The than the requirements in the appropriate bac Inculcate the ability to understand clearly systems which are in tune with current te changes 5. Create an environment such that gradua and software design and be part of the eleleaders in indigenous product development 	arch /investiga technical repo- degree of ma- mastery should helor program the steps in chnology and tes develop a ectronic design	tion at rt/doc stery o d be a desig adap passion n indu	nd de umen over i t a le gning table on foi istry	velop: the are evel hi electri for fu r hard to bec	ment ea as igher ronic uture ware come
Content			No. of hours	ESE	Ma	rks ('	%)
Module 1: Sys	stem F	Reliability Concepts	8	20			
Introduction to co configuration, Par Time to Failure (I Concepts, System Procedures, Rules	oncepts rallel MTTF) n Down s for Fa	of reliability, nature of reliability problems in ele Configuration, Mixed Configuration, Methods o and Mean Time between Failure (MTBF) of Sys time, Mean time to Repair (MTTR), Fault T sult Tree Construction.	ctronic equipr f Solving Con tems. Maintai ree Analysis-	nent, s nplex { nabili · Cor	series Syste ty, A ncepts	ms, M vailab s and	lean ility
Module 2: Erg	gonon	nics and Aesthetics in Electronic Produc	t Design 8			20	
Overview of El Supply Design Designing Electro Consideration.	lectroni as an onic Pro	c Product Design, Top-Down and Bottom-U example, Ergonomic and Aesthetics Definit oducts, Design of Controls and Display w. r. t. Er	Jp Approach, ion with Exam gonomic and A	Cons pple, is Aesthe	iderin ssues etics	ng Po in	ower
Module 3: Con	ntrol	Panel Design and thermal consideration	8			20	
Types of Contr of Components, S Fabrication. Ther level, board level.	rols, De Selectio rmal ma l, syster	sign and Organization of Control Panel, Er on of Materials, Sheet metals and plastic, Structura magement of electronic equipment, Thermal design n level, Fans and system operating characteristics	ngineering Co al Design and gn consideratio , Heat Sink de	onside Contro ons, C sign.	ration ol Ca ompo	ns, Lay binets onent	yout

Module 4: C	Computer Aided design	8	20
Introduction to Analysis, Tech Techniques, Fo	Computer Aided Design, Applications and Examples, Finite Elemen niques for Surface Modelling, Rendering and Shading, Sources of Ne orm factor, Shape, Colour, Graphics etc.	t Methods (F w Ideas, Cre	•EM) and eativity
Module 5: M	Iini Project	8	20
Mini Project ba	ased on EDA Tools.		
Reference B	ooks		
List of Expe	 Ralph Remsburg, "Advanced Thermal Design of I Springer V.S. Bagad, "Electronic Product Design", Technical Publication Dave S. Steinberg, "Cooling techniques for electronic equipm Ernest Paul DeGarmo, J. T. Black, Ronald A. Kohser "Ma Manufacturing", John Wiley & Son. Military Handbook, Electronic Reliability Design Han Defense, USA Patrick O'Connor & Andre Kleyne, "Practical Reliability Eng Publication. Milton Ohring, "Reliability and Failure of Elect Devices", Academic Press. Dale H. Bester field, "Total Quality Management", 3rd ed., Petriments: 	Electronic ons. ent", Wiley, aterials and ndbook, Dep gineering", 5 cronic Mat earson Educa	Equipment", 1991. Processes in partment of th ed., Wiley terials and ation.
	 Finding out Reliability Parameters from Datasheet for Followie •Any type and Rating of Resistance. •Any type and Rating Capacitance. •Any type and Rating Diode. •Any type and Rating Transistor. Prototype Electronic Product Design and Development for Provide Structure Product Design and Development for Traditional Using Hand Made Model, Software Packages etc. Control panel layout design for various home appliances. CAD base design and simulation of product cabinet. Design and analysis of ergonomic consideration of cabin products. Design a prototype of led based street light. Design a prototype of led based table lamp. 10 Thermal design consideration for component level board level 	ng Compone wer Supply. affic Light. nets used fo	ent: or electronic

Course title:	Solar Ins	stallation and Maintenance	Sub code:	7LP	43.2		
			Structure:	L	Т	Р	С
				3	0	2	5
Course Objec	ctive:	 Solar power plants have got mathematical these objectives are Energy Battery Backup, Green energy. Install and maintain solar photo equipment. 	any objectives in a Savings, Eco-Frie voltaic (PV) powe	broad ndly, 1	contex Easy I ration s	xt. So instal yster	ome of lation, ns and
Course Outco)me:	 At the end of the course, the student w Identify renewable energy source Understand basic concepts of systems for its utilization. Understand working of solatechnologies. Identify methods of energy stor Compare energy utilization biomass, biogas and hydrogen. 	ill be able to: - ces and their utiliza solar radiation an r cells and its age. from wind energ	ntion. d analy moder gy, geo	yze so n mai otherm	lar th nufac al e	nermal cturing nergy,
Content			No. of ho	ours	ESE (%)	Mar	:ks
Module 1: Int	troduction	to Solar Energy		8		20	
Energy Technolo Fundamentals; Measurement of Module 2: So Introduction; Ba Solar air collec conditioning; Th	ogies. Necess Solar Radia solar radiati lar Therm sics of therm ctor; Solar ermal energ	sity of Energy Storage; Energy Stora ttion; Estimation of solar radiation on data. Tal systems nodynamics and heat transfer; Flat pl concentrator; Solar distillation; So y storage systems.	ge Methods. on on horizontal ate collector; Evac olar cooker; Sola	and i 8 uated 7 r refri	nclined Fubular geratic	d sur 20 r Col on ar	lector; nd air
Module 3: So	lar Photov	voltaic Energy and battery sto	orage	8		20	
Definition of Porequirements: D Modules, Rating generated by SP parallel connectine mounting structure of a battery celle batteries, VRLA series/parallel construction Module 4: So	wer and Ene paily energy gs of SPV V Modules, ons, mixed c ures. Some b 1. Types of batteries. Se onnected batt	ergy, Renewable Energy and non-reaconsumption, monthly energy co Modules, Standard SPV Module Measuring module parameters, Sol connections, calculation of total array asics about batteries, working of a b batteries, parameters of batteries. eries/Parallel connection of batteries, eries. Electronics and wiring	newable energy so nsumption and el- Parameters. Facto lar PV Module arr y power. Junction I attery (charging, d Batteries for PV Estimating total en	urces I ectricit ors aff ays: Se boxes, ischarg system hergy s	Estimat y bill. fecting eries co fuses, o ging), c ns Liq torage	ting e Sol elec conne conne comp uid capa 20	energy ar PV ctricity ctions, ectors, onents vented city in
Inverters (DC to working, Charg Resistance, volta sizing, DC cablin	AC inverter e controller age drop, typ ng, DC distri	rs): Types of inverters, Inverter spect function, working, types, specific bes of wires, their current carrying c abution box, AC cabling, AC distribution	ifications, Inverter cations MPPT Ch capacity and voltag tion box.	componarge component	onents: control calcul	circu ler, ation	uit and Wires: a, wire

Module 5: Solar PV system design, operation and maintenance	8	20
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Introduction; Solar cell Fundamentals; Characteristics and classification; Solar cell: Module, panel and Array construction; Photovoltaic thermal systems. Load estimation and energy requirement, sizing and configuration of SPV Modules, Sizing of inverter, charge controller and batteries, Selection of cables, fuses, junction box, mounting structures, Maintenance and troubleshooting of SPV Modules, batteries, maintenance and troubleshooting of inverters.

Reference Books	:
1 2 3	 Sukhatme S.P. and J.K.Nayak, Solar Energy - Principles of Thermal Collection and Storage, Tata McGraw Hill, New Delhi, 2008. J.A. Duffie and W.A. Beckman, Solar Energy - Thermal Pro Khan B.H., Non-Conventional Energy Resources, Tata McGraw Hill, New Delhi, 2006.
List of Experime	ents:
1	. Study and Install Solar Panel Mounts.
2	. Study and Install the Solar Panels.
3	. Study and Wire the Solar Panels.
4	. Study and Install Solar Inverter.
5	. Study and install Bond Solar Inverter and Solar Battery.
6	. Study and connect the Inverter to the Consumer Unit.
7	. Start and Test Solar Panels.
8	. Solar Panel Maintenance.

Course title:	Indu	istrial automation using PLC and Scada	Sub code:		8 I	.P4	4
			Structure:	L	T	Р	C
				3	0	2	5
Course Object	tive:	This course provides theoretical and practical as in industry. This course offers learning of electrical controls and Programmable logic cont	pects of implen pneumatics/ hy rollers.	nenting ydraulio	aut cs	oma syste	tion ems,
Course Outco	me:	 Students should be able to design and impneumatics. Students should be able to provide hyautomated systems. Students should be able to devise Assembly orienteers and escapement devices Students should be able to design and imply solutions for automated systems. Students should be able to apply PLC prograkits. 	plement automa ydraulic solutio v automated syst ement electro-pr camming and im	nted systems for tems us neumat	sten d ing ic/h	ns us esigr feed ydra on F	sing ning lers, ulic PLC
Content			No. of hours	ESE N	lar	ks (9	%)
Module 1: Int	roduc	tion to Automation	8	20			
Introduction-Auto an automated sys transfer mechanis	omation stem, A sms, Ai	n in production system, Principles and strategies Advanced automation functions, Levels of autom nalysis of transfer lines without storage, Automate	of automation, aations, Automa ed flow lines wi	Basic ted flo th stora	elei w li ge l	nent ines ouffe	s of and ers.
Module 2: Pro	ogram	mable Logic Controller (PLC)		8		2	0
Block diagram of interlocks, Netwo Levels of process international stand	of PLC orking s safet dards i	e, Programming languages of PLC, Basic instruct of PLC, Overview of safety of PLC with case st y through use of PLCs, Integrating Process safe n process safety control.	action sets, De udies. Process S ety PLC and DO	sign of Safety A CS, Ap	ala Auto plic	arm omat ation	and ion: n of
Module 3: Int	roduc	ction to computer based industrial	automation	8		2	0
Direct Digital acquisition(SCAI RTUs,Pumping s of pipelines, Tran	Con DA) b tations isport A	trol (DDC), Distributed Control System (DCS) ased architectures.SCADA for process indus Evacuation processes, Mass Flow Metersand oth Automation.	andsupervisory tries includes ter flow meters,	y contr unders Leak-1	ol a stan flov	and o ding / stu	data of dies
Module 4: Hydapplications	draul	ic System Elements, Actuators, Circuits	and their	8		2	0
Hydraulic System connectors, their Hydraulic Actuat and velocity of pi Speed control ci with accumulator Introduction to Fl	n Elem selection fors: Li ston Sy rcuits, and in luidics	ents: Pumps, types, working, characteristics, appl on: Seals and packing, types, materials, application near and Rotary, types, working, cushioning effor ystem components: Accumulators, Intensifiers, the regenerative, sequencing, counterbalancing, sys- tensifier. and study of simple logic gates: Hydraulic clamp	ications: Types ns. ect, mounting, c eir types, worki nchronizing, inf ing and braking	of conc alculat ng, app erlocki system	luct ion lica ng, s.	of fo tions circ	and orce s. cuits
Module 5: Pne	eumat	tics & Pneumatic System Control Eleme	nts	8		2	0
D			•	÷	-		

Pneumatics: Air compressors, types, working, selection criteria; FRL unit, construction and working; Pneumatic cylinders and air motors, construction and working, types, calculation of force and air consumption, Comparison of air, hydraulic and electric motor.

Pneumatic System Control Elements: Direction control valves, types, control methods for spool working; Flow control valves, working of variable flow control, quick exhaust, time delay and shuttle valve; Pressure control valves, types and working.

Reference Bool	ks
	 Johnson, C. D., "Process control instrumentation Technology" Prentice Hall, 8th edition, United States of America,2014 ISBN: 978-0131194571 Dunning, Gary "Intro. To Programmable logic control" Cenage Learning, United States of America,2005 ISBN: 9781401884260 Mitra, Madhuchhanda; Gupta, SamarjitSen, "Programmable logic controllers and industrial automation an introduction" Penram. 1st Edition, Mumbai. 2007 ISBN: 9788187972174 "Programmable logic controllers",Petruzella, F.D. Tata- McGraw Hill, 3"Edition, 2010 ISBN: 9780071067386 Espositio A., "Fluid Power with Applications", Pearson, 2002. Majumdar S. R., "Oil Hydraulic Systems", Tata McGraw Hill 2000 Majumdar S. R., "Robotics and image processing", Tata McGraw Hill, 1995. YoramKoren, "Robotics", McGraw Hill, 1992.
list of Experim	ents
	 Use potentiometer as error detector. Determine error of angular position of DC servo system. Test the Step response of R-C (first order) circuit. Test the Step response of R-L-C (second order) circuit. Test the functionality of temperature control with on-off controller. Use PI controller to control temperature of the given process. Use PID controller to control temperature of the given process. Use PID controller to control temperature of the given process. Use PID controller to control temperature of the given process. Identify and test different parts of PLC. Develop ladder diagram to test the functionality of the logic gates. Develop the ladder diagram for Adder and Subtractor by using PLC. Develop ladder diagram for traffic light Control system. Develop ladder diagram for stepper motor control. Develop ladder diagram for temperature control.

Course title:	Digital image Processing	Sub code:	8L	P45.	1	
		Structure:	L	Τ	P	С
			3	0	2	5
Course Objective:	 To study the image fundamentals an image processing. To study the image enhancement tech To study image restoration procedure To study the image compression proce 	d mathematical tra niques s. edures.	unsfo	orms n	necessa	ry for
Course outcome:	 After the completion of the course studer Understand the need for image transform Choose appropriate technique for infrequency domains. Identify causes for image degradation Compare the image compression techniques for 	at will be able to: as and their propertie mage enhancement a and apply restorat niques in spatial an or image analysis a	s. it bo ion t nd fro nd ro	oth in eechnic equence ecogni	spatia ques. cy don ition.	al and nains.
Content		No. of hour	S	ESE I	Marks	s (%)
Module 1: Digital I	mage Fundamentals	8		20		
 Processing Systems. Elements of Visual Per Pixels, Pixel Connectivi Operations, Image Trans Module 2: Image En Processing Spatial Domain Methon Histogram Processing, Frequency Domain, Low Sub band Coding, Haa Dimension, Discrete V Dimensions, Wavelet Pa 	ception, A Simple image model, Sampli ty, Labelling of Connected Components, I sformations, Perspective Transformations, nhancement, Wavelets And Multi- ds, Frequency Domain Methods, Point Spatial filtering, Smoothing Filters, Si v Pass Filtering, High Pass Filtering, Home ar Transform, Multiresolution Series Ex Wavelet Transform, Fast Wavelet Transform, Automatic States, State	ng and Quantizati Distance Measures Stereo Imaging. resolution processing, Inter harpening Filters, omorphic filtering. spansions, Wavelet nsform, Wavelet	on, 1 , Ari 8 nsity Enf et Tr Tra	Neighl thmeti Tran nancer ransfor nsforr	bourho ic and 20 sforma nent i rms ir ns in	ations, in the Two
Module 3: Image C	ompression & Image Segmentation	n	8		20	
Fundamentals of Compr Coding, and Transform Detection of Discontine Thresholding, Threshold Merging, Use of motion	ession, Image Compression Model, Error E Coding. uities, Line Detection, Edge Detection, d Selection on Boundary Characteristics, in Segmentation.	free Compression, Edge Linking and Region Growing,	Loss Bo Reg	y Prec undary gion S	dictive y Dete Splittin	ection, g and
Module 4: Image R	epresentation and Description		8		20	
Chain Codes, Polygonal Fourier descriptors, Mor	Approximations, Signatures, Skeleton, Bonents, Topological Descriptors.	oundary Descriptio	ns, S	hape I	Numbe	ers,
Module 5: Image R	ecognition and Interpretation		8		20	
Elements of Image Anal Correlation, Baye's Class	ysis, Pattern and Pattern Classes, Minimur sifier, Neural Network Training Algorithm	n Distance Classifi n, Structural metho	er, N ds.	Aatchi	ing by	

Reference Books:	
	 Rafael C Gonzalez and Richard E Woods, Digital Image Processing, Pearson Education Asia, New Delhi, 2000. B. Chanda, D. DuttaMajumder, Digital Image Processing and Analysis, PHI, New Delhi, 2000. A.K. Jain, Fundamentals of Digital Image Processing, PHI, New Delhi, 2001.
list of Experiments:	
	 Program to enhance image using image arithmetic and logical operations. Program for an image enhancement using pixel operation. Program for Gray level slicing with and without background. Program for image enhancement using histogram equalization. Program to filter an image using averaging low pass filter in spatial domain. And median filter. Program to sharpen an image using 2-D Laplacian high pass filter in spatial domain. Program for detecting edges in an image using Roberts cross gradient operator and sobel operator. Program for smooth an image using low pass filter in frequency domain. (Butterworth lpf) Program for smooth an image using high pass filter in frequency domain. Program for morphological image operations-erosion, dilation, opening & closing. Program for illustrating colour image processing. Program for image Watermarking.

Course title:	Cor	nsumer Electronics	Sub code				
			Structure	L	Т	Р	С
				3	0	2	5
Course Object	ive:	A consumer electronic appliance is ind	creasing demand	da	v b	v da	l iv in
Course Object		developing nations. This requires large n	umber of technic	ally	tra	ined	men
		power in relevant industries. Looking to	wards the need of	the	co	untry	y, in-
		depth knowledge for maintaining variou	s electronics audi	io-v	ideo	o sys	stems
		and home appliances is necessary for engine	neering students.	of 1		ulad	an of
		varied electronic audio-video micro	wave washer	er r aiı		nditi	oner
		consumer appliance. To develop skills t	o troubleshoot in	SV	sten	natic	wav
		knowledge so gained would also help in r	production units of	f the	ose	cons	umer
		gadgets or help the scholars to start out the	eir own enterprise	s.			
Course outcom	ne:	After the completion of the course student	s will be able to:				
		• To identify the various digital and	analog signal.				
		• Describe various safety standar	ds use in consu	ıme	r e	lectro	onics
		appliances.	arophones and an	aalze	ra		
		 Understand the principal and appli 	cation of home ar	nlia	nce	s	
		 Maintain audio systems. 	eactor of nonice up	piie	ince	5.	
		Analyse the composite video signa	l used in TV sign	al tr	ansi	miss	ion.
		Troubleshoot colour TV receivers.					
		Maintain various consumer electro	nic appliances.				
Content			No. of hours	ES (%	5E N 5)	Marl	KS
Module 1: Aud	lio Fu	undamentals and Devices	8			20	
Basic characterist	ics of	sound signal: level and loudness, pitch,	frequency respon	nse,	fid	lelity	and
linearity, Reverbe	ration	, Audio level metering, decibel level in ac	oustic measureme	ent,	Mic	cropł	none:
working principle	e, ser	nsitivity, nature of response, directional	characteristics,	Ту	pes	ca	rbon,
condenser, crysta	l, eleo	ctrets, tie- clip, wireless, Loud speaker:	working princip	le,	cha	racte	ristic
impedance,	alactr	ostatic dynamic permanent magnet etc.	woofers and	two	otor	с С	watt
recording: Optical	recor	ding stereophony and multichannel sound.	MP3 standard	twe	CICI	s, 5	ound
Module 2: Aud	lio Sy	vstems	8			20	
Audio system: Cl	$\frac{1}{D}$ $\frac{1}{D}$	var home theatre sound system surroun	d sound Digita	1 00	mac	Jac 1	alook
diagram working	princi	iple applications FM tuner concepts of dis	vital tuning. ICs u	sed	in I	FM t	uner
Public address sy	stem:	planning, speaker impedance matching,	Characteristics,	pow	er	ampl	lifier,
Specification. Trop	ublesh	nooting procedure of audio systems.				1	
Module 3: Tele	evisio	on Systems	8			20	
Monochrome TV	standa	ards, scanning process, aspect ratio, persiste	ence of vision and	flic	ker,	inte	rlace
scanning, picture	resolu	tion. Composite video signal: horizontal a	and vertical sync	deta	uils,	scar	nning
sequence. Colour	TV sta	andards, colour theory, hue, brightness, satu	ration, luminance	&c	hroi	mina	nce.
diagram of Colour	Т Т V • Т V Т	camera. Iransmission standards: PAL s	ystem, channel b	and	widi r	th. E	SIOCK
Module 4: Tele	evisio	on Receivers and Video Systems	8			20	
PAL D color TV	rocoiv	or block diagram Precision IN Line color	nicture tube Dig	ital	тV	a• 1	
LED PLASMA	HDT	V 3-D TV projection TV OI FD DTH	receiver. Concen	11.01 t re	т V сей	s I ver l	ulock
diagram. Indoor a	ind on	itdoor unit.Video interface: Composite. Co	mponent. Separat	te V	'ide	0, D	igital
Video, SDI, HDM	4I Mu	Iltimedia Interface), Digital Video Interfac	e. CD and DVD	pla	yer:	WO	rking
principles, interfac	ces.b t	roubleshooting procedure of Color TV Reco	eiver systems.	•	-		0

Module 5: Hon	ne /Office Consumer Appliances	8	20
Photocopier and I wiring and safety i controller for wash conditioner and Re camera and cam co	FAX block diagram, working. Microwave Over instructions, technical specifications. Washing Managements for the specification of the spe	en: types, single lachine: wiring dia washing machine, and technical spec- ture storage.	chip controllers, agram, electronic fuzzy logic. Air cification, Digital
Reference Bool	ks		
	 Bali S.P, "Consumer Electronics latest edition Bali R and Bali S.P., "Audio vid troubleshooting", Khanna Book P India, latest edition. Gulati R.R., "Modern Television Publication (P) Ltd. New Delhi Ye Gupta R.G., "Audio video system India 2010, , latest edition. Whitaker Jerry & Benson Blair McGraw-Hill Professional, 2010, Whitaker Jerry & Benson Blair engineering", McGraw-Hill Profest 	⁷ , Pearson Educat leo systems: princ ublishing Co. (P) practices", New A ear 2011, latest ed s", Tata McGraw , "Mastering Dig latest edition. ⁷ , "Standard hand ssional, 2010, latest	tion India,2010 , Eiple practices & Ltd., 2010Delhi, Age International ition. Hill, New Delhi, ital Television", lbook of Audio st edition.
list of Experim	ents		
	 17. Test the performance of the Speaker an 18. Measure audio intensity level with the h 19. Build and Test FM tuner. 20. Build Test 2 channel audio power ampli 21. Build Test sound mixer circuit. 22. To obtain composite video signal by measure its dimensions. 23. To visualize / compare the various patter for fault finding. 24. Operate digital TV trailer kit and observ 25. Verify the performance of LED TVs. of at least three brands. 26. Install and test DTH receiver. 27. Explore the various functions of autom various sensors used in that washing ma 28. Check the wiring of ACs and explore all 29. Test various functions of microwave over 30. Verify functions of Camcorder. 	d Microphone. elp of suitable auc fiers. using TV patter rns of colour TV e wave form. Compare perform natic washing ma chines. I the functions. en.	lio level meter. n generator and pattern generator nance parameters chine and locate

Course title:	RAI	DAR Communication	Sub code:	8L46							
	1		Structure:	L	Т	Р	С				
				3	2	0	5				
Course Objective:		This course is an introduction to radar. Its objective is to provide an understanding of the basic concepts, operation, and applications of modern radar systems. It is designed to develop the knowledge and techniques necessary to analyse the performance of radar systems so that ultimately, the student is able to specify the subsystem performance requirements in a radar system design.									
 Course Outcome: Understand the basic operation of pulse and CW radar systems. Evaluate the radar performance based on pulse width, peak power and beam width. Choose suitable tracking radar for a given problem. Select appropriate criterion for detecting a target. Understand the working of phased array radars and navigational aids 											
Content			No. of hou	rs 1	ESE M	larks ((%)				
Module 1: Radar and Radar Equation			8		20						
Introduction, Radar block diagram and operation, frequencies, applications, types of displays, derivation of radar equation, minimum detectable signal, probability of false alarm and threshold detection, radar cross-section, system losses.											
Module 2: CW Radar			8	20							
Doppler Effect, C Radar – MTI, De MTI, Pulse Dopple	CW Ra elay Li er Rad	idar, applications, FM – CW radar, al ne Canceller, Multiple Frequencies, R ar.	timeter, Multiple F ange-gated Dopple	Freque r Filte	ency Ra ers, No	adar. 1 on-coh	Pulse erent				
Module 3: Tracking Radar			8	20							
Sequential lobing, conical scanning, mono pulse, phase comparison mono pulse, tracking in range, comparison of trackers.											
Module 4: Det	ection	l	8	20							
Introduction, Mate	ched Fi	lter, Detection Criteria, Detector charac	teristics								
Module 5: Phased Arrays			8		20						
Basic concepts, fe limitations. Navig	eds, plational	hase shifters, frequency scan arrays, mu Aids: Direction Finder, VOR, ILS and I	iltiple beams, appli Loran	cation	s, adva	intages	s and				
Reference Boo	ks:										
 M.I. Skolnik, Introduction Radar Systems, Second Edition, McGraw Hill Book Co., 1981 F.E. Terman, Radio Engineering, McGraw Hill Book Co. (for Chapter 7 only), Fourth Edition 1955 Simon Kingsley & Shaun Quegan, Understanding RADAR Systems, McGraw Hill Book Co., 1993. 											

Course title:	Project-II	ject-II Sub code: 8P47								
		Structure:	L	Т	Р	C				
			1	2	12	15				
Course Object	ive: Final Year Projects represent the culm Engineering degree. Projects offer the learned throughout the program. As presentation, submission of a thesis, undertaken. The projects undertaken span a divers simulation and experimental studies. The student learning in technical, project mat	Final Year Projects represent the culmination of study towards the Bachelor of Engineering degree. Projects offer the opportunity to apply and extend material learned throughout the program. Assessment is by means of a seminar presentation, submission of a thesis, and a public demonstration of work undertaken. The projects undertaken span a diverse range of topics, including theoretical, simulation and experimental studies. The emphasis is necessarily on facilitating student learning in technical, project management and presentation spheres.								
Course outcom	 Demonstrate a sound technical know Undertake problem identification, for Design engineering solutions to approach. Conduct an engineering project. Communicate with engineers and the form. 6. Demonstrate the knowledge, skill 	 Demonstrate a sound technical knowledge of their selected project topic. Undertake problem identification, formulation and solution. Design engineering solutions to complex problems utilising a systems approach. Conduct an engineering project. Communicate with engineers and the community at large in written an oral form. 6. Demonstrate the knowledge, skills and attitudes of a professional engineer. 								
Content		No. of hours	ESE N	lark	as (%)					

Module 1: Term Work

Project Part-II, is in continuation of Project Part-I undertaken by the candidates in first term. The term work shall consist of a typed report of about 70 pages or more, on the work carried out by the batch of students in respect of the project assigned, during first term and second term. It should be in the proper format.

Module 2: Practical Examination:

It shall consist of demonstration of designed, fabricated project and oral based on it. The said examination will be conducted by a panel of two examiners; one of them will be a guide and another will be an external examiner. The external examiner will be either from the allied industry or a senior faculty member from another institute.